The following document contains information on Cypress products. The document has the series name, product name, and ordering part numbering with the prefix “MB”. However, Cypress will offer these products to new and existing customers with the series name, product name, and ordering part number with the prefix “CY”.

How to Check the Ordering Part Number

1. Go to www.cypress.com/pcn.
2. Enter the keyword (for example, ordering part number) in the **SEARCH PCNS** field and click **Apply**.
3. Click the corresponding title from the search results.
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About Cypress

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MB9A130LB Series

32-bit ARM® Cortex®-M3 FM3 Microcontroller

The MB9A130LB Series are highly integrated 32-bit microcontrollers that dedicated for embedded controllers with low-power consumption mode and competitive cost.
The MB9A130LB Series are based on the ARM® Cortex®-M3 Processor with on-chip Flash memory and SRAM, and has peripheral functions such as Motor Control Timers, ADCs and Communication Interfaces (UART, CSIO, I^2C).

The products which are described in this data sheet are placed into TYPE3 product categories in FM3 Family Peripheral Manual.

Features

32-bit ARM® Cortex®-M3 Core

- Processor version: r2p1
- Up to 20 MHz Operation Frequency
- Integrated Nested Vectored Interrupt Controller (NVIC): 1 channel NMI (non-maskable interrupt) and 32 channels' peripheral interrupts and 8 priority levels
- 24-bit System timer (Sys Tick): System timer for OS task management

On-chip Memories

[Flash memory]

- Up to 128 Kbytes
- Read cycle: 0 wait-cycle
- Security function for code protection

[SRAM]

This series contains 8 Kbyte on-chip SRAM that is connected to System bus of Cortex-M3 core.

- SRAM1: 8 Kbytes

Multi-function Serial Interface (Max 8 channels)

Operation mode is selectable from the followings for each channel.

- UART
- CSIO
- I^2C

[UART]

- Full-duplex double buffer
- Selection with or without parity supported
- Built-in dedicated baud rate generator
- External clock available as a serial clock
- Various error detection functions available (parity errors, framing errors, and overrun errors)

[CSIO]

- Full-duplex double buffer
- Built-in dedicated baud rate generator
- Overrun error detection function available

[I^2C]

Standard-mode (Max 100 kbps) / Fast-mode (Max 400 kbps) supported

A/D Converter (Max 8 channels)

[12-bit A/D Converter]

- Successive Approximation type
- Conversion time: Min. 1.0 μs
- Priority conversion available (priority at 2 levels)
- Scanning conversion mode
- Built-in FIFO for conversion data storage (for SCAN conversion: 16 steps, for Priority conversion: 4 steps)

Base Timer (Max 8 channels)

Operation mode is selectable from the followings for each channel.

- 16-bit PWM timer
- 16-bit PPG timer
- 16-/32-bit reload timer
- 16-/32-bit PWC timer

General Purpose I/O Port

This series can use its pins as general purpose I/O ports when they are not used for peripherals. Moreover, the port relocate function is built in. It can set which I/O port the peripheral function can be allocated.

- Capable of pull-up control per pin
- Capable of reading pin level directly
- Built-in the port relocate function
- Up to 52 fast general purpose I/O Ports@64 pin Package
- Some pins are 5V tolerant I/O
  See List of Pin Functions and I/O Circuit Type to confirm the corresponding pins.

Multi-function Timer

The Multi-function timer is composed of the following blocks.

- 16-bit free-run timer × 3 ch.
- Input capture × 4 ch.
- Output compare × 6 ch.
- A/D activation compare × 1 ch.
- Waveform generator × 3 ch.
- 16-bit PPG timer × 3 ch.

The following function can be used to achieve the motor control.

- PWM signal output function
- DC chopper waveform output function
- Dead time function
- Input capture function
- A/D convertor activate function
- DTIF (Motor emergency stop) interrupt function

Real-time clock (RTC)

The Real-time clock can count Year/Month/Day/Hour/Minute/Second/A day of the week from 00 to 99.

- Interrupt function with specifying date and time (Year/Month/Day/Hour/Minute) is available. This function is also available by specifying only Year, Month, Day, Hour or Minute.
- Timer interrupt function after set time or each set time.
- Capable of rewriting the time with continuing the time count.
- Leap year automatic count is available.

External Interrupt Controller Unit

- Up to 8 external interrupt input pins
- Include one non-maskable interrupt (NMI) input pin

Watchdog Timer (2 channels)

A watchdog timer can generate interrupts or a reset when a time-out value is reached.

This series consists of two different watchdogs, a Hardware watchdog and a Software watchdog.

Hardware watchdog timer is clocked by built-in Low-speed CR oscillator. Therefore, Hardware watchdog is active in any low power consumption mode except RTC and Stop and Deep Standby RTC and Deep Standby Stop modes.

Clock and Reset

[Clocks]

Five clock sources (2 external oscillators, 2 built-in CR oscillators, and Main PLL) that are dynamically selectable.

■Main Clock:	4 MHz to 20 MHz
■Sub Clock:	32.768 kHz
■Built-in High-speed CR Clock:	4 MHz
■Built-in Low-speed CR Clock:	100 kHz
■Main PLL Clock	

[Resets]

- Reset requests from INITX pin
- Power on reset
- Software reset
- Watchdog timers reset
- Low voltage detector reset
- Clock supervisor reset

Clock Super Visor (CSV)

Clocks generated by built-in CR oscillators are used to supervise abnormality of the external clocks.

- If external clock failure (clock stop) is detected, reset is asserted.
- If external frequency anomaly is detected, interrupt or reset is asserted.

Low Voltage Detector (LVD)

This Series include 2-stage monitoring of voltage on the VCC. When the voltage falls below the voltage has been set, Low Voltage Detector generates an interrupt or reset.

- LVD1: error reporting via interrupt
- LVD2: auto-reset operation

Low Power Consumption Mode

Six low power consumption modes supported.

- Sleep
- Timer
- RTC
- Stop
- Deep Standby RTC
- Deep Standby Stop

Back up register is 16 bytes.

Debug

Serial Wire JTAG Debug Port (SWJ-DP)

Power Supply

Wide range voltage: VCC = 1.8 V to 5.5 V

Contents

1. Product Lineup

Memory size

Product name		MB9AF131KB/LB	MB9AF132KB/LB
On-chip Flash		64 Kbytes	128 Kbytes
On-chip SRAM	SRAM1	8 Kbytes	8 Kbytes

Function

Product name			MB9AF131KB MB9AF132KB	MB9AF131LB MB9AF132LB
Pin count			48	64
CPU			Cortex-M3	
	Freq.		20 MHz	
Power supply voltage range			1.8 V to 5.5 V	
MF Serial Interface (UART/CSIO/I^{2}C)			4 ch. (Max) (CSIO and I^{2}C is Max 3 ch.)	8 ch. (Max)
Base Timer (PWC/ Reload timer/PWM/PPG)			8 ch. (Max)	
MF-Timer	A/D activation compare	1 ch.	1 unit (Max)	
	Input capture	4 ch.		
	Free-run timer	3 ch.		
	Output compare	6 ch.		
	Waveform generator	3 ch.		
	PPG	3 ch.		
Real-time clock			1 unit	
Watchdog timer			1 ch. (SW) + 1 ch. (HW)	
External Interrupts			6 pins (Max) + NMI × 1	8 pins (Max) + NMI × 1
general purpose I/O ports			37 pins (Max)	52 pins (Max)
12-bit A/D converter			6 ch. (1 unit)	8 ch. (1 unit)
CSV (Clock Super Visor)			Yes	
LVD (Low Voltage Detector)			2 ch.	
Built-in CR	High-speed		4 MHz	
	Low-speed		100 kHz	
Debug Function			SWJ-DP	

Note:

– *All signals of the peripheral function in each product cannot be allocated by limiting the pins of package. It is necessary to use the port relocate function of the I/O port according to your function use.*
See Electrical Characteristics (12.4) AC Characteristics (12.4.3) Built-in CR Oscillation Characteristics for accuracy of built-in CR.

2. Packages

Package \ Product name	MB9AF131KB MB9AF132KB	MB9AF131LB MB9AF132LB
LQFP: LQA048 (0.5mm pitch)	❍	-
QFN: VNA048	❍	-
LQFP: LQD064 (0.5mm pitch)	-	❍
LQFP: LQG064 (0.65mm pitch)	-	❍
QFN: VNC064	-	❍

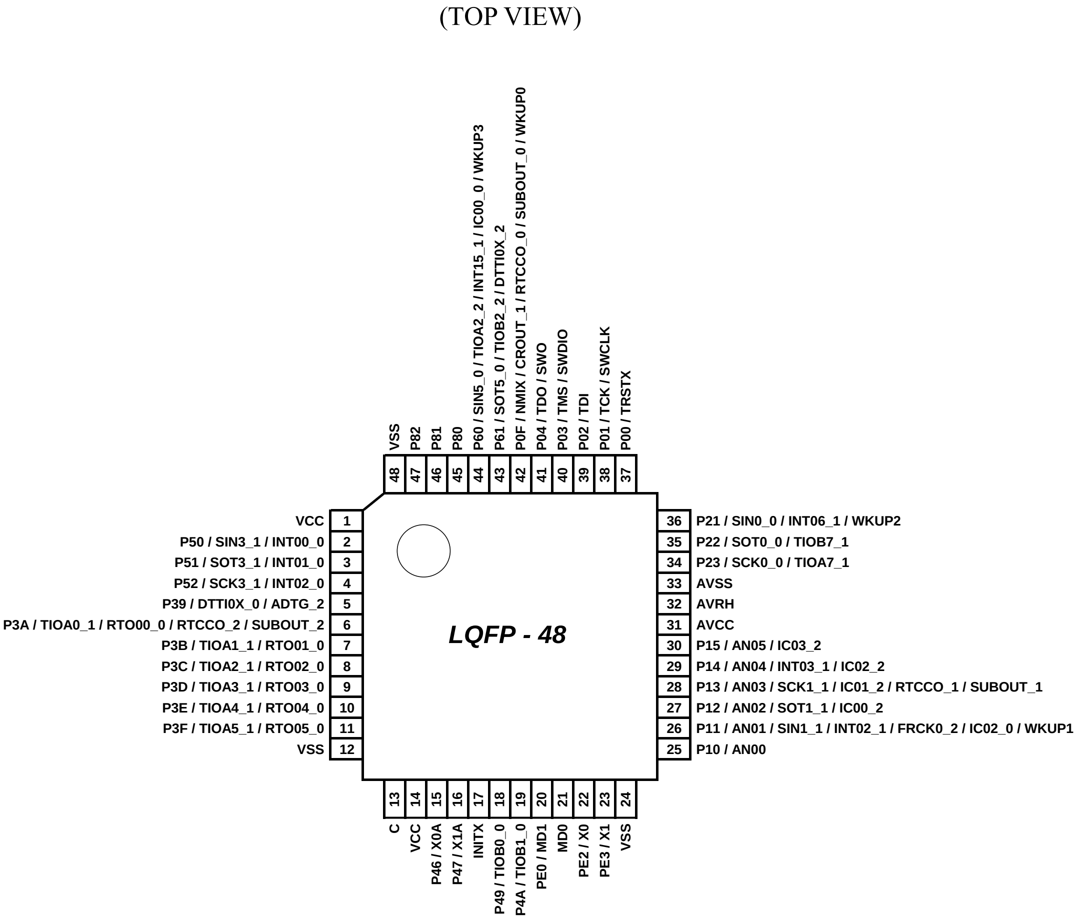
❍: Supported

Note:

– *See Package Dimensions for detailed information on each package.*

3. Pin Assignment

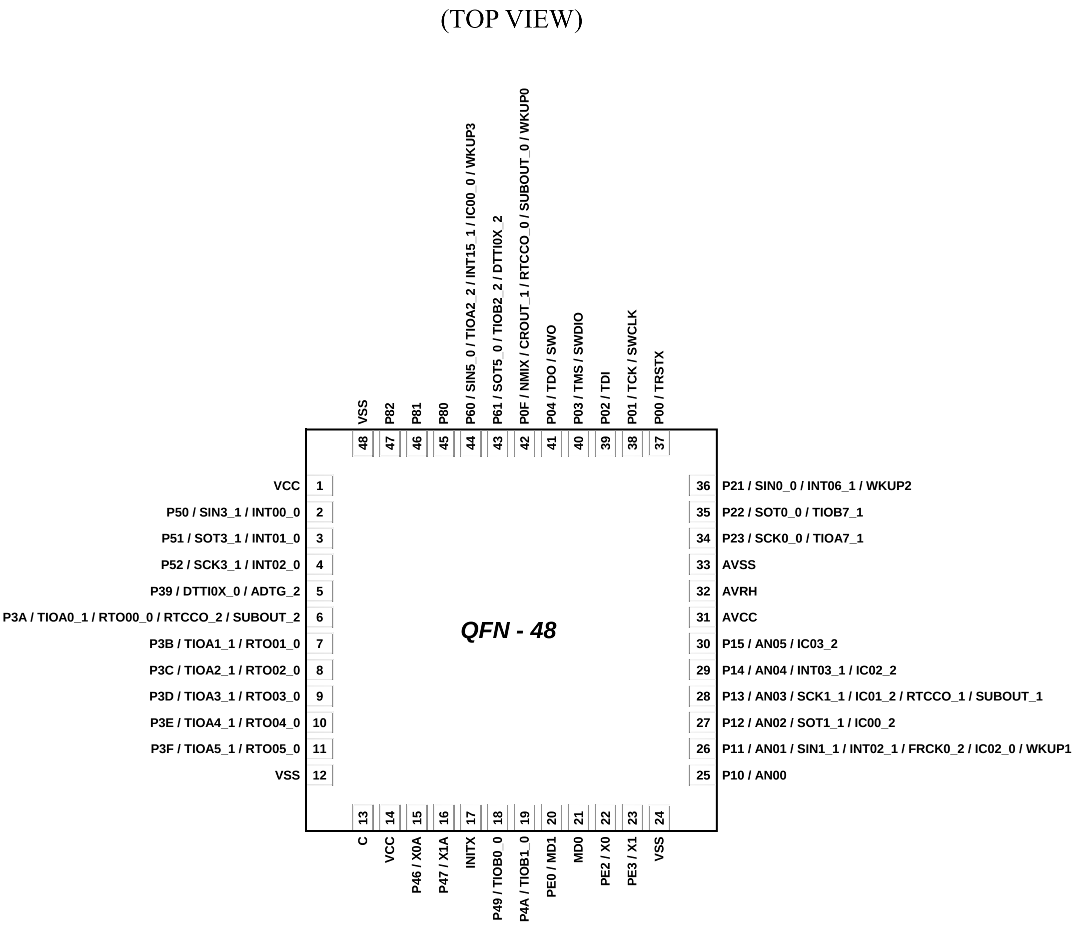
LQA048



Note:

– *The number after the underscore ("_") in pin names such as XXX_1 and XXX_2 indicates the relocated port number. For these pins, there are multiple pins that provide the same function for the same channel. Use the extended port function register (EPFR) to select the pin.*

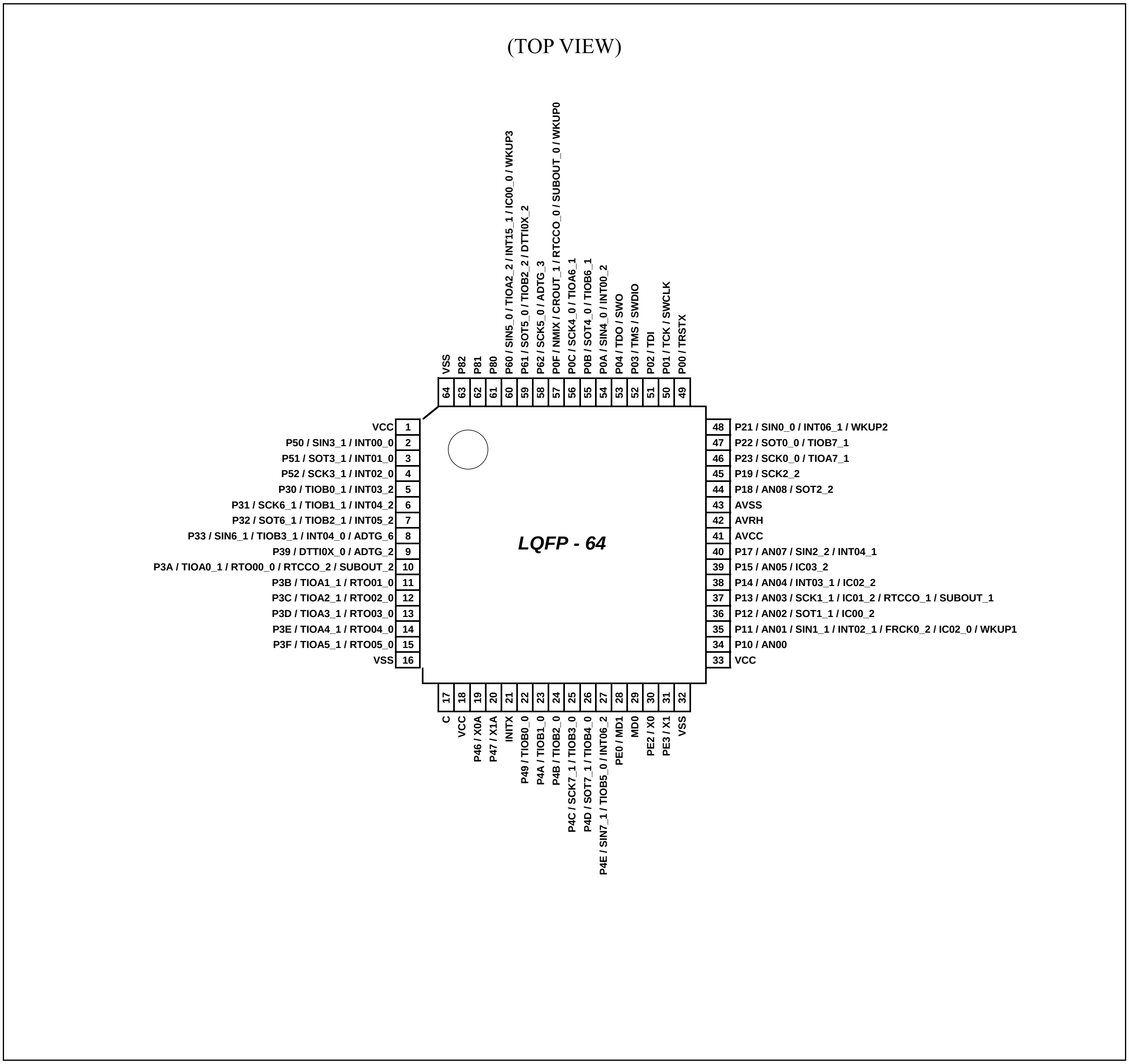
VNA048



Note:

– *The number after the underscore ("_") in pin names such as XXX_1 and XXX_2 indicates the relocated port number. For these pins, there are multiple pins that provide the same function for the same channel. Use the extended port function register (EPFR) to select the pin.*

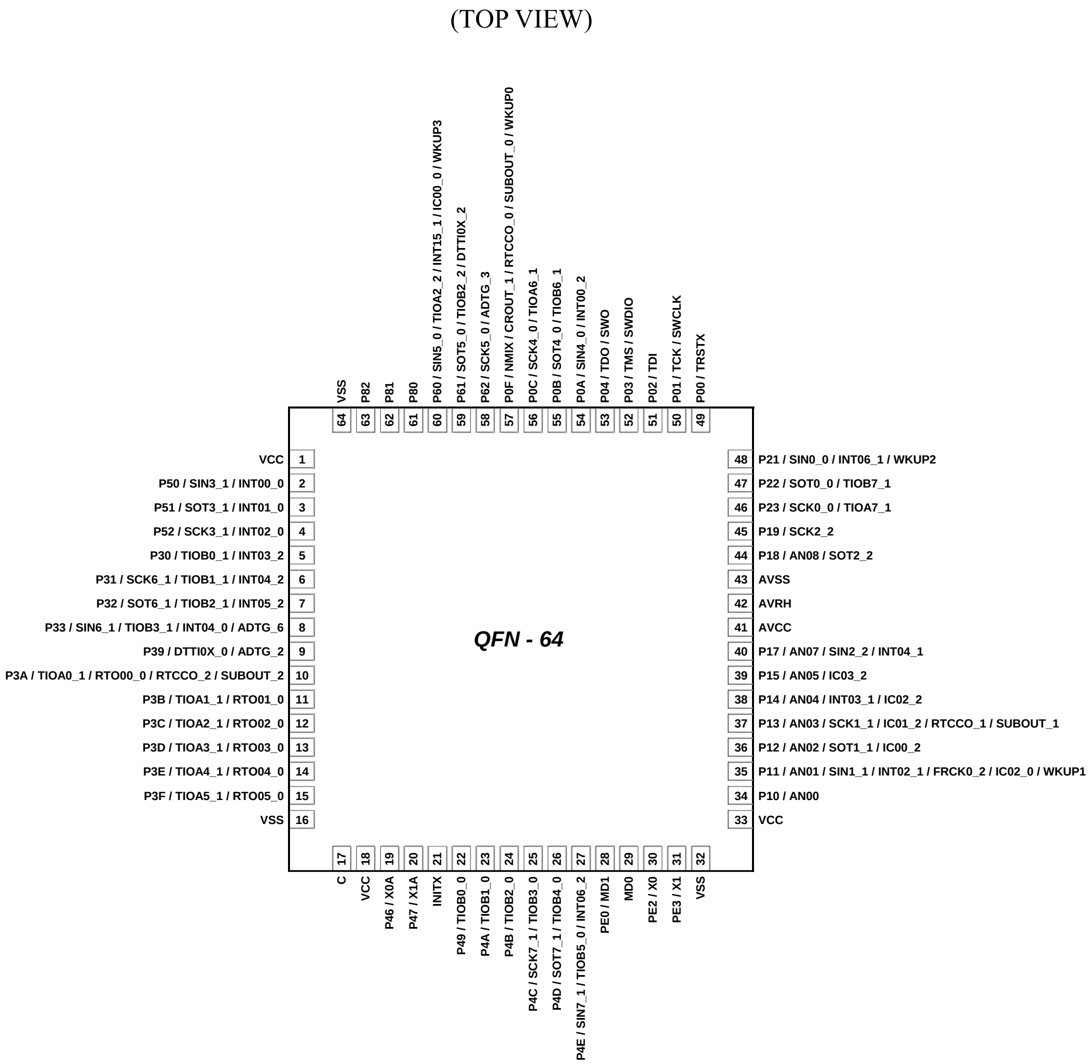
LQD064/LQG064



Note:

– *The number after the underscore ("_") in pin names such as XXX_1 and XXX_2 indicates the relocated port number. For these pins, there are multiple pins that provide the same function for the same channel. Use the extended port function register (EPFR) to select the pin.*

VNC064



Note:

– *The number after the underscore ("_") in pin names such as XXX_1 and XXX_2 indicates the relocated port number. For these pins, there are multiple pins that provide the same function for the same channel. Use the extended port function register (EPFR) to select the pin.*

4. List of Pin Functions

List of pin numbers

The number after the underscore ("_") in pin names such as XXX_1 and XXX_2 indicates the relocated port number. For these pins, there are multiple pins that provide the same function for the same channel. Use the extended port function register (EPFR) to select the pin.

Pin No		Pin name	I/O circuit type	Pin state type
LQFP-64 QFN-64	LQFP-48 QFN-48			
1	1	VCC	-	
2	2	P50 INT00_0 SIN3_1	G	F
3	3	P51 INT01_0 SOT3_1 (SDA3_1)	G	F
4	4	P52 INT02_0 SCK3_1 (SCL3_1)	G	F
5	-	P30 TIOB0_1 INT03_2	E	F
6	-	P31 TIOB1_1 SCK6_1 (SCL6_1) INT04_2	E	F
7	-	P32 TIOB2_1 SOT6_1 (SDA6_1) INT05_2	E	F
8	-	P33 INT04_0 TIOB3_1 SIN6_1 ADTG_6	E	F
9	5	P39 DTTI0X_0 ADTG_2	E	H
10	6	P3A RTO00_0 (PPG00_0) TIOA0_1 RTCCO_2 SUBOUT_2	E	H

Pin No		Pin name	I/O circuit type	Pin state type
LQFP-64 QFN-64	LQFP-48 QFN-48			
11	7	P3B RTO01_0 (PPG00_0) TIOA1_1	E	H
12	8	P3C RTO02_0 (PPG02_0) TIOA2_1	E	H
13	9	P3D RTO03_0 (PPG02_0) TIOA3_1	E	H
14	10	P3E RTO04_0 (PPG04_0) TIOA4_1	E	H
15	11	P3F RTO05_0 (PPG04_0) TIOA5_1	E	H
16	12	VSS	-	
17	13	C	-	
18	14	VCC	-	
19	15	P46 X0A	D	M
20	16	P47 X1A	D	N
21	17	INITX	B	C
22	18	P49 TIOB0_0	E	H
23	19	P4A TIOB1_0	E	H
24	-	P4B TIOB2_0	E	H

Pin No		Pin name	I/O circuit type	Pin state type
LQFP-64 QFN-64	LQFP-48 QFN-48			
25	-	P4C TIOB3_0 SCK7_1 (SCL7_1)	E	H
26	-	P4D TIOB4_0 SOT7_1 (SDA7_1)	E	H
27	-	P4E TIOB5_0 INT06_2 SIN7_1	E	F
28	20	PE0 MD1	C	P
29	21	MD0	H	D
30	22	PE2 X0	A	A
31	23	PE3 X1	A	B
32	24	VSS	-	
33	-	VCC	-	
34	25	P10 AN00	F	J
35	26	P11 AN01 SIN1_1 INT02_1 FRCK0_2 IC02_0 WKUP1	F	L
36	27	P12 AN02 SOT1_1 (SDA1_1) IC00_2	F	J
37	28	P13 AN03 SCK1_1 (SCL1_1) IC01_2 RTCCO_1 SUBOUT_1	F	J

Pin No		Pin name	I/O circuit type	Pin state type
LQFP-64 QFN-64	LQFP-48 QFN-48			
38	29	P14 AN04 INT03_1 IC02_2	F	K
39	30	P15 AN05 IC03_2	F	J
40	-	P17 AN07 SIN2_2 INT04_1	F	K
41	31	AVCC	-	
42	32	AVRH	-	
43	33	AVSS	-	
44	-	P18 AN08 SOT2_2 (SDA2_2)	F	J
45	-	P19 SCK2_2 (SCL2_2)	E	H
46	34	P23 SCK0_0 (SCL0_0) TIOA7_1	G	H
47	35	P22 SOT0_0 (SDA0_0) TIOB7_1	G	H
48	36	P21 SIN0_0 INT06_1 WKUP2	G	G
49	37	P00 TRSTX	E	E
50	38	P01 TCK SWCLK	E	E
51	39	P02 TDI	E	E

Pin No		Pin name	I/O circuit type	Pin state type
LQFP-64 QFN-64	LQFP-48 QFN-48			
52	40	P03	E	E
		TMS		
		SWDIO		
53	41	P04	E	E
		TDO		
		SWO		
54	-	P0A	E	F
		SIN4_0		
		INT00_2		
55	-	P0B	E	H
		SOT4_0 (SDA4_0)		
		TIOB6_1		
56	-	P0C	E	H
		SCK4_0 (SCL4_0)		
		TIOA6_1		
57	42	P0F	E	I
		NMIX		
		CROUT_1		
		RTCCO_0		
		SUBOUT_0		
		WKUP0		
58	-	P62	I	H
		SCK5_0 (SCL5_0)		
		ADTG_3		
59	43	P61	I	H
		SOT5_0 (SDA5_0)		
		TIOB2_2		
		DTTI0X_2		
60	44	P60	I	G
		SIN5_0		
		TIOA2_2		
		INT15_1		
		IC00_0		
		WKUP3		
61	45	P80	G	O
62	46	P81	G	O
63	47	P82	G	O
64	48	VSS	-	

List of pin functions

The number after the underscore ("_") in pin names such as XXX_1 and XXX_2 indicates the relocated port number. For these pins, there are multiple pins that provide the same function for the same channel. Use the extended port function register (EPFR) to select the pin.

Pin function	Pin name	Function description	Pin No	
			LQFP-64 QFN-64	LQFP-48 QFN-48
ADC	ADTG_2	A/D converter external trigger input pin	9	5
	ADTG_3		58	-
	ADTG_6		8	-
	AN00	A/D converter analog input pin. ANxx describes ADC ch.xx.	34	25
	AN01		35	26
	AN02		36	27
	AN03		37	28
	AN04		38	29
	AN05		39	30
	AN07		40	-
	AN08		44	-
Base Timer 0	TIOA0_1	Base timer ch.0 TIOA pin	10	6
	TIOB0_0	Base timer ch.0 TIOB pin	22	18
	TIOB0_1		5	-
Base Timer 1	TIOA1_1	Base timer ch.1 TIOA pin	11	7
	TIOB1_0	Base timer ch.1 TIOB pin	23	19
	TIOB1_1		6	-
Base Timer 2	TIOA2_1	Base timer ch.2 TIOA pin	12	8
	TIOA2_2		60	44
	TIOB2_0	Base timer ch.2 TIOB pin	24	-
	TIOB2_1		7	-
	TIOB2_2		59	43
Base Timer 3	TIOA3_1	Base timer ch.3 TIOA pin	13	9
	TIOB3_0	Base timer ch.3 TIOB pin	25	-
	TIOB3_1		8	-
Base Timer 4	TIOA4_1	Base timer ch.4 TIOA pin	14	10
	TIOB4_0	Base timer ch.4 TIOB pin	26	-
Base Timer 5	TIOA5_1	Base timer ch.5 TIOA pin	15	11
	TIOB5_0	Base timer ch.5 TIOB pin	27	-
Base Timer 6	TIOA6_1	Base timer ch.6 TIOA pin	56	-
	TIOB6_1	Base timer ch.6 TIOB pin	55	-
Base Timer 7	TIOA7_1	Base timer ch.7 TIOA pin	46	34
	TIOB7_1	Base timer ch.7 TIOB pin	47	35
Debugger	SWCLK	Serial wire debug interface clock input pin	50	38
	SWDIO	Serial wire debug interface data input / output pin	52	40
	SWO	Serial wire viewer output pin	53	41
	TRSTX	JTAG reset Input pin	49	37
	TCK	JTAG test clock input pin	50	38
	TDI	JTAG test data input pin	51	39
	TMS	JTAG test mode state input/output pin	52	40
	TDO	JTAG debug data output pin	53	41

Pin function	Pin name	Function description	Pin No	
			LQFP-64 QFN-64	LQFP-48 QFN-48
External Interrupt	INT00_0	External interrupt request 00 input pin	2	2
	INT00_2		54	-
	INT01_0	External interrupt request 01 input pin	3	3
	INT02_0	External interrupt request 02 input pin	4	4
	INT02_1		35	26
	INT03_1	External interrupt request 03 input pin	38	29
	INT03_2		5	-
	INT04_0	External interrupt request 04 input pin	8	-
	INT04_1		40	-
	INT04_2		6	-
	INT05_2	External interrupt request 05 input pin	7	-
	INT06_1	External interrupt request 06 input pin	48	36
	INT06_2		27	-
	INIT15_1	External interrupt request 15 input pin	60	44
	NMIX	Non-Maskable Interrupt input pin	57	42
GPIO	P00	General-purpose I/O port 0	49	37
	P01		50	38
	P02		51	39
	P03		52	40
	P04		53	41
	P0A		54	-
	P0B		55	-
	P0C		56	-
	P0F		57	42
	P10	General-purpose I/O port 1	34	25
	P11		35	26
	P12		36	27
	P13		37	28
	P14		38	29
	P15		39	30
	P17		40	-
	P18		44	-
	P19		45	-
	P21	General-purpose I/O port 2	48	36
	P22		47	35
	P23		46	34

Pin function	Pin name	Function description	Pin No	
			LQFP-64 QFN-64	LQFP-48 QFN-48
GPIO	P30	General-purpose I/O port 3	5	-
	P31		6	-
	P32		7	-
	P33		8	-
	P39		9	5
	P3A		10	6
	P3B		11	7
	P3C		12	8
	P3D		13	9
	P3E		14	10
	P3F		15	11
	P46	General-purpose I/O port 4	19	15
	P47		20	16
	P49		22	18
	P4A		23	19
	P4B		24	-
	P4C		25	-
	P4D		26	-
	P4E		27	-
	P50	General-purpose I/O port 5	2	2
	P51		3	3
	P52		4	4
	P60	General-purpose I/O port 6	60	44
	P61		59	43
	P62		58	-
	P80	General-purpose I/O port 8	61	45
	P81		62	46
	P82		63	47
	PE0	General-purpose I/O port E	28	20
	PE2		30	22
	PE3		31	23

Pin function	Pin name	Function description	Pin No	
			LQFP-64 QFN-64	LQFP-48 QFN-48
Multi-function Serial 0	SIN0_0	Multi-function serial interface ch.0 input pin	48	36
	SOT0_0 (SDA0_0)	Multi-function serial interface ch.0 output pin. This pin operates as SOT0 when it is used in a UART/CSIO (operation modes 0 to 2) and as SDA0 when it is used in an I^{2}C (operation mode 4).	47	35
	SCK0_0 (SCL0_0)	Multi-function serial interface ch.0 clock I/O pin. This pin operates as SCK0 when it is used in a UART/CSIO (operation modes 0 to 2) and as SCL0 when it is used in an I^{2}C (operation mode 4).	46	34
Multi-function Serial 1	SIN1_1	Multi-function serial interface ch.1 input pin	35	26
	SOT1_1 (SDA1_1)	Multi-function serial interface ch.1 output pin. This pin operates as SOT1 when it is used in a UART/CSIO (operation modes 0 to 2) and as SDA1 when it is used in an I^{2}C (operation mode 4).	36	27
	SCK1_1 (SCL1_1)	Multi-function serial interface ch.1 clock I/O pin. This pin operates as SCK1 when it is used in a UART/CSIO (operation modes 0 to 2) and as SCL1 when it is used in an I^{2}C (operation mode 4).	37	28
Multi-function Serial 2	SIN2_2	Multi-function serial interface ch.2 input pin	40	-
	SOT2_2 (SDA2_2)	Multi-function serial interface ch.2 output pin. This pin operates as SOT2 when it is used in a UART/CSIO (operation modes 0 to 2) and as SDA2 when it is used in an I^{2}C (operation mode 4).	44	-
	SCK2_2 (SCL2_2)	Multi-function serial interface ch.2 clock I/O pin. This pin operates as SCK2 when it is used in a UART/CSIO (operation modes 0 to 2) and as SCL2 when it is used in an I^{2}C (operation mode 4).	45	-

Pin function	Pin name	Function description	Pin No	
			LQFP-64 QFN-64	LQFP-48 QFN-48
Multi-function Serial 3	SIN3_1	Multi-function serial interface ch.3 input pin	2	2
	SOT3_1 (SDA3_1)	Multi-function serial interface ch.3 output pin. This pin operates as SOT3 when it is used in a UART/CSIO (operation modes 0 to 2) and as SDA3 when it is used in an I^{2}C (operation mode 4).	3	3
	SCK3_1 (SCL3_1)	Multi-function serial interface ch.3 clock I/O pin. This pin operates as SCK3 when it is used in a UART/CSIO (operation modes 0 to 2) and as SCL3 when it is used in an I^{2}C (operation mode 4).	4	4
Multi-function Serial 4	SIN4_0	Multi-function serial interface ch.4 input pin	54	-
	SOT4_0 (SDA4_0)	Multi-function serial interface ch.4 output pin. This pin operates as SOT4 when it is used in a UART/CSIO (operation modes 0 to 2) and as SDA4 when it is used in an I^{2}C (operation mode 4).	55	-
	SCK4_0 (SCL4_0)	Multi-function serial interface ch.4 clock I/O pin. This pin operates as SCK4 when it is used in a UART/CSIO (operation modes 0 to 2) and as SCL4 when it is used in an I^{2}C (operation mode 4).	56	-
Multi-function Serial 5	SIN5_0	Multi-function serial interface ch.5 input pin	60	44
	SOT5_0 (SDA5_0)	Multi-function serial interface ch.5 output pin. This pin operates as SOT5 when it is used in a UART/CSIO (operation modes 0 to 2) and as SDA5 when it is used in an I^{2}C (operation mode 4).	59	43
	SCK5_0 (SCL5_0)	Multi-function serial interface ch.5 clock I/O pin. This pin operates as SCK5 when it is used in a UART/CSIO (operation modes 0 to 2) and as SCL5 when it is used in an I^{2}C (operation mode 4).	58	-

Pin function	Pin name	Function description	Pin No	
			LQFP-64 QFN-64	LQFP-48 QFN-48
Multi-function Serial 6	SIN6_1	Multi-function serial interface ch.6 input pin	8	-
	SOT6_1 (SDA6_1)	Multi-function serial interface ch.6 output pin. This pin operates as SOT6 when it is used in a UART/CSIO (operation modes 0 to 2) and as SDA6 when it is used in an I^2C (operation mode 4).	7	-
	SCK6_1 (SCL6_1)	Multi-function serial interface ch.6 clock I/O pin. This pin operates as SCK6 when it is used in a UART/CSIO (operation modes 0 to 2) and as SCL6 when it is used in an I^2C (operation mode 4).	6	-
Multi-function Serial 7	SIN7_1	Multi-function serial interface ch.7 input pin	27	-
	SOT7_1 (SDA7_1)	Multi-function serial interface ch.7 output pin. This pin operates as SOT7 when it is used in a UART/CSIO (operation modes 0 to 2) and as SDA7 when it is used in an I^2C (operation mode 4).	26	-
	SCK7_1 (SCL7_1)	Multi-function serial interface ch.7 clock I/O pin. This pin operates as SCK7 when it is used in a UART/CSIO (operation modes 0 to 2) and as SCL7 when it is used in an I^2C (operation mode 4).	25	-

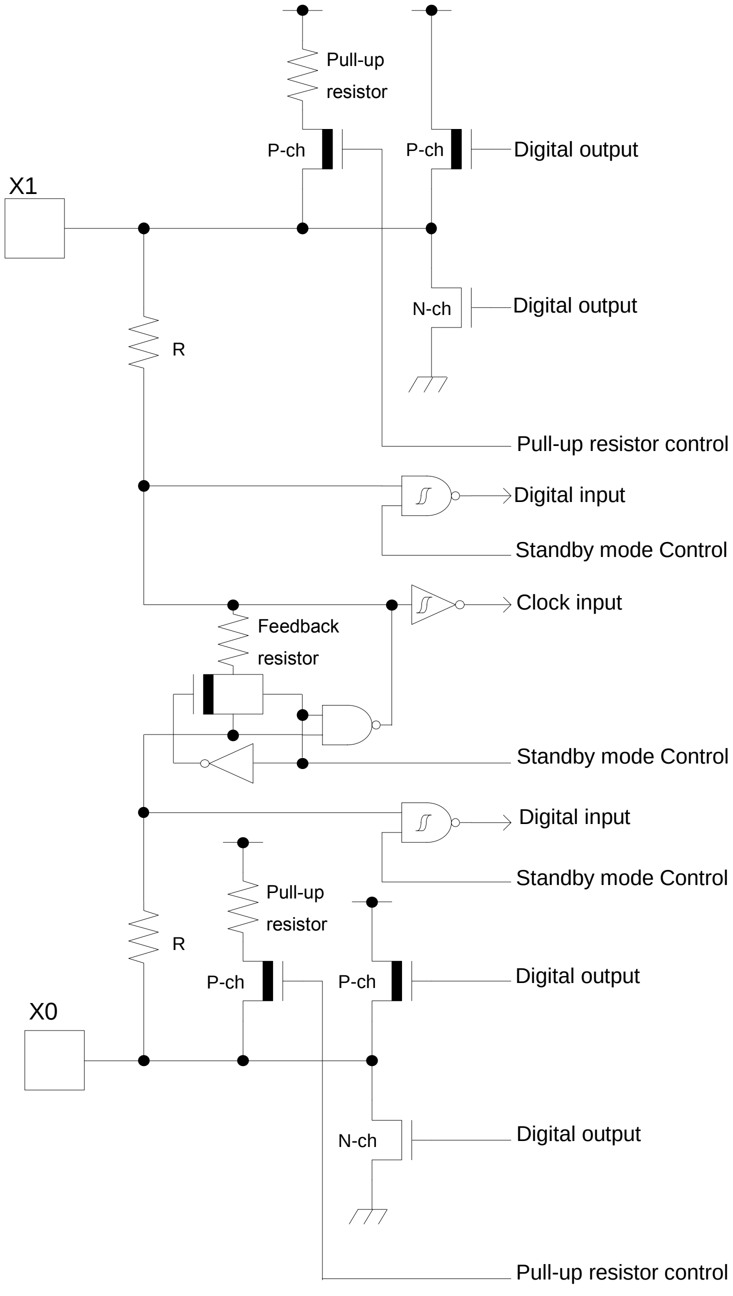
Pin function	Pin name	Function description	Pin No	
			LQFP-64 QFN-64	LQFP-48 QFN-48
Multi-function Timer 0	DTTI0X_0	Input signal of waveform generator to control outputs RTO00 to RTO05 of Multi-function timer 0	9	5
	DTTI0X_2		59	43
	FRCK0_2	16-bit free-run timer ch.0 external clock input pin	35	26
	IC00_0	16-bit input capture input pin of Multi-function timer 0. ICxx describes a channel number.	60	44
	IC00_2		36	27
	IC01_2		37	28
	IC02_0		35	26
	IC02_2		38	29
	IC03_2		39	30
	RTO00_0 (PPG00_0)	Waveform generator output pin of Multi-function timer 0. This pin operates as PPG00 when it is used in PPG0 output modes.	10	6
	RTO01_0 (PPG00_0)	Waveform generator output pin of Multi-function timer 0. This pin operates as PPG00 when it is used in PPG0 output modes.	11	7
	RTO02_0 (PPG02_0)	Waveform generator output pin of Multi-function timer 0. This pin operates as PPG02 when it is used in PPG0 output modes.	12	8
	RTO03_0 (PPG02_0)	Waveform generator output pin of Multi-function timer 0. This pin operates as PPG02 when it is used in PPG0 output modes.	13	9
	RTO04_0 (PPG04_0)	Waveform generator output pin of Multi-function timer 0. This pin operates as PPG04 when it is used in PPG0 output modes.	14	10
	RTO05_0 (PPG04_0)	Waveform generator output pin of Multi-function timer 0. This pin operates as PPG04 when it is used in PPG0 output modes.	15	11
Real-time clock	RTCCO_0	0.5 seconds pulse output pin of Real-time clock	57	42
	RTCCO_1		37	28
	RTCCO_2		10	6
	SUBOUT_0	Sub clock output pin	57	42
	SUBOUT_1		37	28
	SUBOUT_2		10	6
Low Power Consumption Mode	WKUP0	Deep stand-by mode return signal input pin 0	57	42
	WKUP1	Deep stand-by mode return signal input pin 1	35	26
	WKUP2	Deep stand-by mode return signal input pin 2	48	36
	WKUP3	Deep stand-by mode return signal input pin 3	60	44

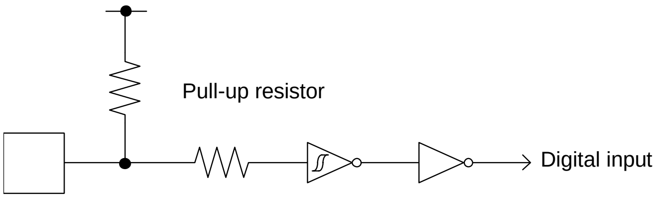
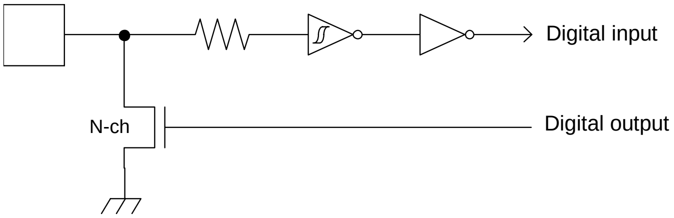
Pin function	Pin name	Function description	Pin No	
			LQFP-64 QFN-64	LQFP-48 QFN-48
Reset	INITX	External Reset Input pin. A reset is valid when INITX = L.	21	17
Mode	MD0	Mode 0 pin. During normal operation, MD0 = L must be input During serial programming to flash memory, MD0 = H must be input.	29	21
	MD1	Mode 1 pin. During normal operation, input is not needed During serial programming to flash memory, MD1 = L must be input.	28	20
Power	VCC	Power supply pin	1	1
			18	14
			33	-
GND	VSS	GND pin	16	12
			32	24
			64	48
Clock	X0	Main clock (oscillation) input pin	30	22
	X0A	Sub clock (oscillation) input pin	19	15
	X1	Main clock (oscillation) I/O pin	31	23
	X1A	Sub clock (oscillation) I/O pin	20	16
	CROUT_1	Built-in High-speed CR-osc clock output port	57	42
ADC Power	AVCC	A/D converter analog power pin	41	31
	AVRH	A/D converter analog reference voltage input pin	42	32
ADC GND	AVSS	A/D converter GND pin	43	33
C pin	C	Power stabilization capacity pin	17	13

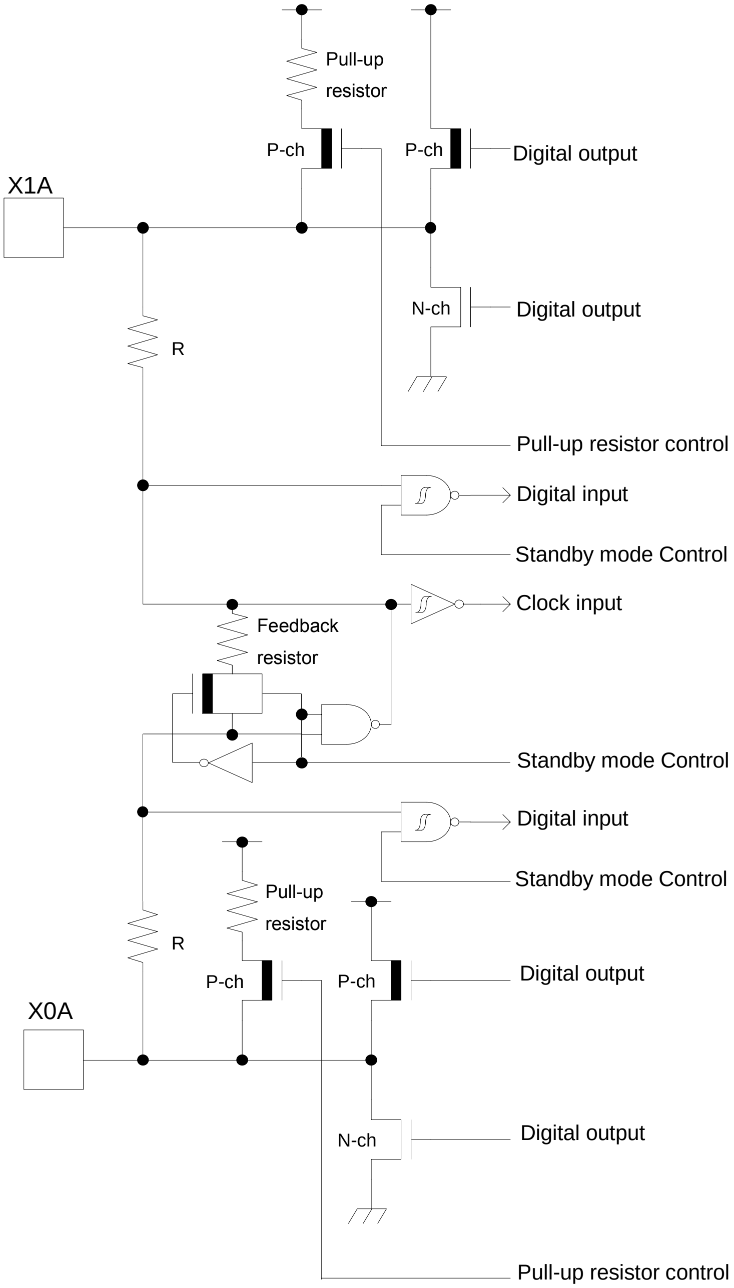
Note:

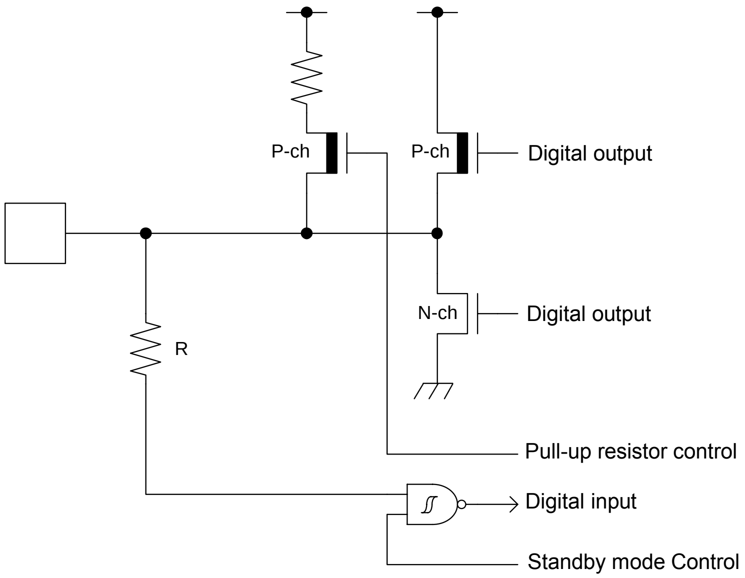
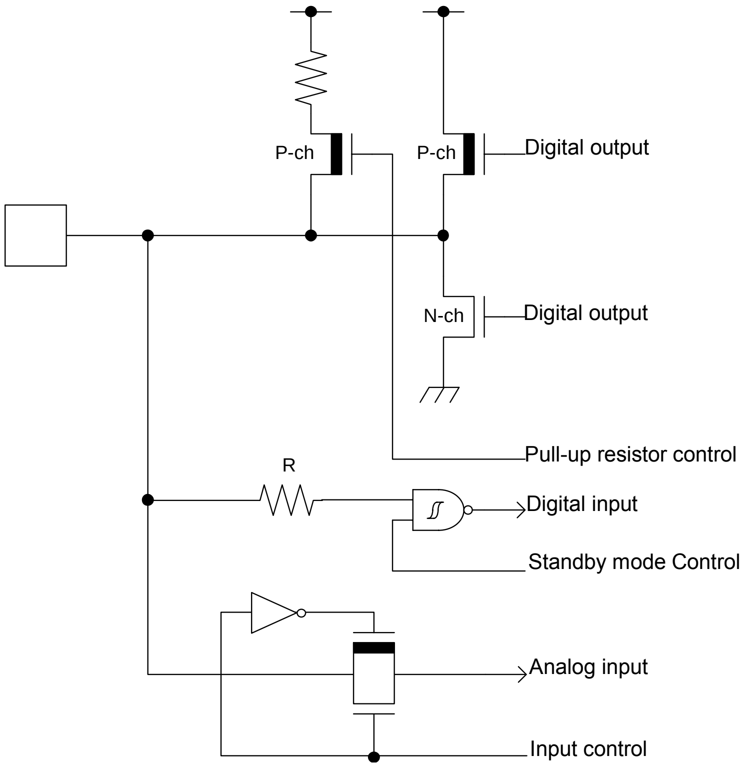
– *While this device contains a Test Access Port (TAP) based on the IEEE 1149.1-2001 JTAG standard, it is not fully compliant to all requirements of that standard. This device may contain a 32-bit device ID that is the same as the 32-bit device ID in other devices with different functionality. The TAP pins may also be configurable for purposes other than access to the TAP controller.*

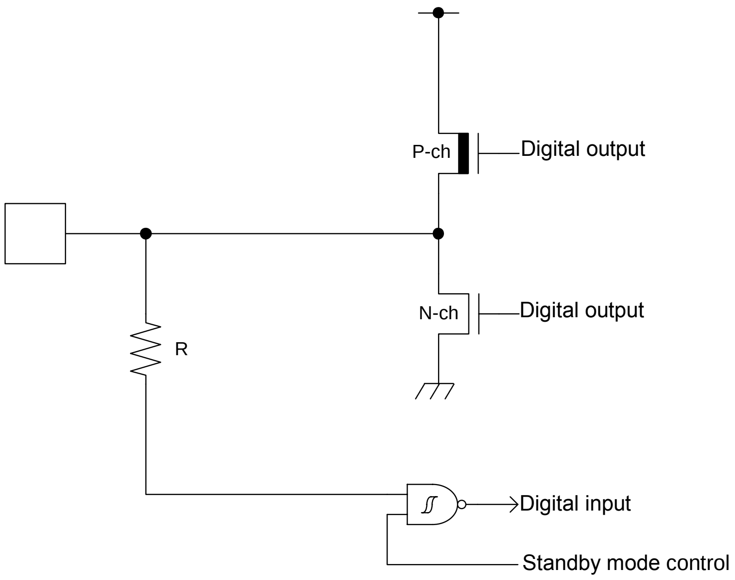
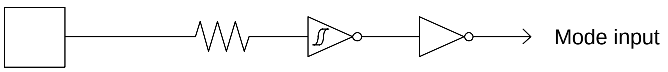
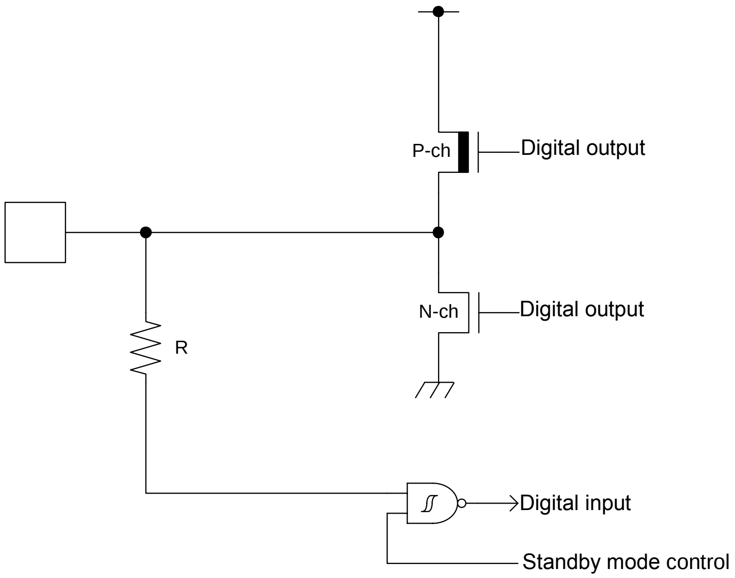
5. I/O Circuit Type

Type	Circuit	Remarks
A		It is possible to select the main oscillation / GPIO function. When the main oscillation is selected. • Oscillation feedback resistor : Approximately 1 MΩ • With Standby control When the GPIO is selected. • CMOS level output. • CMOS level hysteresis input • With pull-up resistor control • With standby control • Pull-up resistor : Approximately 50 kΩ • I_{OH} = -4 mA, I_{OL} = 4 mA

Type	Circuit	Remarks
B		• CMOS level hysteresis input • Pull-up resistor : Approximately 50 kΩ
C		• Open drain output • CMOS level hysteresis input

Type	Circuit	Remarks
D		It is possible to select the sub oscillation / GPIO function When the sub oscillation is selected. • Oscillation feedback resistor : Approximately 5 MΩ • With Standby control When the GPIO is selected. • CMOS level output. • CMOS level hysteresis input • With pull-up resistor control • With standby control • Pull-up resistor : Approximately 50 kΩ • I_{OH} = -4 mA, I_{OL} = 4 mA

Type	Circuit	Remarks
E		• CMOS level output • CMOS level hysteresis input • With pull-up resistor control • With standby control • Pull-up resistor : Approximately 50 kΩ • I_{OH} = -4 mA, I_{OL} = 4 mA • When this pin is used as an I^{2}C pin, the digital output P-ch transistor is always off
F		• CMOS level output • CMOS level hysteresis input • With input control • Analog input • With pull-up resistor control • With standby control • Pull-up resistor : Approximately 50 kΩ • I_{OH} = -4 mA, I_{OL} = 4 mA • When this pin is used as an I^{2}C pin, the digital output P-ch transistor is always off

Type	Circuit	Remarks
G		- CMOS level output - CMOS level hysteresis input - With standby control - 5 V tolerant input - I_{OH} = -4 mA, I_{OL} = 4 mA - Available to control of PZR registers. Only P22, P23, P51, P52 - When this pin is used as an I^2C pin, the digital output P-ch transistor is always off
H		CMOS level hysteresis input
I		- CMOS level output - CMOS level hysteresis input - With standby control - I_{OH} = -4 mA, I_{OL} = 4 mA - When this pin is used as an I^2C pin, the digital output P-ch transistor is always off

6. Handling Precautions

Any semiconductor devices have inherently a certain rate of failure. The possibility of failure is greatly affected by the conditions in which they are used (circuit conditions, environmental conditions, etc.). This page describes precautions that must be observed to minimize the chance of failure and to obtain higher reliability from your Cypress semiconductor devices.

6.1 Precautions for Product Design

This section describes precautions when designing electronic equipment using semiconductor devices.

Absolute Maximum Ratings

Semiconductor devices can be permanently damaged by application of stress (voltage, current, temperature, etc.) in excess of certain established limits, called absolute maximum ratings. Do not exceed these ratings.

Recommended Operating Conditions

Recommended operating conditions are normal operating ranges for the semiconductor device. All the device's electrical characteristics are warranted when operated within these ranges.

Always use semiconductor devices within the recommended operating conditions. Operation outside these ranges may adversely affect reliability and could result in device failure.

No warranty is made with respect to uses, operating conditions, or combinations not represented on the data sheet. Users considering application outside the listed conditions are advised to contact their sales representative beforehand.

Processing and Protection of Pins

These precautions must be followed when handling the pins which connect semiconductor devices to power supply and input/output functions.

1. Preventing Over-Voltage and Over-Current Conditions

   Exposure to voltage or current levels in excess of maximum ratings at any pin is likely to cause deterioration within the device, and in extreme cases leads to permanent damage of the device. Try to prevent such overvoltage or over-current conditions at the design stage.

2. Protection of Output Pins

   Shorting of output pins to supply pins or other output pins, or connection to large capacitance can cause large current flows. Such conditions if present for extended periods of time can damage the device.
   Therefore, avoid this type of connection.

3. Handling of Unused Input Pins

   Unconnected input pins with very high impedance levels can adversely affect stability of operation. Such pins should be connected through an appropriate resistance to a power supply pin or ground pin.

Latch-up

Semiconductor devices are constructed by the formation of P-type and N-type areas on a substrate. When subjected to abnormally high voltages, internal parasitic PNPN junctions (called thyristor structures) may be formed, causing large current levels in excess of several hundred mA to flow continuously at the power supply pin. This condition is called latch-up.

CAUTION: The occurrence of latch-up not only causes loss of reliability in the semiconductor device, but can cause injury or damage from high heat, smoke or flame. To prevent this from happening, do the following:

1. Be sure that voltages applied to pins do not exceed the absolute maximum ratings. This should include attention to abnormal noise, surge levels, etc.
2. Be sure that abnormal current flows do not occur during the power-on sequence.

Observance of Safety Regulations and Standards

Most countries in the world have established standards and regulations regarding safety, protection from electromagnetic interference, etc. Customers are requested to observe applicable regulations and standards in the design of products.

Fail-Safe Design

Any semiconductor devices have inherently a certain rate of failure. You must protect against injury, damage or loss from such failures by incorporating safety design measures into your facility and equipment such as redundancy, fire protection, and prevention of over-current levels and other abnormal operating conditions.

Precautions Related to Usage of Devices

Cypress semiconductor devices are intended for use in standard applications (computers, office automation and other office equipment, industrial, communications, and measurement equipment, personal or household devices, etc.).

CAUTION: Customers considering the use of our products in special applications where failure or abnormal operation may directly affect human lives or cause physical injury or property damage, or where extremely high levels of reliability are demanded (such as aerospace systems, atomic energy controls, sea floor repeaters, vehicle operating controls, medical devices for life support, etc.) are requested to consult with sales representatives before such use. The company will not be responsible for damages arising from such use without prior approval.

6.2 Precautions for Package Mounting

Package mounting may be either lead insertion type or surface mount type. In either case, for heat resistance during soldering, you should only mount under Cypress' recommended conditions. For detailed information about mount conditions, contact your sales representative.

Lead Insertion Type

Mounting of lead insertion type packages onto printed circuit boards may be done by two methods: direct soldering on the board, or mounting by using a socket.

Direct mounting onto boards normally involves processes for inserting leads into through-holes on the board and using the flow soldering (wave soldering) method of applying liquid solder. In this case, the soldering process usually causes leads to be subjected to thermal stress in excess of the absolute ratings for storage temperature. Mounting processes should conform to Cypress recommended mounting conditions.

If socket mounting is used, differences in surface treatment of the socket contacts and IC lead surfaces can lead to contact deterioration after long periods. For this reason it is recommended that the surface treatment of socket contacts and IC leads be verified before mounting.

Surface Mount Type

Surface mount packaging has longer and thinner leads than lead-insertion packaging, and therefore leads are more easily deformed or bent. The use of packages with higher pin counts and narrower pin pitch results in increased susceptibility to open connections caused by deformed pins, or shorting due to solder bridges.

You must use appropriate mounting techniques. Cypress recommends the solder reflow method, and has established a ranking of mounting conditions for each product. Users are advised to mount packages in accordance with Cypress ranking of recommended conditions.

Lead-Free Packaging

CAUTION: When ball grid array (BGA) packages with Sn-Ag-Cu balls are mounted using Sn-Pb eutectic soldering, junction strength may be reduced under some conditions of use.

Storage of Semiconductor Devices

Because plastic chip packages are formed from plastic resins, exposure to natural environmental conditions will cause absorption of moisture. During mounting, the application of heat to a package that has absorbed moisture can cause surfaces to peel, reducing moisture resistance and causing packages to crack. To prevent, do the following:

3. Avoid exposure to rapid temperature changes, which cause moisture to condense inside the product. Store products in locations where temperature changes are slight.
4. Use dry boxes for product storage. Products should be stored below 70% relative humidity, and at temperatures between 5°C and 30°C.
   When you open Dry Package that recommends humidity 40% to 70% relative humidity.
5. When necessary, Cypress packages semiconductor devices in highly moisture-resistant aluminum laminate bags, with a silica gel desiccant. Devices should be sealed in their aluminum laminate bags for storage.
6. Avoid storing packages where they are exposed to corrosive gases or high levels of dust.

Baking

Packages that have absorbed moisture may be de-moisturized by baking (heat drying). Follow the Cypress recommended conditions for baking.

Condition: 125°C/24 h

Static Electricity

Because semiconductor devices are particularly susceptible to damage by static electricity, you must take the following precautions:

1. Maintain relative humidity in the working environment between 40% and 70%. Use of an apparatus for ion generation may be needed to remove electricity.
2. Electrically ground all conveyors, solder vessels, soldering irons and peripheral equipment.
3. Eliminate static body electricity by the use of rings or bracelets connected to ground through high resistance (on the level of 1 MΩ).
   Wearing of conductive clothing and shoes, use of conductive floor mats and other measures to minimize shock loads is recommended.
4. Ground all fixtures and instruments, or protect with anti-static measures.
5. Avoid the use of styrofoam or other highly static-prone materials for storage of completed board assemblies.

6.3 Precautions for Use Environment

Reliability of semiconductor devices depends on ambient temperature and other conditions as described above.

For reliable performance, do the following:

1. Humidity

   Prolonged use in high humidity can lead to leakage in devices as well as printed circuit boards. If high humidity levels are anticipated, consider anti-humidity processing.
2. Discharge of Static Electricity

   When high-voltage charges exist close to semiconductor devices, discharges can cause abnormal operation. In such cases, use anti-static measures or processing to prevent discharges.
3. Corrosive Gases, Dust, or Oil

   Exposure to corrosive gases or contact with dust or oil may lead to chemical reactions that will adversely affect the device. If you use devices in such conditions, consider ways to prevent such exposure or to protect the devices.
4. Radiation, Including Cosmic Radiation

   Most devices are not designed for environments involving exposure to radiation or cosmic radiation. Users should provide shielding as appropriate.
5. Smoke, Flame

   CAUTION: Plastic molded devices are flammable, and therefore should not be used near combustible substances. If devices begin to smoke or burn, there is danger of the release of toxic gases.

Customers considering the use of Cypress products in other special environmental conditions should consult with sales representatives.

7. Handling Devices

Power supply pins

In products with multiple VCC and VSS pins, respective pins at the same potential are interconnected within the device in order to prevent malfunctions such as latch-up. However, all of these pins should be connected externally to the power supply or ground lines in order to reduce electromagnetic emission levels, to prevent abnormal operation of strobe signals caused by the rise in the ground level, and to conform to the total output current rating.

Moreover, connect the current supply source with each Power supply pins and GND pins of this device at low impedance. It is also advisable that a ceramic capacitor of approximately 0.1 µF be connected as a bypass capacitor between each Power supply pins and GND pins, between AVCC pin and AVSS pin near this device.

Stabilizing power supply voltage

A malfunction may occur when the power supply voltage fluctuates rapidly even though the fluctuation is within the recommended operating conditions of the VCC power supply voltage. As a rule, with voltage stabilization, suppress the voltage fluctuation so that the fluctuation in VCC ripple (peak-to-peak value) at the commercial frequency (50 Hz/60 Hz) does not exceed 10% of the VCC value in the recommended operating conditions, and the transient fluctuation rate does not exceed 0.1 V/µs when there is a momentary fluctuation on switching the power supply.

Crystal oscillator circuit

Noise near the X0/X1 and X0A/X1A pins may cause the device to malfunction. Design the printed circuit board so that X0/X1, X0A/X1A pins, the crystal oscillator, and the bypass capacitor to ground are located as close to the device as possible.

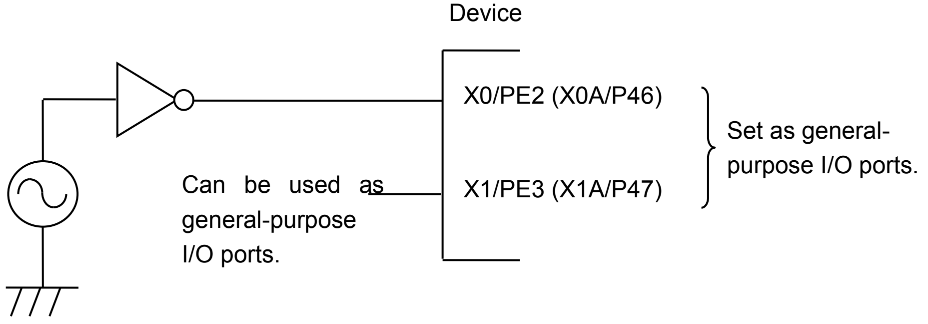
It is strongly recommended that the PC board artwork be designed such that the X0/X1 and X0A/X1A pins are surrounded by ground plane as this is expected to produce stable operation.

Evaluate oscillation of your using crystal oscillator by your mount board.

Using an external clock

To use the external clock, set general-purpose I/O ports to input the clock to X0/PE2 and X0A/P46 pins.

- Example of Using an External Clock

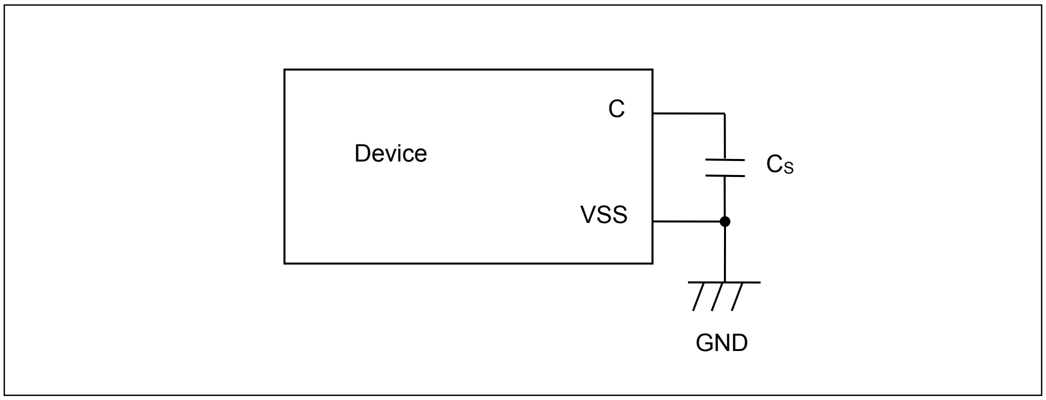


Handling when using Multi-function serial pin as I²C pin

If it is using the Multi-function serial pin as I²C pins, P-ch transistor of digital output is always disable. However, I²C pins need to keep the electrical characteristic like other pins and not to connect to external I²C bus system with power OFF.

C Pin

This series contains the regulator. Be sure to connect a smoothing capacitor (CS) for the regulator between the C pin and the GND pin. Please use a ceramic capacitor or a capacitor of equivalent frequency characteristics as a smoothing capacitor.
However, some laminated ceramic capacitors have the characteristics of capacitance variation due to thermal fluctuation (F characteristics and Y5V characteristics). Please select the capacitor that meets the specifications in the operating conditions to use by evaluating the temperature characteristics of a capacitor.
A smoothing capacitor of about 4.7uF would be recommended for this series.



Mode pins (MD0, MD1)

Connect the MD pin (MD0, MD1) directly to VCC or VSS pins. Design the printed circuit board such that the pull-up/down resistance stays low, as well as the distance between the mode pins and VCC pins or VSS pins is as short as possible and the connection impedance is low, when the pins are pulled-up/down such as for switching the pin level and rewriting the Flash memory data. It is because of preventing the device erroneously switching to test mode due to noise.

Notes on power-on

Turn power on/off in the following order or at the same time.
If not using the A/D converter, connect AVCC = VCC and AVSS = VSS.

Turning on: VCC → AVCC → AVRH

Turning off: AVRH → AVCC → VCC

Serial Communication

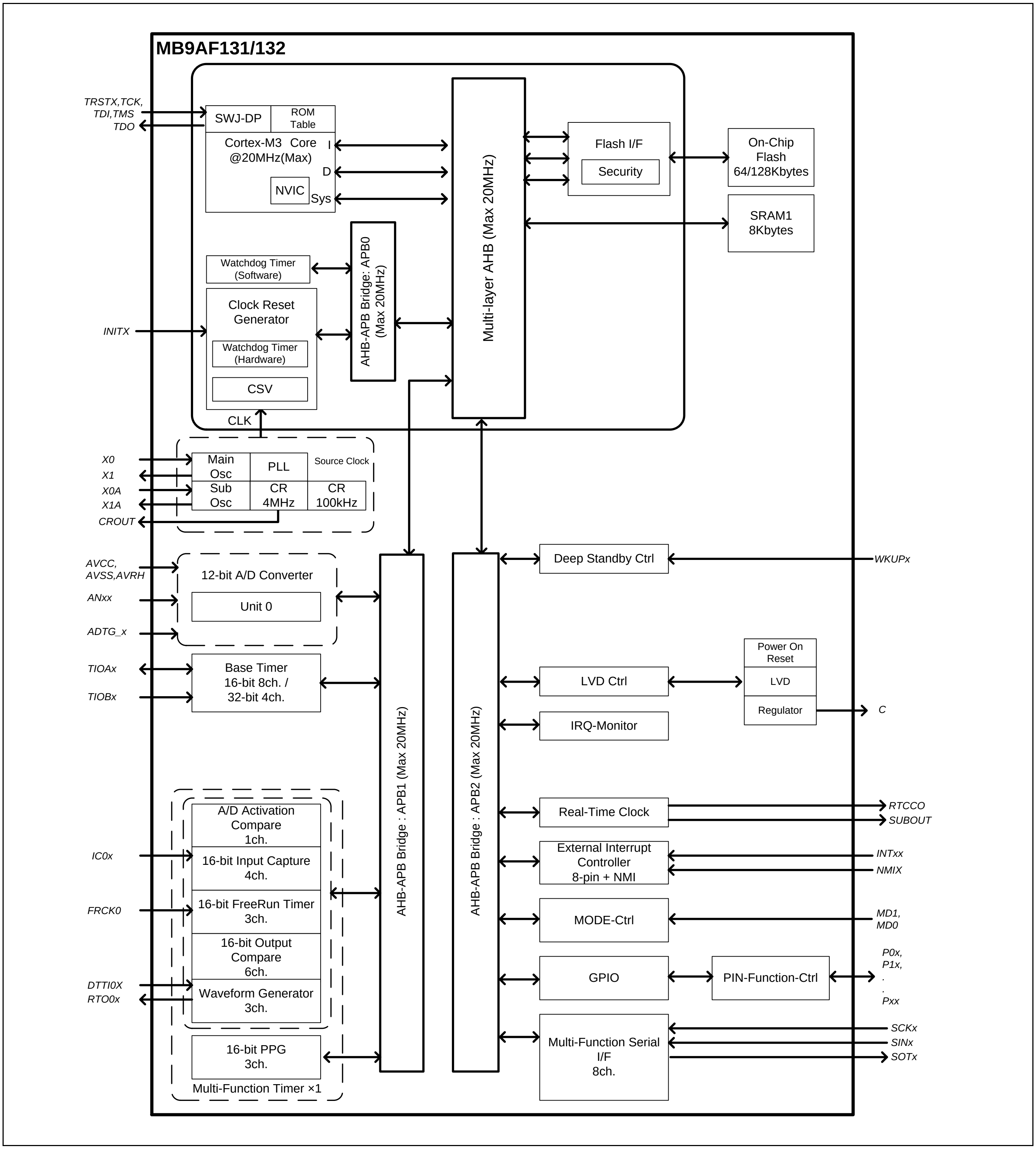
There is a possibility to receive wrong data due to the noise or other causes on the serial communication.
Therefore, design a printed circuit board so as to avoid noise.
Consider the case of receiving wrong data due to noise, perform error detection such as by applying a checksum of data at the end. If an error is detected, retransmit the data.

Differences in features among the products with different memory sizes and between Flash memory products and MASK products

The electric characteristics including power consumption, ESD, latch-up, noise characteristics, and oscillation characteristics among the products with different memory sizes and between Flash memory products and MASK products are different because chip layout and memory structures are different.

If you are switching to use a different product of the same series, please make sure to evaluate the electric characteristics.

8. Block Diagram

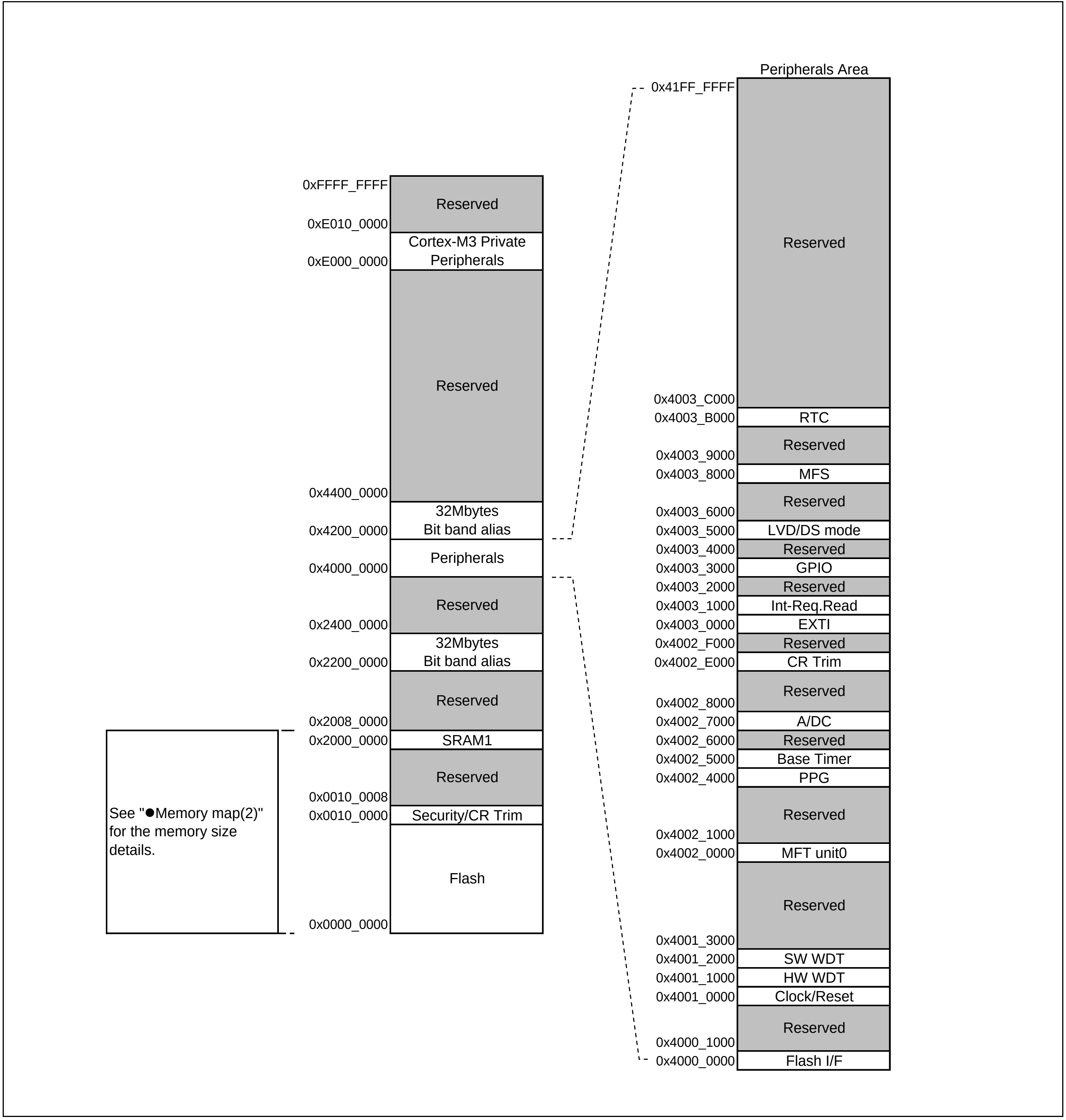


9. Memory Size

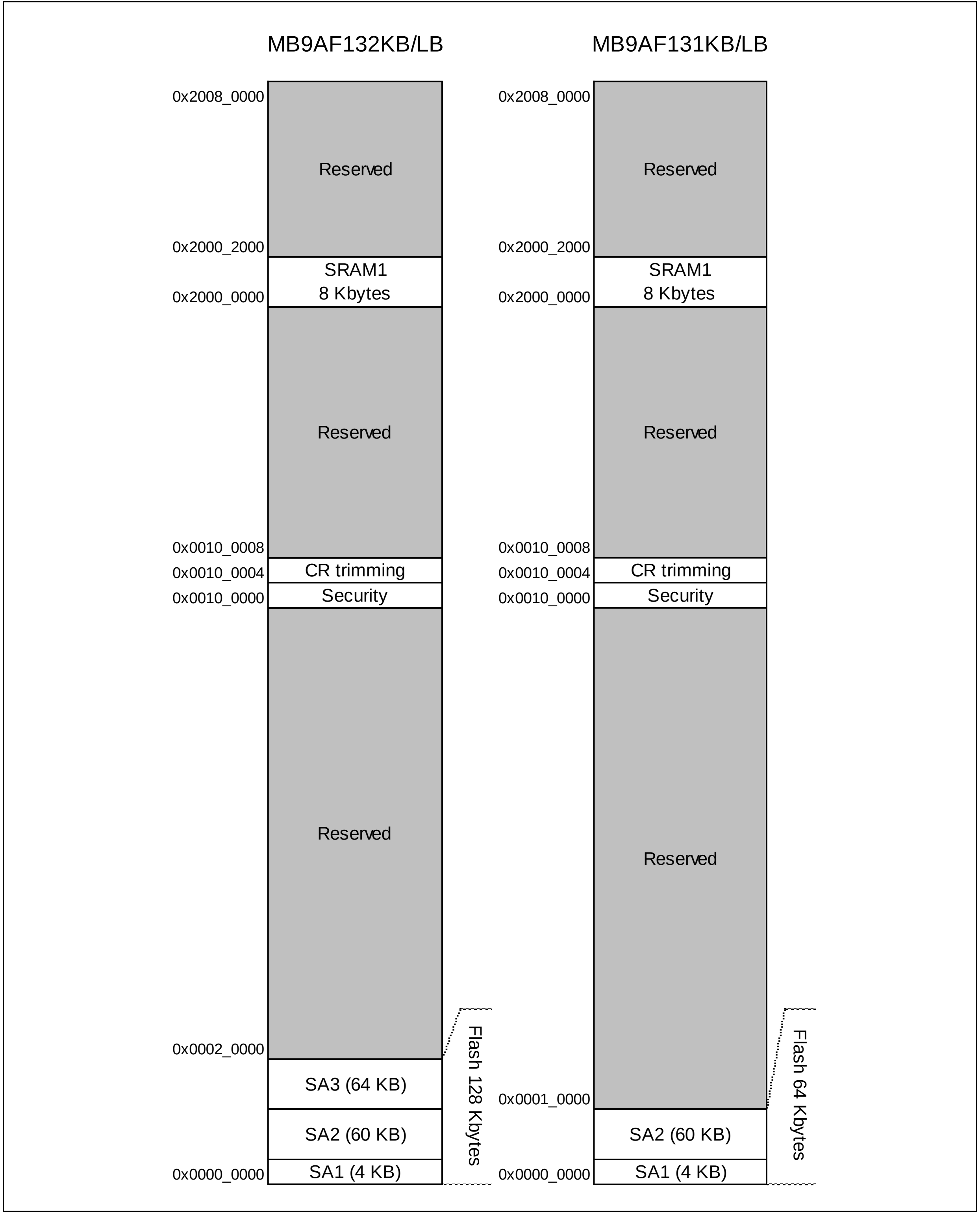
See Memory size in Product Lineup to confirm the memory size.

10. Memory Map

Memory Map (1)



Memory Map (2)



*: See MB9AAA0N/1A0N/A30N/130N/130L Series Flash Programming Manual to confirm the detail of Flash memory.

Peripheral Address Map

Start address	End address	Bus	Peripherals
0x4000_0000	0x4000_0FFF	AHB	Flash I/F register
0x4000_1000	0x4000_FFFF		Reserved
0x4001_0000	0x4001_0FFF	APB0	Clock/Reset Control
0x4001_1000	0x4001_1FFF		Hardware Watchdog timer
0x4001_2000	0x4001_2FFF		Software Watchdog timer
0x4001_3000	0x4001_4FFF		Reserved
0x4001_5000	0x4001_5FFF		Reserved
0x4001_6000	0x4001_FFFF		Reserved
0x4002_0000	0x4002_0FFF	APB1	Multi-function timer unit0
0x4002_1000	0x4002_1FFF		Reserved
0x4002_2000	0x4002_3FFF		Reserved
0x4002_4000	0x4002_4FFF		PPG
0x4002_5000	0x4002_5FFF		Base Timer
0x4002_6000	0x4002_6FFF		Reserved
0x4002_7000	0x4002_7FFF		A/D Converter
0x4002_8000	0x4002_DFFF		Reserved
0x4002_E000	0x4002_EFFF		Built-in CR trimming
0x4002_F000	0x4002_FFFF		Reserved
0x4003_0000	0x4003_0FFF	APB2	External Interrupt Controller
0x4003_1000	0x4003_1FFF		Interrupt Source Check Register
0x4003_2000	0x4003_2FFF		Reserved
0x4003_3000	0x4003_3FFF		GPIO
0x4003_4000	0x4003_4FFF		Reserved
0x4003_5000	0x4003_50FF		Low Voltage Detector
0x4003_5100	0x4003_5FFF		Deep stand-by mode Controller
0x4003_6000	0x4003_6FFF		Reserved
0x4003_7000	0x4003_7FFF		Reserved
0x4003_8000	0x4003_8FFF		Multi-function serial Interface
0x4003_9000	0x4003_9FFF		Reserved
0x4003_A000	0x4003_AFFF		Reserved
0x4003_B000	0x4003_BFFF		Real-time clock
0x4003_C000	0x4003_FFFF		Reserved
0x4004_0000	0x4004_FFFF	AHB	Reserved
0x4005_0000	0x4005_FFFF		Reserved
0x4006_0000	0x4006_0FFF		Reserved
0x4006_1000	0x4006_1FFF		Reserved
0x4006_2000	0x4006_2FFF		Reserved
0x4006_3000	0x4006_3FFF		Reserved
0x4006_4000	0x41FF_FFFF		Reserved

11. Pin Status in Each CPU State

The terms used for pin status have the following meanings.

■INITX = 0

This is the period when the INITX pin is the L level.

■INITX = 1

This is the period when the INITX pin is the H level.

■SPL = 0

This is the status that standby pin level setting bit (SPL) in standby mode control register (STB_CTL) is set to 0.

■SPL = 1

This is the status that standby pin level setting bit (SPL) in standby mode control register (STB_CTL) is set to 1.

■Input enabled

Indicates that the input function can be used.

■Internal input fixed at 0

This is the status that the input function cannot be used. Internal input is fixed at L.

■Hi-Z

Indicates that the pin drive transistor is disabled and the pin is put in the Hi-Z state.

■Setting disabled

Indicates that the setting is disabled.

■Maintain previous state

Maintains the state that was immediately prior to entering the current mode.
If a built-in peripheral function is operating, the output follows the peripheral function.
If the pin is being used as a port, that output is maintained.

■Analog input is enabled

Indicates that the analog input is enabled.

■Trace output

Indicates that the trace function can be used.

■GPIO selected

In Deep Standby mode, pins switch to the general-purpose I/O port.

List of Pin Status

Pin status type	Function group	Power-on reset or low voltage detection state	INITX input state	Device internal reset state	Run mode or Sleep mode state	Timer mode, RTC mode, or Stop mode state		Deep Standby RTC mode or Deep Standby Stop mode state		Return from Deep Standby mode state
		Power supply unstable	Power supply stable		Power supply stable	Power supply stable		Power supply stable		Power supply stable
		-	INITX = 0	INITX = 1	INITX = 1	INITX = 1		INITX = 1		INITX = 1
		-	-	-	-	SPL = 0	SPL = 1	SPL = 0	SPL = 1	-
A	Main crystal oscillator input pin	Input enabled	Input enabled	Input enabled	Input enabled	Input enabled	Input enabled	Input enabled	Input enabled	Input enabled
	External main clock input selected	Setting disabled	Setting disabled	Setting disabled	Maintain previous state	Maintain previous state / When oscillation stop*1, output maintain previous state / Internal input fixed at 0	Hi-Z / Input enabled / When oscillation stop*1, Hi-Z / Internal input fixed at 0	Output maintain previous state / Internal input fixed at 0	Hi-Z / Internal input fixed at 0	GPIO selected
	GPIO selected	Setting disabled	Setting disabled	Setting disabled	Maintain previous state	Output maintain previous state / Internal input fixed at 0	Hi-Z / Internal input fixed at 0	Output maintain previous state / Internal input fixed at 0	Hi-Z / Internal input fixed at 0	Maintain previous state
B	Main crystal oscillator output pin	Hi-Z / Internal input fixed at 0	Hi-Z / Internal input fixed at 0	Hi-Z / Internal input fixed at 0	Maintain previous state / When oscillation stop*1, Hi-Z output / Internal input fixed at 0	Maintain previous state / When oscillation stop*1, Hi-Z output / Internal input fixed at 0	Maintain previous state / When oscillation stop*1, Hi-Z output / Internal input fixed at 0	Maintain previous state / When oscillation stop*1, Hi-Z output / Internal input fixed at 0	Maintain previous state / When oscillation stop*1, Hi-Z output / Internal input fixed at 0	Maintain previous state / When oscillation stop*1, Hi-Z output / Internal input fixed at "0"
	GPIO selected	Setting disabled	Setting disabled	Setting disabled	Maintain previous state	Maintain previous state	Hi-Z / Internal input fixed at 0	Maintain previous state	Hi-Z / Internal input fixed at 0	Maintain previous state
C	INITX input pin	Pull-up / Input enabled	Pull-up / Input enabled	Pull-up / Input enabled	Pull-up / Input enabled	Pull-up / Input enabled	Pull-up / Input enabled	Pull-up / Input enabled	Pull-up / Input enabled	Pull-up / Input enabled

Pin status type	Function group	Power-on reset or low voltage detection state	INITX input state	Device internal reset state	Run mode or Sleep mode state	Timer mode, RTC mode, or Stop mode state		Deep Standby RTC mode or Deep Standby Stop mode state		Return from Deep Standby mode state
		Power supply unstable	Power supply stable		Power supply stable	Power supply stable		Power supply stable		Power supply stable
		-	INITX = 0	INITX = 1	INITX = 1	INITX = 1		INITX = 1		INITX = 1
		-	-	-	-	SPL = 0	SPL = 1	SPL = 0	SPL = 1	-
D	Mode input pin	Input enabled	Input enabled	Input enabled	Input enabled	Input enabled	Input enabled	Input enabled	Input enabled	Input enabled
E	JTAG selected	Hi-Z	Pull-up / Input enabled	Pull-up / Input enabled	Maintain previous state	Maintain previous state	Maintain previous state	Maintain previous state	Maintain previous state	Maintain previous state
	GPIO selected	Setting disabled	Setting disabled	Setting disabled			Hi-Z / Internal input fixed at 0		Hi-Z / Internal input fixed at 0	
F	External interrupt enabled selected	Setting disabled	Setting disabled	Setting disabled	Maintain previous state	Maintain previous state	Maintain previous state	GPIO selected	Hi-Z / Internal input fixed at 0	GPIO selected
	Resource other than above selected	Hi-Z	Hi-Z / Input enabled	Hi-Z / Input enabled			Hi-Z / Internal input fixed at 0			
	GPIO selected							Maintain previous state		Maintain previous state
G	WKUP enabled	Setting disabled	Setting disabled	Setting disabled	Maintain previous state	Maintain previous state	Hi-Z / Internal input fixed at 0	WKUP input enabled	Hi-Z / WKUP input enabled	GPIO selected
	External interrupt enabled selected	Setting disabled	Setting disabled	Setting disabled			Maintain previous state	GPIO selected	Hi-Z / Internal input fixed at 0	GPIO selected
	Resource other than above selected	Hi-Z	Hi-Z / Input enabled	Hi-Z / Input enabled			Hi-Z / Internal input fixed at 0			
	GPIO selected							Maintain previous state		Maintain previous state
H	Resource selected	Hi-Z	Hi-Z / Input enabled	Hi-Z / Input enabled	Maintain previous state	Maintain previous state	Hi-Z / Internal input fixed at 0	GPIO selected	Hi-Z / Internal input fixed at 0	GPIO selected
	GPIO selected							Maintain previous state		Maintain previous state

Pin status type	Function group	Power-on reset or low voltage detection state	INITX input state	Device internal reset state	Run mode or Sleep mode state	Timer mode, RTC mode, or Stop mode state		Deep Standby RTC mode or Deep Standby Stop mode state		Return from Deep Standby mode state
		Power supply unstable	Power supply stable		Power supply stable	Power supply stable		Power supply stable		Power supply stable
		-	INITX = 0	INITX = 1	INITX = 1	INITX = 1		INITX = 1		INITX = 1
		-	-	-	-	SPL = 0	SPL = 1	SPL = 0	SPL = 1	-
I	NMIX selected	Setting disabled	Setting disabled	Setting disabled	Maintain previous state	Maintain previous state	Maintain previous state	WKUP input enabled	Hi-Z / WKUP input enabled	GPIO selected
	Resource other than above selected	Hi-Z	Hi-Z / Input enabled	Hi-Z / Input enabled			Hi-Z / Internal input fixed at 0			
	GPIO selected									Maintain previous state
J	Analog input selected	Hi-Z	Hi-Z / Internal input fixed at 0 / Analog input enabled	Hi-Z / Internal input fixed at 0 / Analog input enabled	Hi-Z / Internal input fixed at 0 / Analog input enabled	Hi-Z / Internal input fixed at 0 / Analog input enabled	Hi-Z / Internal input fixed at 0 / Analog input enabled	Hi-Z / Internal input fixed at 0 / Analog input enabled	Hi-Z / Internal input fixed at 0 / Analog input enabled	Hi-Z / Internal input fixed at 0 / Analog input enabled
	Resource other than above selected	Setting disabled	Setting disabled	Setting disabled	Maintain previous state	Maintain previous state	Hi-Z / Internal input fixed at 0	GPIO selected	Hi-Z / Internal input fixed at 0	GPIO selected
	GPIO selected							Maintain previous state		Maintain previous state
K	Analog input selected	Hi-Z	Hi-Z / Internal input fixed at 0 / Analog input enabled	Hi-Z / Internal input fixed at 0 / Analog input enabled	Hi-Z / Internal input fixed at 0 / Analog input enabled	Hi-Z / Internal input fixed at 0 / Analog input enabled	Hi-Z / Internal input fixed at 0 / Analog input enabled	Hi-Z / Internal input fixed at 0 / Analog input enabled	Hi-Z / Internal input fixed at 0 / Analog input enabled	Hi-Z / Internal input fixed at 0 / Analog input enabled
	External interrupt enabled selected	Setting disabled	Setting disabled	Setting disabled	Maintain previous state	Maintain previous state	Maintain previous state	GPIO selected	Hi-Z / Internal input fixed at 0	GPIO selected
	Resource other than above selected						Hi-Z / Internal input fixed at 0			
	GPIO selected							Maintain previous state		Maintain previous state

Pin status type	Function group	Power-on reset or low voltage detection state	INITX input state	Device internal reset state	Run mode or Sleep mode state	Timer mode, RTC mode, or Stop mode state		Deep Standby RTC mode or Deep Standby Stop mode state		Return from Deep Standby mode state
		Power supply unstable	Power supply stable		Power supply stable	Power supply stable		Power supply stable		Power supply stable
		-	INITX = 0	INITX = 1	INITX = 1	INITX = 1		INITX = 1		INITX = 1
		-	-	-	-	SPL = 0	SPL = 1	SPL = 0	SPL = 1	-
L	Analog input selected	Hi-Z	Hi-Z / Internal input fixed at 0 / Analog input enabled	Hi-Z / Internal input fixed at 0 / Analog input enabled	Hi-Z / Internal input fixed at 0 / Analog input enabled	Hi-Z / Internal input fixed at 0 / Analog input enabled	Hi-Z / Internal input fixed at 0 / Analog input enabled	Hi-Z / Internal input fixed at 0 / Analog input enabled	Hi-Z / Internal input fixed at 0 / Analog input enabled	Hi-Z / Internal input fixed at 0 / Analog input enabled
	WKUP enabled	Setting disabled	Setting disabled	Setting disabled	Maintain previous state	Maintain previous state	Hi-Z / Internal input fixed at 0	WKUP input enabled	Hi-Z / WKUP input enabled	GPIO selected
	External interrupt enabled selected						Maintain previous state	GPIO selected	Hi-Z / Internal input fixed at 0	
	Resource other than above selected						Hi-Z / Internal input fixed at 0			
	GPIO selected							Maintain previous state		Maintain previous state
M	Sub crystal oscillator input pin	Input enabled	Input enabled	Input enabled	Input enabled	Input enabled	Input enabled	Input enabled	Input enabled	Input enabled
	External sub clock input selected	Setting disabled	Setting disabled	Setting disabled	Maintain previous state	Maintain previous state / When oscillation stop[*2], output maintain previous state / Internal input fixed at 0	Hi-Z / Input enabled / When oscillation stop[*2], Hi-Z / Internal input fixed at 0	Maintain previous state / When oscillation stop[*2], output maintain previous state / Internal input fixed at 0	Hi-Z / Input enabled / When oscillation stop[*2], Hi-Z / Internal input fixed at 0	Maintain previous state / When Return from Deep Stand-by STOP mode, GPIO selected
	GPIO selected	Setting disabled	Setting disabled	Setting disabled	Maintain previous state	Output maintain previous state / Internal input fixed at 0	Hi-Z / Internal input fixed at 0	Output maintain previous state / Internal input fixed at 0	Hi-Z / Internal input fixed at 0	Maintain previous state

Pin status type	Function group	Power-on reset or low voltage detection state	INITX input state	Device internal reset state	Run mode or Sleep mode state	Timer mode, RTC mode, or Stop mode state		Deep Standby RTC mode or Deep Standby Stop mode state		Return from Deep Standby mode state
		Power supply unstable	Power supply stable		Power supply stable	Power supply stable		Power supply stable		Power supply stable
		-	INITX = 0	INITX = 1	INITX = 1	INITX = 1		INITX = 1		INITX = 1
		-	-	-	-	SPL = 0	SPL = 1	SPL = 0	SPL = 1	-
N	Sub crystal oscillator output pin	Hi-Z / Internal input fixed at 0	Hi-Z / Internal input fixed at 0	Hi-Z / Internal input fixed at 0	Maintain previous state	Maintain previous state / When oscillation stops*2, Hi-Z / Internal input fixed at 0	Maintain previous state / When oscillation stops*2, Hi-Z / Internal input fixed at 0	Maintain previous state / When oscillation stops*2, Hi-Z / Internal input fixed at 0	Maintain previous state / When oscillation stops*2, Hi-Z / Internal input fixed at 0	Maintain previous state / When oscillation stops*2, Hi-Z / Internal input fixed at 0
	GPIO selected	Setting disabled	Setting disabled	Setting disabled	Maintain previous state	Maintain previous state	Hi-Z / Internal input fixed at 0	Maintain previous state	Hi-Z / Internal input fixed at 0	Maintain previous state
O	GPIO	Hi-Z	Hi-Z / Input enabled	Hi-Z / Input enabled	Maintain previous state	Maintain previous state	Hi-Z / Internal input fixed at 0	GPIO/ Internal input fixed at 0	Hi-Z / Internal input fixed at 0	Maintain previous state
P	Mode input pin	Input enabled	Input enabled	Input enabled	Input enabled	Input enabled	Input enabled	Input enabled	Input enabled	Input enabled
	GPIO selected	Setting disabled	Setting disabled	Setting disabled	Maintain previous state	Maintain previous state	Hi-Z / Input enabled	Maintain previous state	Hi-Z / Input enabled	Maintain previous state

*1: Oscillation is stopped at Sub run mode, Low-speed CR Run mode, Sub Sleep mode, Low-speed CR Sleep mode, Sub Timer mode, Low-speed CR Timer mode, RTC mode, Stop mode, Deep Standby RTC mode, and Deep Standby Stop mode.

*2: Oscillation is stopped at Stop mode and Deep Standby Stop mode.

12. Electrical Characteristics

12.1 Absolute Maximum Ratings

Parameter	Symbol	Rating		Unit	Remarks
		Min	Max		
Power supply voltage*1,*2	V_{CC}	V_{SS} - 0.5	V_{SS} + 6.5	V	
Analog power supply voltage*1,*3	AV_{CC}	V_{SS} - 0.5	V_{SS} + 6.5	V	
Analog reference voltage*1,*3	AVRH	V_{SS} - 0.5	V_{SS} + 6.5	V	
Input voltage*1	V_I	V_{SS} - 0.5	V_{CC} + 0.5 (≤ 6.5 V)	V	
		V_{SS} - 0.5	V_{SS} + 6.5	V	5V tolerant
Analog pin input voltage*1	V_{IA}	V_{SS} - 0.5	AV_{CC} + 0.5 (≤ 6.5 V)	V	
Output voltage*1	V_O	V_{SS} - 0.5	V_{CC} + 0.5 (≤ 6.5 V)	V	
L level maximum output current*4	I_{OL}	-	10	mA	
L level average output current*5	I_{OLAV}	-	4	mA	
L level total maximum output current	$\sum I_{OL}$	-	60	mA	
L level total average output current*6	$\sum I_{OLAV}$	-	30	mA	
H level maximum output current*4	I_{OH}	-	-10	mA	
H level average output current*5	I_{OHAV}	-	- 4	mA	
H level total maximum output current	$\sum I_{OH}$	-	-60	mA	
H level total average output current*6	$\sum I_{OHAV}$	-	-30	mA	
Power consumption	P_D	-	400	mW	
Storage temperature	T_{STG}	- 55	+ 150	°C	

*1: These parameters are based on the condition that $V_{SS} = AV_{SS} = 0.0$ V.

*2: V_{CC} must not drop below V_{SS} - 0.5 V.

*3: Be careful not to exceed V_{CC} + 0.5 V, for example, when the power is turned on.

*4: The maximum output current is defined as the value of the peak current flowing through any one of the corresponding pins.

*5: The average output current is defined as the average current value flowing through any one of the corresponding pins for a 100 ms period.

*6: The total average output current is defined as the average current value flowing through all of corresponding pins for a 100 ms.

WARNING:

– *Semiconductor devices can be permanently damaged by application of stress (voltage, current, temperature, etc.) in excess of absolute maximum ratings. Do not exceed these ratings.*

12.2 Recommended Operating Conditions

(V_{SS} = AV_{SS} = 0.0V)

Parameter		Symbol	Conditions	Value		Unit	Remarks
				Min	Max		
Power supply voltage		V_{CC}	-	1.8	5.5	V	
Analog power supply voltage		AV_{CC}	-	1.8	5.5	V	AV_{CC} = V_{CC}
Analog reference voltage		AVRH	-	2.7	AV_{CC}	V	$AV_{CC} \geq 2.7$ V
				AV_{CC}	AV_{CC}		$AV_{CC} < 2.7$ V
Smoothing capacitor		C_S	-	1	10	μF	For built-in Regulator *
Operating Temperature	LQA048, VNA048, LQD064, LQG064, VNC064	T_A	-	- 40	+ 85	°C	

*: See C Pin in Handling Devices for the connection of the smoothing capacitor.

WARNING:

– *The recommended operating conditions are required in order to ensure the normal operation of the semiconductor device. All of the device's electrical characteristics are warranted when the device is operated within these ranges.*
Always use semiconductor devices within their recommended operating condition ranges. Operation outside these ranges may adversely affect reliability and could result in device failure. No warranty is made with respect to uses, operating conditions, or combinations not represented on the data sheet. Users considering application outside the listed conditions are advised to contact their representatives beforehand.

12.3 DC Characteristics

12.3.1 Current Rating

(V_{CC} = AV_{CC} = 1.8V to 5.5V, V_{SS} = AV_{SS} = 0V, T_A = - 40°C to + 85°C)

Parameter	Symbol	Pin name	Conditions		Value		Unit	Remarks
					Typ^{*3}	Max^{*4}		
Power supply current	I_{CC}	VCC	PLL Run mode	CPU: 20 MHz, Peripheral: 20 MHz, Flash memory 0 Wait, FRWTR.RWT = 00, FSYNDN.SD = 000	20	25	mA	*1, *5
				CPU: 20 MHz, Peripheral: clock stopped, NOP operation	10	15	mA	*1, *5
			High-speed CR Run mode	CPU/Peripheral: 4 MHz^{*2} Flash memory 0 Wait FRWTR.RWT = 00 FSYNDN.SD = 000	4.5	5	mA	*1
			Sub Run mode	CPU/Peripheral: 32 kHz, Flash memory 0 Wait, FRWTR.RWT = 00, FSYNDN.SD = 000	0.25	0.35	mA	*1, *6
			Low-speed CR Run mode	CPU/Peripheral: 100 kHz, Flash memory 0 Wait, FRWTR.RWT = 00, FSYNDN.SD = 000	0.3	0.45	mA	*1
	I_{CCS}		PLL Sleep mode	Peripheral: 20 MHz	9	13	mA	*1, *5
			High-speed CR Sleep mode	Peripheral: 4 MHz^{*2}	2	2.5	mA	*1
			Sub Sleep mode	Peripheral: 32 kHz	0.1	0.2	mA	*1, *6
			Low-speed CR Sleep mode	Peripheral: 100 kHz	0.2	0.35	mA	*1

*1: When all ports are fixed.

*2: When setting it to 4 MHz by trimming.

*3: T_A=+25°C, V_{CC}=3.3 V

*4: T_A=+85°C, V_{CC}=5.5 V

*5: When using the crystal oscillator of 4 MHz(Including the current consumption of the oscillation circuit)

*6: When using the crystal oscillator of 32 kHz(Including the current consumption of the oscillation circuit)

Parameter	Symbol	Pin name	Conditions		Value		Unit	Remarks
					Typ[*2]	Max[*3]		
Power supply current	I_{CCT}	VCC	Main Timer mode	T_A = + 25°C, When LVD is off	1	3.6	mA	*1, *4
				T_A = + 85°C, When LVD is off	1.7	3.9	mA	*1, *4
			Sub Timer mode	T_A = + 25°C, When LVD is off	8.5	70	μA	*1, *5
				T_A = + 85°C, When LVD is off	18	170	μA	*1, *5
	I_{CCR}		RTC mode	T_A = + 25°C, When LVD is off	1.8	7.5	μA	*1, *5
				T_A = + 85°C, When LVD is off	7	62	μA	*1, *5
	I_{CCH}		Stop mode	T_A = + 25°C, When LVD is off	0.7	7	μA	*1
				T_A = + 85°C, When LVD is off	6	60	μA	*1
	I_{CCRD}		Deep Standby RTC mode	T_A = + 25°C, When LVD is off	1.6	3	μA	*1, *5
				T_A = + 85°C, When LVD is off	3.6	14.5	μA	*1, *5
	I_{CCHD}		Deep Standby Stop mode	T_A = + 25°C, When LVD is off	0.5	2.5	μA	*1
				T_A = + 85°C, When LVD is off	2.5	12.5	μA	*1

*1: When all ports are fixed.

*2: V_{CC} = 3.3 V

*3: V_{CC} = 5.5 V

*4: When using the crystal oscillator of 4 MHz(Including the current consumption of the oscillation circuit)

*5: When using the crystal oscillator of 32 kHz(Including the current consumption of the oscillation circuit)

Low Voltage Detection Current

(V_{CC} = AV_{CC} = 1.8 V to 5.5 V, V_{SS} = AV_{SS} = 0 V, T_A = - 40°C to + 85°C)

Parameter	Symbol	Pin name	Conditions	Value		Unit	Remarks
				Typ*	Max		
Low-voltage detection circuit (LVD) power supply current	I_{CCLVD}	VCC	For occurrence of reset or for occurrence of interrupt in normal mode operation	10	20	µA	When not detected
			For occurrence of reset and for occurrence of interrupt in normal mode operation	14	30	µA	
			For occurrence of interrupt in low-power mode operation	0.3	2	µA	When not detected

*: When V_{CC} = 3.3 V

Flash Memory Current

(V_{CC} = 1.8 V to 5.5 V, V_{SS} = 0 V, T_A = - 40°C to + 85°C)

Parameter	Symbol	Pin name	Conditions	Value		Unit	Remarks
				Typ	Max		
Flash memory write/erase current	$I_{CCFLASH}$	VCC	At Write/Erase	10.8	11.9	mA	

A/D Converter Current

(V_{CC} = AV_{CC} = 1.8 V to 5.5 V, V_{SS} = AV_{SS} = 0 V, T_A = - 40°C to + 85°C)

Parameter	Symbol	Pin name	Conditions	Value		Unit	Remarks
				Typ	Max		
Power supply current	I_{CCAD}	AVCC	At 1unit operation	1.4	2.5	mA	
			At stop	0.1	0.35	µA	
Reference power supply current	I_{CCAVRH}	AVRH	At 1unit operation AVRH=5.5 V	0.8	1.5	mA	
			At stop	0.1	0.3	µA	

12.3.2 Pin Characteristics

(V_{CC} = AV_{CC} = 1.8V to 5.5V, V_{SS} = AV_{SS} = 0V, T_A = - 40°C to + 85°C)

Parameter	Symbol	Pin name	Conditions	Value			Unit	Remarks
				Min	Typ	Max		
H level input voltage (hysteresis input)	V_{IHS}	MD0, MD1, PE0, PE2, PE3, P46, P47, INITX	-	V_{CC} × 0.8	-	V_{CC} + 0.3	V	
		P21, P22, P23, P50, P51, P52, P80, P81, P82	-	V_{CC}× 0.7	-	V_{SS} + 5.5	V	5V tolerant
		CMOS hysteresis input pins other than the above	-	V_{CC} × 0.7	-	V_{CC} + 0.3	V	
L level input voltage (hysteresis input)	V_{ILS}	MD0, MD1, PE0, PE2, PE3, P46, P47, INITX	-	V_{SS} - 0.3	-	V_{CC}× 0.2	V	
		CMOS hysteresis input pins other than the above	-	V_{SS} - 0.3	-	V_{CC}× 0.3	V	
H level output voltage	V_{OH}	Pxx	$V_{CC} \geq 4.5$ V I_{OH} = - 4 mA	V_{CC} - 0.5	-	V_{CC}	V	
			$V_{CC} < 4.5$ V I_{OH} = - 1 mA	V_{CC} - 0.5	-	V_{CC}		
L level output voltage	V_{OL}	Pxx	$V_{CC} \geq 4.5$ V I_{OL} = 4 mA	V_{SS}	-	0.4	V	
			$V_{CC} < 4.5$ V I_{OL} = 2 mA					
Input leak current	I_{IL}	-	-	- 5	-	+5	μA	
Pull-up resistance value	R_{PU}	Pull-up pin	$V_{CC} \geq 4.5$ V	25	50	100	kΩ	
			$V_{CC} < 4.5$ V	40	100	400		
Input capacitance	C_{IN}	Other than VCC, VSS, AVCC, AVSS, AVRH	-	-	5	15	pF	

12.4 AC Characteristics

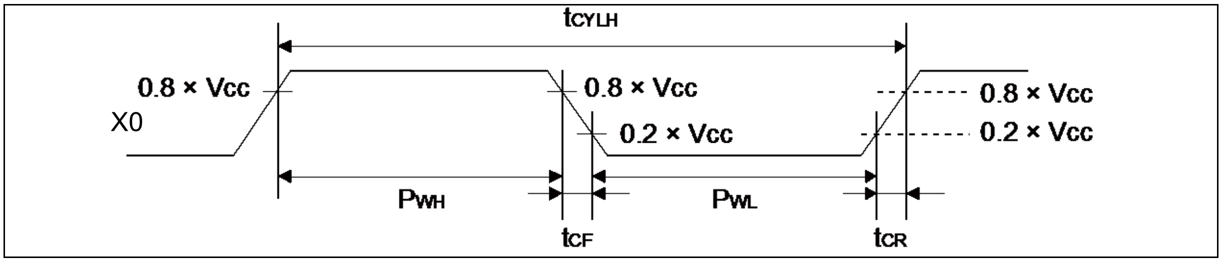
12.4.1 Main Clock Input Characteristics

(V_{CC} = 1.8V to 5.5V, V_{SS} = 0V, T_A = - 40°C to + 85°C)

Parameter	Symbol	Pin name	Conditions	Value		Unit	Remarks
				Min	Max		
Input frequency	f_{CH}	X0, X1	$V_{CC} \geq 2.0$ V	4	20	MHz	When crystal oscillator is connected
			$V_{CC} < 2.0$ V	4	4	MHz	
			$V_{CC} \geq 4.5$ V	4	20	MHz	When using external clock
			$V_{CC} < 4.5$ V	4	16	MHz	
Input clock cycle	t_{CYLH}		$V_{CC} \geq 4.5$ V	50	250	ns	When using external clock
			$V_{CC} < 4.5$ V	62.5	250	ns	
Input clock pulse width	-		P_{WH}/t_{CYLH}, P_{WL}/t_{CYLH}	45	55	%	When using external clock
Input clock rise time and fall time	t_{CF}, t_{CR}		-	-	5	ns	When using external clock
Internal operating clock*1 frequency	f_{CM}	-	-	-	20	MHz	Master clock
	f_{CC}	-	-	-	20	MHz	Base clock (HCLK/FCLK)
	f_{CP0}	-	-	-	20	MHz	APB0 bus clock*2
	f_{CP1}	-	-	-	20	MHz	APB1 bus clock*2
	f_{CP2}	-	-	-	20	MHz	APB2 bus clock*2
Internal operating clock*1 cycle time	t_{CYCC}	-	-	50	-	ns	Base clock (HCLK/FCLK)
	t_{CYCP0}	-	-	50	-	ns	APB0 bus clock*2
	t_{CYCP1}	-	-	50	-	ns	APB1 bus clock*2
	t_{CYCP2}	-	-	50	-	ns	APB2 bus clock*2

*1: For more information about each internal operating clock, see Chapter 2-1: Clock in FM3 Family Peripheral Manual.

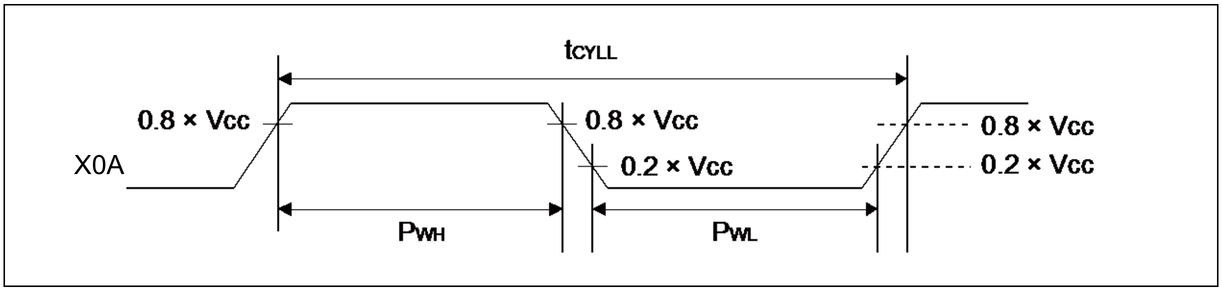
*2: For about each APB bus which each peripheral is connected to, see Block Diagram in this data sheet.



12.4.2 Sub Clock Input Characteristics

(V_{CC} = 1.8V to 5.5V, V_{SS} = 0V, T_A = - 40°C to + 85°C)

Parameter	Symbol	Pin name	Conditions	Value			Unit	Remarks
				Min	Typ	Max		
Input frequency	f_{CL}	X0A, X1A	-	-	32.768	-	kHz	When crystal oscillator is connected
			-	32	-	100	kHz	When using external clock
Input clock cycle	t_{CYLL}		-	10	-	31.25	μs	When using external clock
Input clock pulse width	-		P_{WH}/t_{CYLL}, P_{WL}/t_{CYLL}	45	-	55	%	When using external clock



12.4.3 Built-in CR Oscillation Characteristics

Built-in High-speed CR

(V_{CC} = 1.8V to 5.5V, V_{SS} = 0V, T_A = - 40°C to + 85°C)

Parameter	Symbol	Conditions		Value			Unit	Remarks
				Min	Typ	Max		
Clock frequency	f_{CRH}	$V_{CC} \geq$ 2.2 V	T_A = + 25°C	3.92	4	4.08	MHz	When trimming*1
			T_A = - 40°C to + 85°C	3.8	4	4.2		
			T_A = - 40°C to + 85°C	2.3	-	7.03		When not trimming
		V_{CC} < 2.2 V	T_A = + 25°C	3.4	4	4.6	MHz	When trimming*1
			T_A = - 40°C to + 85°C	3.16	4	4.84		
			T_A = - 40°C to + 85°C	2.3	-	7.03		When not trimming
Frequency stabilization time	t_{CRWT}	-		-	-	10	μs	*2

*1: In the case of using the values in CR trimming area of Flash memory at shipment for frequency trimming.

*2: This is the time to stabilize the frequency of High-speed CR clock after setting trimming value.
This period is able to use High-speed CR clock as source clock.

Built-in Low-speed CR

(V_{CC} = 1.8V to 5.5V, V_{SS} = 0V, T_A = - 40°C to + 85°C)

Parameter	Symbol	Conditions	Value			Unit	Remarks
			Min	Typ	Max		
Clock frequency	f_{CRL}	-	50	100	150	kHz	

12.4.4 Operating Conditions of Main PLL (In the case of using main clock for input of PLL)

(V_{CC} = 1.8V to 5.5V, V_{SS} = 0V, T_A = - 40°C to + 85°C)

Parameter	Symbol	Value			Unit	Remarks
		Min	Typ	Max		
PLL oscillation stabilization wait time*[1] (LOCK UP time)	t_{LOCK}	200	-	-	μs	
PLL input clock frequency	f_{PLLI}	4	-	20	MHz	
PLL multiplication rate	-	1	-	5	multiplier	
PLL macro oscillation clock frequency	f_{PLLO}	10	-	20	MHz	
Main PLL clock frequency*[2]	f_{CLKPLL}	-	-	20	MHz	

*1: Time from when the PLL starts operating until the oscillation stabilizes.

*2: For more information about Main PLL clock(CLKPLL), see Chapter 2-1: Clock in FM3 Family Peripheral Manual.

12.4.5 Operating Conditions of Main PLL (In the case of using built-in High-speed CR clock for input clock of Main PLL)

(V_{CC} = 2.2V to 5.5V, V_{SS} = 0V, T_A = - 40°C to + 85°C)

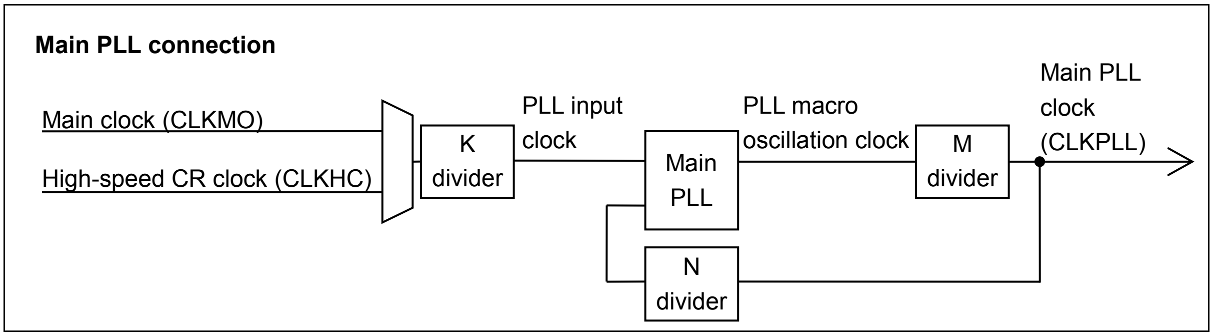
Parameter	Symbol	Value			Unit	Remarks
		Min	Typ	Max		
PLL oscillation stabilization wait time*[1] (LOCK UP time)	t_{LOCK}	200	-	-	μs	
PLL input clock frequency	f_{PLLI}	3.8	4	4.2	MHz	
PLL multiplication rate	-	3	-	4	multiplier	
PLL macro oscillation clock frequency	f_{PLLO}	11.4	-	16.8	MHz	
Main PLL clock frequency*[2]	f_{CLKPLL}	-	-	16.8	MHz	

*1: Time from when the PLL starts operating until the oscillation stabilizes.

*2: For more information about Main PLL clock(CLKPLL), see Chapter 2-1: Clock in FM3 Family Peripheral Manual.

Note:

– *Make sure to input to the Main PLL source clock, the High-speed CR clock (CLKHC) that the frequency has been trimmed. When setting PLL multiple rate, please take the accuracy of the built-in High-speed CR clock into account and prevent the master clock from exceeding the maximum frequency.*



12.4.6 Reset Input Characteristics

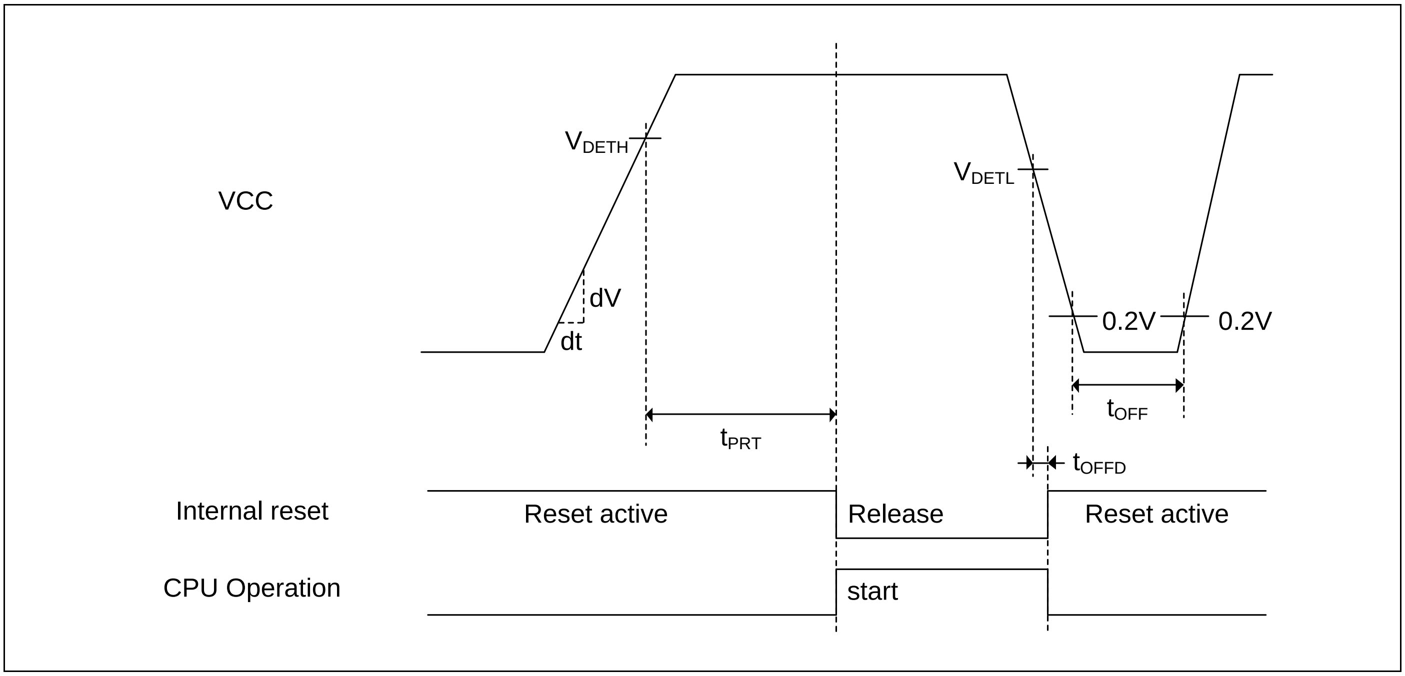
(V_{CC} = 1.8V to 5.5V, V_{SS} = 0V, T_A = - 40°C to + 85°C)

Parameter	Symbol	Pin name	Conditions	Value		Unit	Remarks
				Min	Max		
Reset input time	t_{INITX}	INITX	-	500	-	ns	
				1.5	-	ms	When RTC mode or Stop mode
				1.5	-	ms	When Deep Standby mode

12.4.7 Power-on Reset Timing

(V_{CC} = 1.8V to 5.5V, V_{SS} = 0V, T_A = - 40°C to + 85°C)

Parameter	Symbol	Pin name	Value			Unit	Remarks
			Min	Typ	Max		
Power supply rising time	dV/dt	VCC	0.1	-	-	V/ms	
Power supply shut down time	t_{OFF}		1	-	-	ms	
Reset release voltage	V_{DETH}		1.44	1.60	1.76	V	When voltage rises
Reset detection voltage	V_{DETL}		1.39	1.55	1.71	V	When voltage drops
Time until releasing Power-on reset	t_{PRT}		0.46	-	11.4	ms	dV/dt ≥ 0.1mV/µs
Reset detection delay time	t_{OFFD}		-	-	0.4	ms	dV/dt ≥ -0.04mV/µs

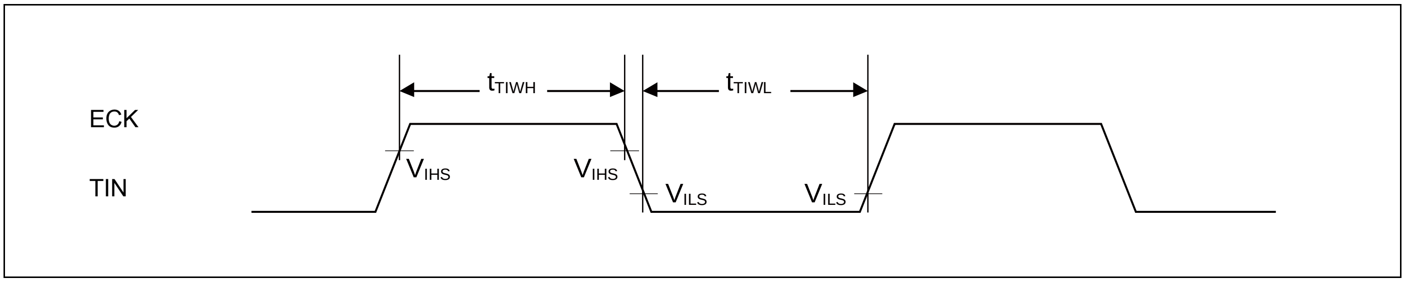


12.4.8 Base Timer Input Timing

Timer input timing

(V_{CC} = 1.8V to 5.5V, V_{SS} = 0V, T_A = - 40°C to + 85°C)

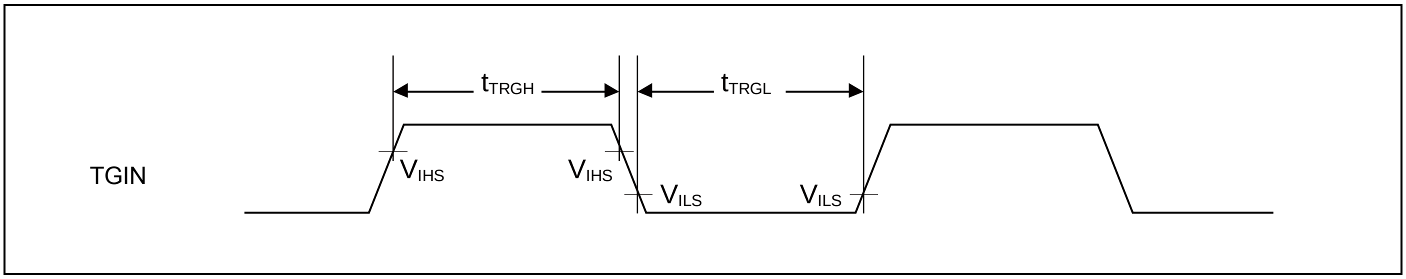
Parameter	Symbol	Pin name	Conditions	Value		Unit	Remarks
				Min	Max		
Input pulse width	t_{TIWH}, t_{TIWL}	TIOAn/TIOBn (when using as ECK,TIN)	-	2t_{CYCP}	-	ns	



Trigger input timing

(V_{CC} = 1.8V to 5.5V, V_{SS} = 0V, T_A = - 40°C to + 85°C)

Parameter	Symbol	Pin name	Conditions	Value		Unit	Remarks
				Min	Max		
Input pulse width	t_{TRGH}, t_{TRGL}	TIOAn/TIOBn (when using as TGIN)	-	2t_{CYCP}	-	ns	



Note:

– *t_{CYCP} indicates the APB bus clock cycle time.*
About the APB bus number which the Base Timer is connected to, see Block Diagram in this data sheet.

12.4.9 CSIO/UART Timing

CSIO (SPI = 0, SCINV = 0)

(V_{CC} = 1.8V to 5.5V, V_{SS} = 0V, T_A = - 40°C to + 85°C)

Parameter	Symbol	Pin name	Conditions	V_{CC} < 2.7 V		2.7 V ≤ V_{CC} < 4.5 V		V_{CC} ≥ 4.5 V		Unit
				Min	Max	Min	Max	Min	Max	
Baud rate	-	-	-	-	5	-	5	-	5	Mbps
Serial clock cycle time	t_{SCYC}	SCKx	Master mode	$4t_{CYCP}$	-	$4t_{CYCP}$	-	$4t_{CYCP}$	-	ns
SCK ↓ → SOT delay time	t_{SLOVI}	SCKx, SOTx		-40	+40	-30	+30	-20	+20	ns
SIN → SCK ↑ setup time	t_{IVSHI}	SCKx, SINx		75	-	50	-	30	-	ns
SCK ↑ → SIN hold time	t_{SHIXI}	SCKx, SINx		0	-	0	-	0	-	ns
Serial clock L pulse width	t_{SLSH}	SCKx	Slave mode	$2t_{CYCP}$ - 10	-	$2t_{CYCP}$ - 10	-	$2t_{CYCP}$ - 10	-	ns
Serial clock H pulse width	t_{SHSL}	SCKx		t_{CYCP} + 10	-	t_{CYCP} + 10	-	t_{CYCP} + 10	-	ns
SCK ↓ → SOT delay time	t_{SLOVE}	SCKx, SOTx		-	75	-	50	-	30*1 40*2	ns
SIN → SCK ↑ setup time	t_{IVSHE}	SCKx, SINx		10	-	10	-	10	-	ns
SCK ↑ → SIN hold time	t_{SHIXE}	SCKx, SINx		20	-	20	-	20	-	ns
SCK falling time	t_F	SCKx		-	5	-	5	-	5	ns
SCK rising time	t_R	SCKx		-	5	-	5	-	5	ns

*1 When PZR = 0.

*2 When PZR = 1.

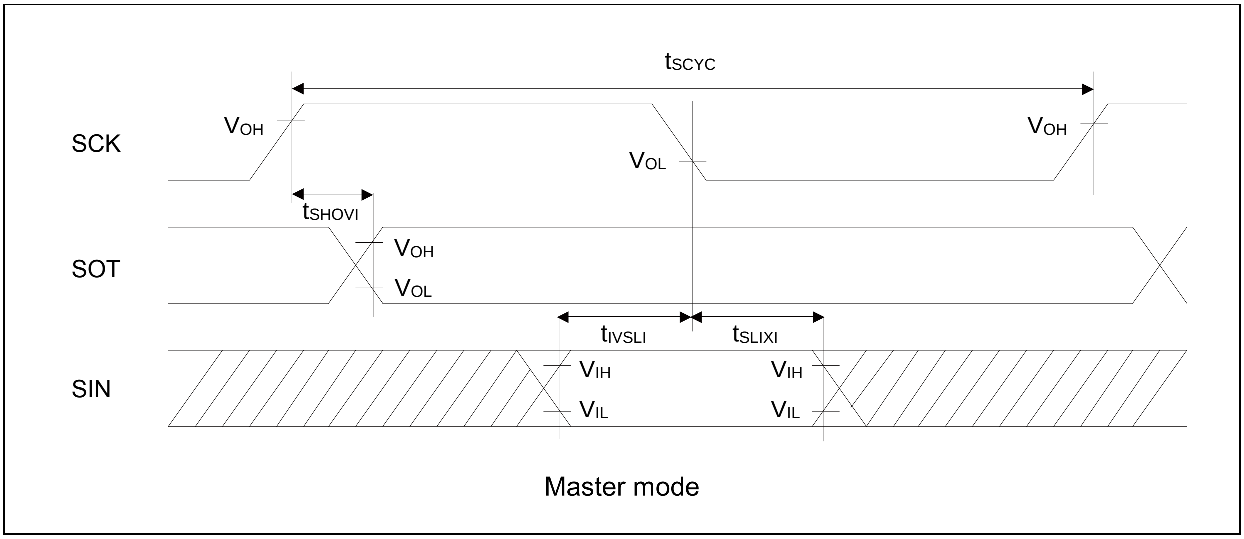
Notes:

– *The above characteristics apply to clock synchronous mode.*

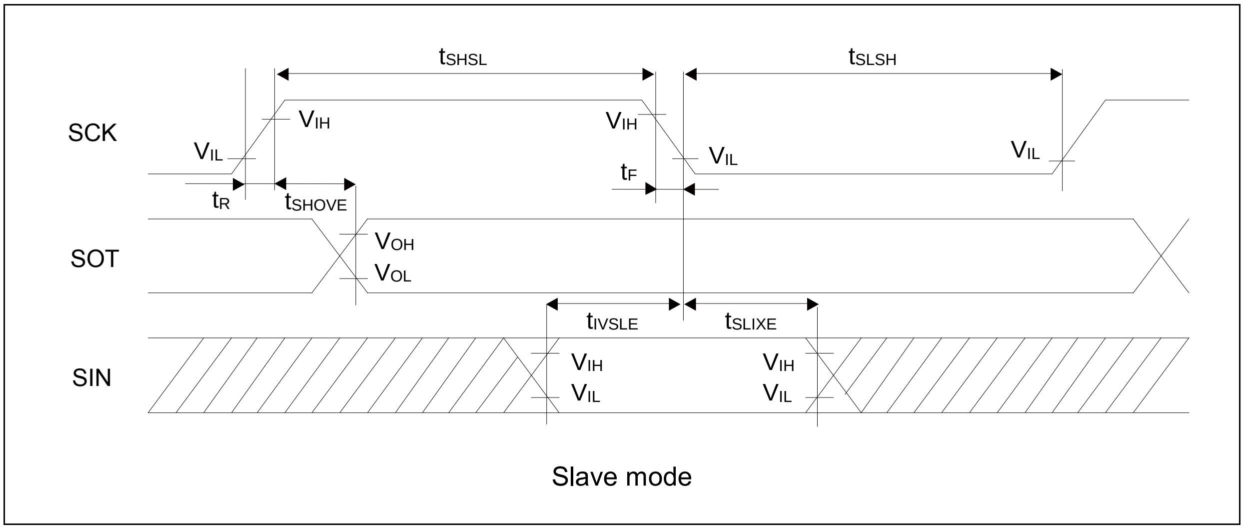
– *t_{CYCP} indicates the APB bus clock cycle time.*
About the APB bus number which Multi-function serial is connected to, see Block Diagram in this data sheet.

– *These characteristics only guarantee the same relocate port number.*
For example, the combination of SCKx_0 and SOTx_1 is not guaranteed.

– *When the external load capacitance C_L = 50 pF.*



Master mode



Slave mode

CSIO (SPI = 0, SCINV = 1)

(V_{CC} = 1.8V to 5.5V, V_{SS} = 0V, T_A = - 40°C to + 85°C)

Parameter	**Symbol**	**Pin name**	**Conditions**	**V_{CC} < 2.7 V**		**2.7 V ≤ V_{CC} < 4.5 V**		**V_{CC} ≥ 4.5 V**		**Unit**
				Min	**Max**	**Min**	**Max**	**Min**	**Max**	
Baud rate	-	-	-	-	5	-	5	-	5	Mbps
Serial clock cycle time	t_{SCYC}	SCKx	Master mode	$4t_{CYCP}$	-	$4t_{CYCP}$	-	$4t_{CYCP}$	-	ns
SCK ↑ → SOT delay time	t_{SHOVI}	SCKx, SOTx		-40	+40	-30	+30	-20	+20	ns
SIN → SCK ↓ setup time	t_{IVSLI}	SCKx, SINx		75	-	50	-	30	-	ns
SCK ↓ → SIN hold time	t_{SLIXI}	SCKx, SINx		0	-	0	-	0	-	ns
Serial clock L pulse width	t_{SLSH}	SCKx	Slave mode	$2t_{CYCP}$ - 10	-	$2t_{CYCP}$ - 10	-	$2t_{CYCP}$ - 10	-	ns
Serial clock H pulse width	t_{SHSL}	SCKx		t_{CYCP} + 10	-	t_{CYCP} + 10	-	t_{CYCP} + 10	-	ns
SCK ↑ → SOT delay time	t_{SHOVE}	SCKx, SOTx		-	75	-	50	-	30[*1] 40[*2]	ns
SIN → SCK ↓ setup time	t_{IVSLE}	SCKx, SINx		10	-	10	-	10	-	ns
SCK ↓ → SIN hold time	t_{SLIXE}	SCKx, SINx		20	-	20	-	20	-	ns
SCK falling time	t_F	SCKx		-	5	-	5	-	5	ns
SCK rising time	t_R	SCKx		-	5	-	5	-	5	ns

*1 When PZR = 0.

*2 When PZR = 1.

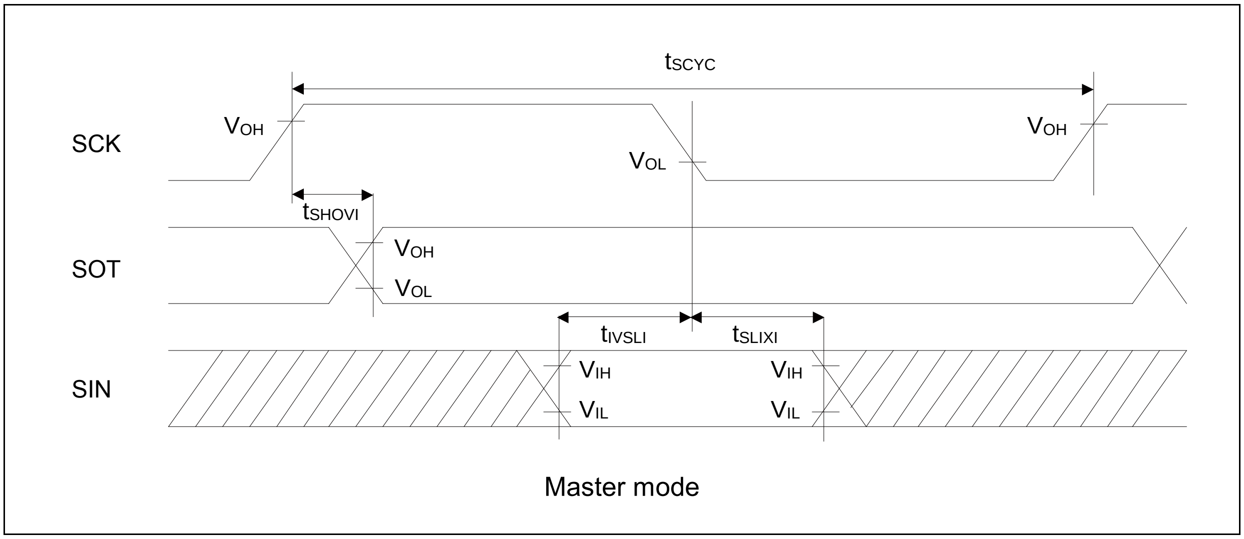
Notes:

– *The above characteristics apply to clock synchronous mode.*

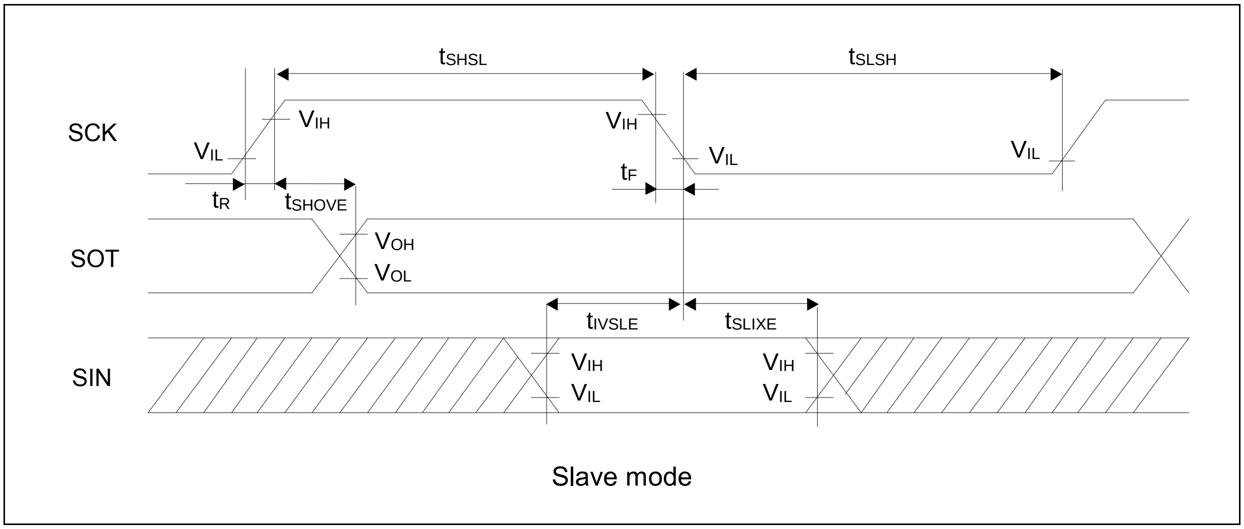
– *t_{CYCP} indicates the APB bus clock cycle time.*
About the APB bus number which Multi-function serial is connected to, see Block Diagram in this data sheet

– *These characteristics only guarantee the same relocate port number.*
For example, the combination of SCKx_0 and SOTx_1 is not guaranteed.

– *When the external load capacitance C_L = 50 pF.*



Master mode



Slave mode

CSIO (SPI = 1, SCINV = 0)

(V_{CC} = 1.8V to 5.5V, V_{SS} = 0V, T_A = - 40°C to + 85°C)

Parameter	Symbol	Pin name	Conditions	V_{CC} < 2.7 V		2.7 V ≤ V_{CC} < 4.5 V		V_{CC} ≥ 4.5 V		Unit
				Min	Max	Min	Max	Min	Max	
Baud rate	-	-	-	-	5	-	5	-	5	Mbps
Serial clock cycle time	t_{SCYC}	SCKx	Master mode	$4t_{CYCP}$	-	$4t_{CYCP}$	-	$4t_{CYCP}$	-	ns
SCK ↑ → SOT delay time	t_{SHOVI}	SCKx, SOTx		-40	+40	-30	+30	-20	+20	ns
SIN → SCK ↓ setup time	t_{IVSLI}	SCKx, SINx		75	-	50	-	30	-	ns
SCK ↓ → SIN hold time	t_{SLIXI}	SCKx, SINx		0	-	0	-	0	-	ns
SOT → SCK ↓ delay time	t_{SOVLI}	SCKx, SOTx		$2t_{CYCP} - 30$	-	$2t_{CYCP} - 30$	-	$2t_{CYCP} - 30$	-	ns
Serial clock L pulse width	t_{SLSH}	SCKx	Slave mode	$2t_{CYCP} - 10$	-	$2t_{CYCP} - 10$	-	$2t_{CYCP} - 10$	-	ns
Serial clock H pulse width	t_{SHSL}	SCKx		$t_{CYCP} + 10$	-	$t_{CYCP} + 10$	-	$t_{CYCP} + 10$	-	ns
SCK ↑ → SOT delay time	t_{SHOVE}	SCKx, SOTx		-	75	-	50	-	30*1 40*2	ns
SIN → SCK ↓ setup time	t_{IVSLE}	SCKx, SINx		10	-	10	-	10	-	ns
SCK ↓ → SIN hold time	t_{SLIXE}	SCKx, SINx		20	-	20	-	20	-	ns
SCK falling time	t_F	SCKx		-	5	-	5	-	5	ns
SCK rising time	t_R	SCKx		-	5	-	5	-	5	ns

*1 When PZR = 0.

*2 When PZR = 1.

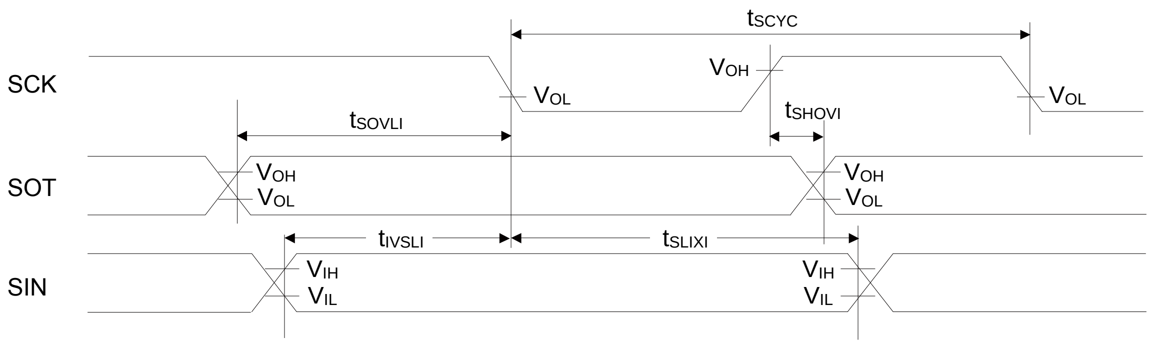
Notes:

– *The above characteristics apply to clock synchronous mode.*

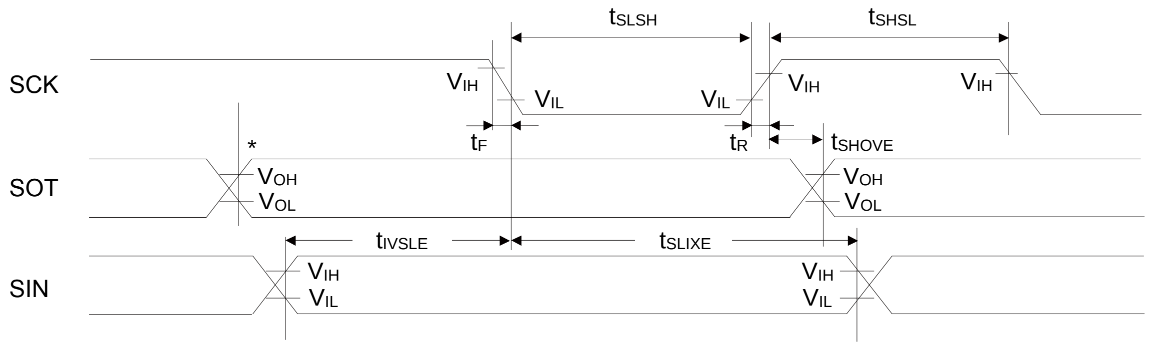
– *t_{CYCP} indicates the APB bus clock cycle time.*
About the APB bus number which Multi-function serial is connected to, see Block Diagram in this data sheet.

– *These characteristics only guarantee the same relocate port number.*
For example, the combination of SCKx_0 and SOTx_1 is not guaranteed.

– *When the external load capacitance C_L = 50 pF.*



Master mode



Slave mode

*: Changes when writing to TDR register

CSIO (SPI = 1, SCINV = 1)

(V_{CC} = 1.8V to 5.5V, V_{SS} = 0V, T_A = - 40°C to + 85°C)

Parameter	Symbol	Pin name	Conditions	V_{CC} < 2.7 V		2.7 V ≤ V_{CC} < 4.5 V		V_{CC} ≥ 4.5 V		Unit
				Min	Max	Min	Max	Min	Max	
Baud rate	-	-	-	-	5	-	5	-	5	Mbps
Serial clock cycle time	t_{SCYC}	SCKx	Master mode	4t_{CYCP}	-	4t_{CYCP}	-	4t_{CYCP}	-	ns
SCK ↓ → SOT delay time	t_{SLOVI}	SCKx, SOTx		-40	+40	-30	+30	-20	+20	ns
SIN → SCK ↑ setup time	t_{IVSHI}	SCKx, SINx		75	-	50	-	30	-	ns
SCK ↑ → SIN hold time	t_{SHIXI}	SCKx, SINx		0	-	0	-	0	-	ns
SOT → SCK ↑ delay time	t_{SOVHI}	SCKx, SOTx		2t_{CYCP} - 30	-	2t_{CYCP} – 30	-	2t_{CYCP} - 30	-	ns
Serial clock L pulse width	t_{SLSH}	SCKx	Slave mode	2t_{CYCP} - 10	-	2t_{CYCP} - 10	-	2t_{CYCP} - 10	-	ns
Serial clock H pulse width	t_{SHSL}	SCKx		t_{CYCP} + 10	-	t_{CYCP} + 10	-	t_{CYCP} + 10	-	ns
SCK ↓ → SOT delay time	t_{SLOVE}	SCKx, SOTx		-	75	-	50	-	30*1 40*2	ns
SIN → SCK ↑ setup time	t_{IVSHE}	SCKx, SINx		10	-	10	-	10	-	ns
SCK ↑ → SIN hold time	t_{SHIXE}	SCKx, SINx		20	-	20	-	20	-	ns
SCK falling time	t_F	SCKx		-	5	-	5	-	5	ns
SCK rising time	t_R	SCKx		-	5	-	5	-	5	ns

*1 When PZR = 0.

*2 When PZR = 1.

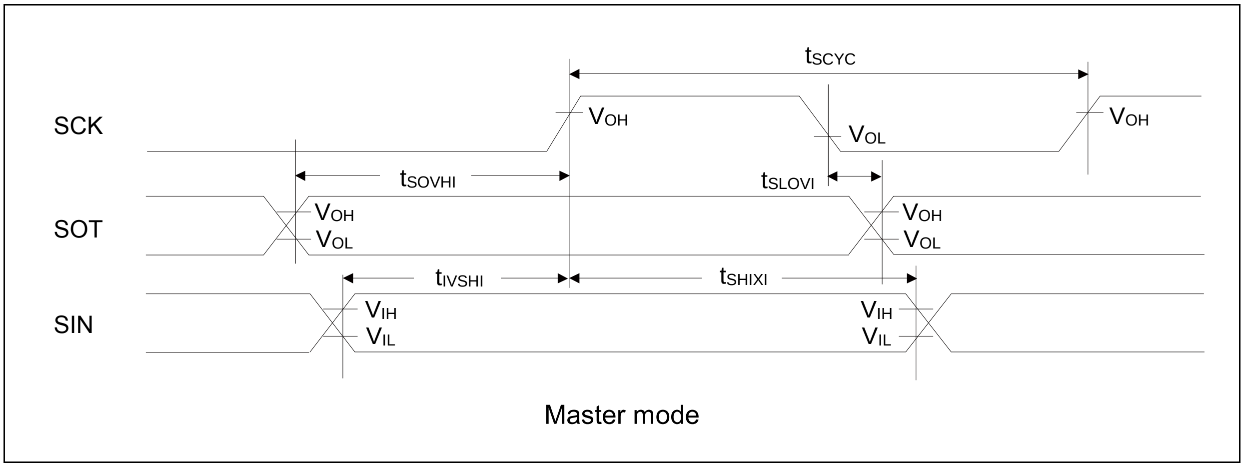
Notes:

– *The above characteristics apply to clock synchronous mode.*

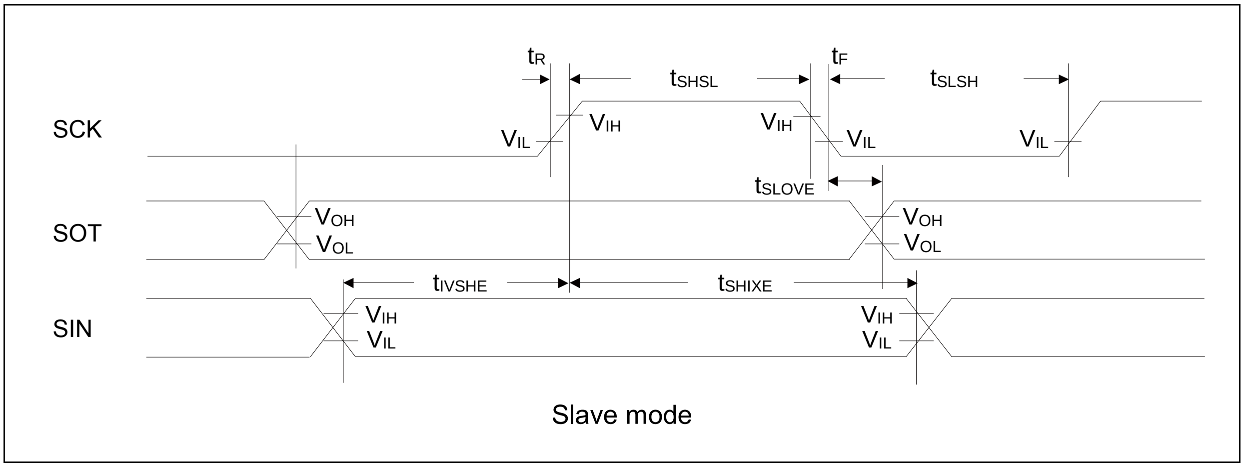
– *t_{CYCP} indicates the APB bus clock cycle time.*
About the APB bus number which Multi-function serial is connected to, see Block Diagram in this data sheet.

– *These characteristics only guarantee the same relocate port number.*
For example, the combination of SCKx_0 and SOTx_1 is not guaranteed.

– *When the external load capacitance C_L = 50 pF.*



Master mode

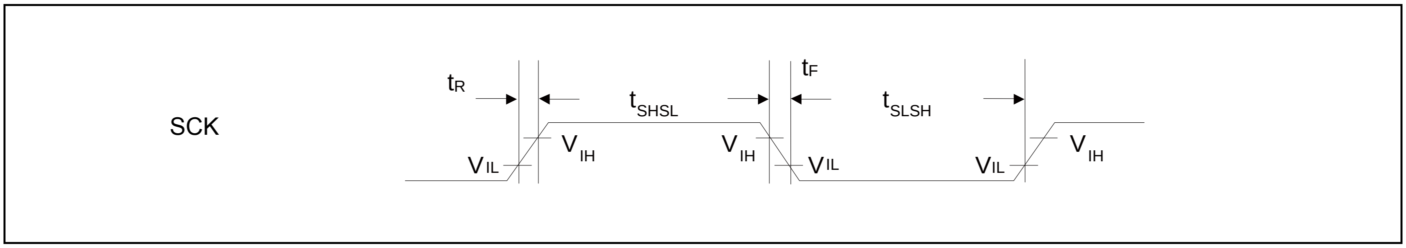


Slave mode

UART external clock input (EXT = 1)

(V_{CC} = 1.8V to 5.5V, V_{SS} = 0V, T_A = - 40°C to + 85°C)

Parameter	Symbol	Conditions	Value		Unit	Remarks
			Min	Max		
Serial clock L pulse width	t_{SLSH}	C_L = 50 pF	t_{CYCP} + 10	-	ns	
Serial clock H pulse width	t_{SHSL}		t_{CYCP} + 10	-	ns	
SCK falling time	t_F		-	5	ns	
SCK rising time	t_R		-	5	ns	



12.4.10 External Input Timing

(V_{CC} = 1.8V to 5.5V, V_{SS} = 0V, T_A = - 40°C to + 85°C)

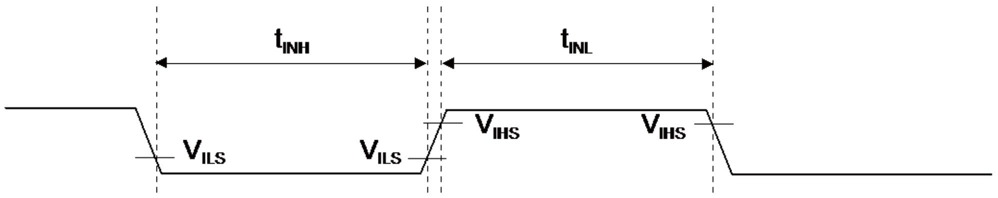
Parameter	Symbol	Pin name	Conditions	Value		Unit	Remarks
				Min	Max		
Input pulse width	t_{INH}, t_{INL}	ADTG	-	$2t_{CYCP}$*1	-	ns	A/D converter trigger input
		FRCKx					Free-run timer input clock
		ICxx					Input capture
		DTTIxX	-	$2t_{CYCP}$*1	-	ns	Waveform generator
		INTxx, NMIX	*2	$2t_{CYCP}$ + 100*1	-	ns	External interrupt NMI
			*3	500	-	ns	
		WKUPx	*4	500	-	ns	Deep Standby wake up

*1: t_{CYCP} indicates the APB bus clock cycle time.
About the APB bus number which A/D converter, Multi-function Timer, External interrupt, Deep Standby mode Controller is connected to, see Block Diagram in this data sheet.

*2: When in Run mode, in Sleep mode.

*3: When in Timer mode, in RTC mode, in Stop mode.

*4: When in Deep Standby RTC mode, in Deep Standby Stop mode.



12.4.11 I²C Timing

(V_{CC} = 1.8V to 5.5V, V_{SS} = 0V, T_A = - 40°C to + 85°C)

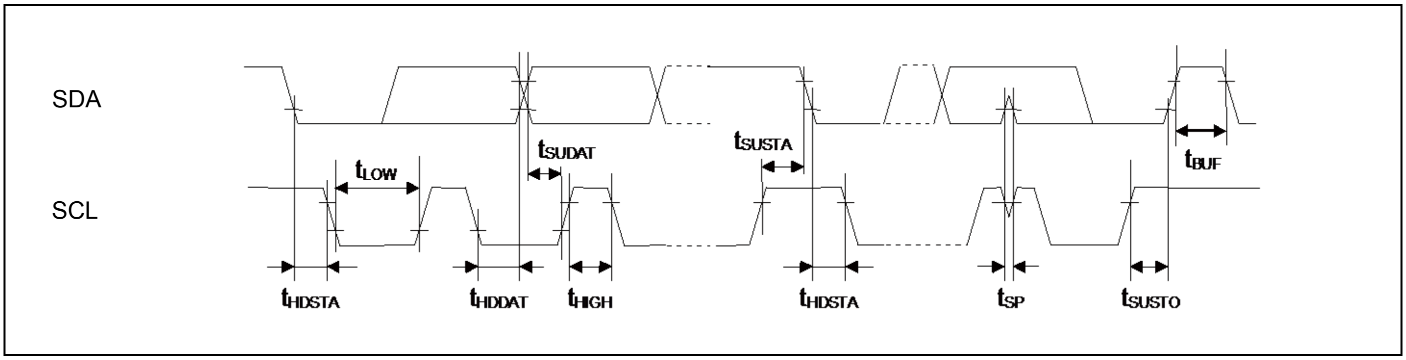
Parameter	Symbol	Conditions	Standard-mode		Fast-mode		Unit	Remarks
			Min	Max	Min	Max		
SCL clock frequency	f_{SCL}	C_L = 50 pF, R = (V_P/I_{OL})*1	0	100	0	400	kHz	
(Repeated) START condition hold time SDA ↓ → SCL ↓	t_{HDSTA}		4.0	-	0.6	-	μs	
SCL clock L width	t_{LOW}		4.7	-	1.3	-	μs	
SCL clock H width	t_{HIGH}		4.0	-	0.6	-	μs	
(Repeated) START condition setup time SCL ↑ → SDA ↓	t_{SUSTA}		4.7	-	0.6	-	μs	
Data hold time SCL ↓ → SDA ↓ ↑	t_{HDDAT}		0	3.45*2	0	0.9*3	μs	
Data setup time SDA ↓ ↑ → SCL ↑	t_{SUDAT}		250	-	100	-	ns	
STOP condition setup time SCL ↑ → SDA ↑	t_{SUSTO}		4.0	-	0.6	-	μs	
Bus free time between STOP condition and START condition	t_{BUF}		4.7	-	1.3	-	μs	
Noise filter	t_{SP}	-	2 t_{CYCP}*4	-	2 t_{CYCP}*4	-	ns	

*1: R and C_L represent the pull-up resistor and load capacitance of the SCL and SDA lines, respectively.
V_P indicates the power supply voltage of the pull-up resistor and I_{OL} indicates V_{OL} guaranteed current.

*2: The maximum t_{HDDAT} must satisfy that it does not extend at least L period (t_{LOW}) of device's SCL signal.

*3: A Fast-mode I²C bus device can be used on a Standard-mode I²C bus system as long as the device satisfies the requirement of $t_{SUDAT} \geq 250$ ns.

*4: t_{CYCP} is the APB bus clock cycle time.
About the APB bus number which I²C is connected to, see Block Diagram in this data sheet.
To use Standard-mode, set the APB bus clock at 2 MHz or more.
To use Fast-mode, set the APB bus clock at 8 MHz or more.



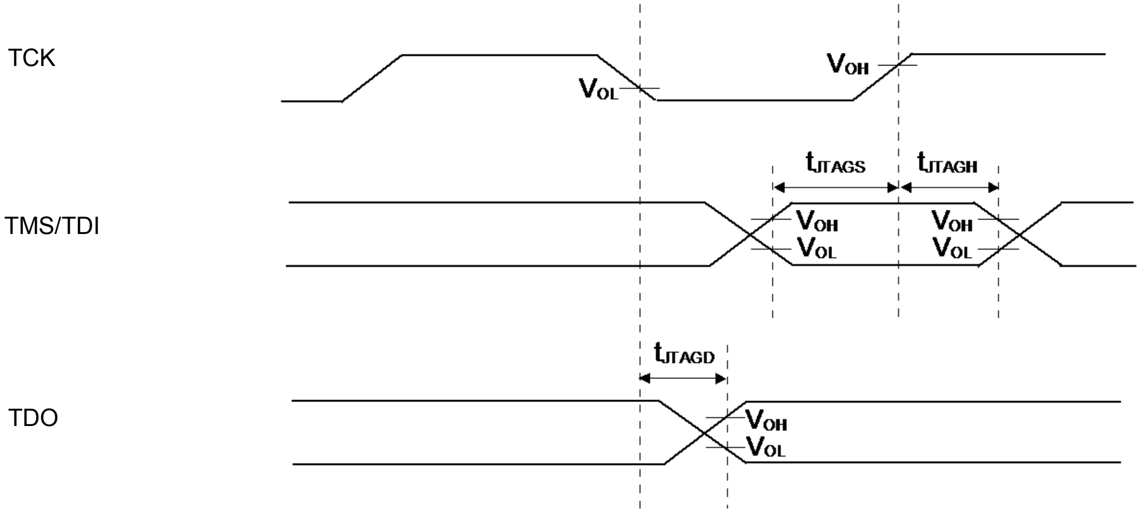
12.4.12 JTAG Timing

(V_{CC} = 1.8V to 5.5V, V_{SS} = 0V, T_A = - 40°C to + 85°C)

Parameter	Symbol	Pin name	Conditions	Value		Unit	Remarks
				Min	Max		
TMS,TDI setup time	t_{JTAGS}	TCK, TMS,TDI	$V_{CC} \geq 4.5$ V	15	-	ns	
			$V_{CC} < 4.5$ V				
TMS,TDI hold time	t_{JTAGH}	TCK, TMS,TDI	$V_{CC} \geq 4.5$ V	15	-	ns	
			$V_{CC} < 4.5$ V				
TDO delay time	t_{JTAGD}	TCK, TDO	$V_{CC} \geq 4.5$ V	-	30	ns	
			2.7 V $\leq V_{CC} <$ 4.5 V	-	45		
			$V_{CC} <$ 2.7 V	-	60		

Note:

– *When the external load capacitance C_L = 50 pF.*



12.5 12-bit A/D Converter

Electrical characteristics for the A/D converter

($V_{CC} = AV_{CC} = 1.8V$ to $5.5V$, $V_{SS} = AV_{SS} = 0V$, $T_A = -40°C$ to $+85°C$)

Parameter	Symbol	Pin name	Value			Unit	Remarks
			Min	Typ	Max		
Resolution	-	-	-	-	12	bit	
Integral Nonlinearity	INL	-	-	-	± 3.0	LSB	$AV_{CC} \geq 2.7$ V
			-	-	± 5.0	LSB	$AV_{CC} < 2.7$ V
Differential Nonlinearity	DNL	-	-	-	± 1.9	LSB	$AV_{CC} \geq 2.7$ V
			-	-	± 2.9	LSB	$AV_{CC} < 2.7$ V
Zero transition voltage	V_{ZT}	ANxx	-	-	± 20	mV	
Full-scale transition voltage	V_{FST}	ANxx	-	-	AVRH ± 20	mV	
Conversion time[*1]	-	-	1.0	-	-	µs	$AV_{CC} \geq 2.7$ V
			4.0				$AV_{CC} < 2.7$ V
Sampling time[*2]	t_S	-	0.3	-	10	µs	$AV_{CC} \geq 2.7$ V
			1.2				$AV_{CC} < 2.7$ V
Compare clock cycle[*3]	t_{CCK}	-	50	-	1000	ns	$AV_{CC} \geq 2.7$ V
			200				$AV_{CC} < 2.7$ V
Period of operation enable state transitions	t_{STT}	-	-	-	1	µs	
Analog input capacity	C_{AIN}	-	-	-	15	pF	
Analog input resistor	R_{AIN}	-	-	-	0.9	kΩ	$AV_{CC} \geq 4.5$ V
					1.6		$2.7 \text{ V} \leq AV_{CC} < 4.5$ V
					4.0		$AV_{CC} < 2.7$ V
Interchannel disparity	-	-	-	-	4	LSB	
Analog port input leak current	-	ANxx	-	-	0.3	µA	
Analog input voltage	-	ANxx	AV_{SS}	-	AVRH	V	
Reference voltage	-	AVRH	2.7	-	AV_{CC}	V	$AV_{CC} \geq 2.7$ V
			AV_{CC}				$AV_{CC} < 2.7$ V

[*1] The conversion time is the value of sampling time (t_S) + compare time (t_C).

The condition of the minimum conversion time is the following.

$AV_{CC} \geq 2.7$ V, HCLK=20 MHz sampling time: 0.3 µs, compare time: 0.7 µs
$AV_{CC} < 2.7$ V, HCLK=20 MHz sampling time: 1.2 µs, compare time: 2.8 µs

Ensure that it satisfies the value of the sampling time (t_S) and compare clock cycle (t_{CCK}).
For setting[*4] of the sampling time and compare clock cycle, see Chapter 1-1: A/D Converter in FM3 Family Peripheral Manual Analog Macro Part.
The register settings of the A/D Converter are reflected in the operation according to the APB bus clock timing.

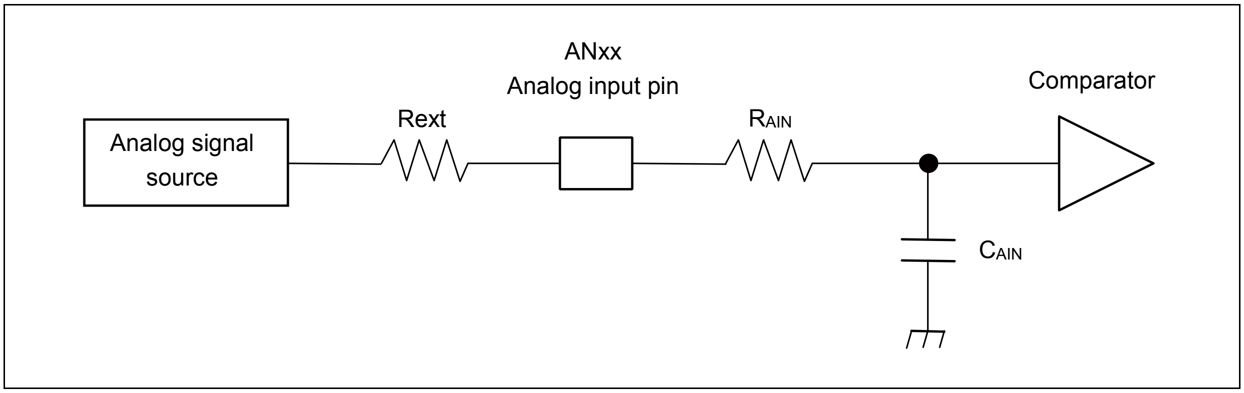
For the number of the APB bus to which the A/D Converter is connected, see Block Diagram.

The Base clock (HCLK) is used to generate the sampling time and the compare clock cycle.

[*2] A necessary sampling time changes by external impedance.

Ensure to set the sampling time to satisfy (Equation 1).

[*3] The compare time (t_C) is the value of (Equation 2).



(Equation 1) $t_S \geq (R_{AIN} + R_{EXT}) \times C_{AIN} \times 9$

t_S: Sampling time

R_{AIN}: Input resistor of A/D = 0.9 kΩ at $4.5\ V \leq AV_{CC} \leq 5.5\ V$

Input resistor of A/D = 1.6 kΩ at $2.7\ V \leq AV_{CC} < 4.5\ V$

Input resistor of A/D = 4.0 kΩ at $1.8\ V \leq AV_{CC} < 2.7\ V$

C_{AIN}: Input capacity of A/D = 15 pF at $1.8\ V \leq AV_{CC} \leq 5.5\ V$

R_{EXT}: Output impedance of external circuit

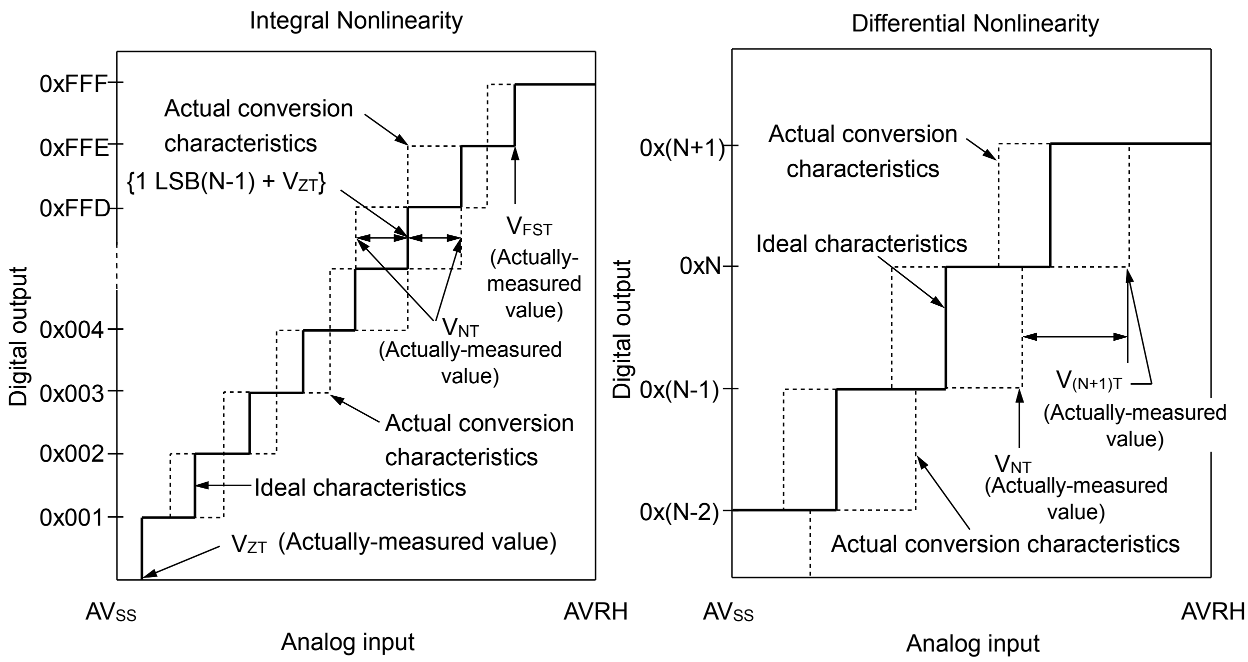
(Equation 2) $t_C = t_{CCK} \times 14$

t_C: Compare time

t_{CCK}: Compare clock cycle

Definition of 12-bit A/D Converter Terms

• Resolution	: Analog variation that is recognized by an A/D converter.
• Integral Nonlinearity	: Deviation of the line between the zero-transition point (0b000000000000 ←→ 0b000000000001) and the full-scale transition point (0b111111111110 ←→ 0b111111111111) from the actual conversion characteristics.
• Differential Nonlinearity	: Deviation from the ideal value of the input voltage that is required to change the output code by 1 LSB.



$$\text{Integral Nonlinearity of digital output N} = \frac{V_{NT} - \{1LSB \times (N - 1) + V_{ZT}\}}{1LSB} \ [LSB]$$

$$\text{Differential Nonlinearity of digital output N} = \frac{V_{(N+1)T} - V_{NT}}{1LSB} - 1 \ [LSB]$$

$$1LSB = \frac{V_{FST} - V_{ZT}}{4094}$$

N:	A/D converter digital output value.
V_{ZT}:	Voltage at which the digital output changes from 0x000 to 0x001.
V_{FST}:	Voltage at which the digital output changes from 0xFFE to 0xFFF.
V_{NT}:	Voltage at which the digital output changes from 0x(N − 1) to 0xN.

12.6 Low-Voltage Detection Characteristics

12.6.1 Low-Voltage Detection Reset

(T_A = - 40°C to + 85°C)

Parameter	Symbol	Conditions	Value			Unit	Remarks
			Min	Typ	Max		
Detected voltage	V_{DLR}	SVHR = 0001	1.43	1.53	1.63	V	When voltage drops
Released voltage	V_{DHR}		1.53	1.63	1.73	V	When voltage rises
Detected voltage	V_{DLR}	SVHR = 0100	1.80	1.93	2.06	V	When voltage drops
Released voltage	V_{DHR}		1.90	2.03	2.16	V	When voltage rises
LVD stabilization wait time	t_{LVDRW}	-	-	-	633 × t_{CYCP} *	µs	
Detection delay time	t_{LVDRD}	dV/dt ≥ -4mV/µs	-	-	60	µs	

*: t_{CYCP} indicates the APB2 bus clock cycle time.

12.6.2 Interrupt of Low-voltage Detection

Normal mode

(T_A = - 40°C to + 85°C)

Parameter	Symbol	Conditions	Value			Unit	Remarks
			Min	Typ	Max		
Detected voltage	V_{DLI}	SVHI = 0000	1.87	2.00	2.13	V	When voltage drops
Released voltage	V_{DHI}		1.97	2.10	2.23	V	When voltage rises
Detected voltage	V_{DLI}	SVHI = 0001	1.96	2.10	2.24	V	When voltage drops
Released voltage	V_{DHI}		2.06	2.20	2.34	V	When voltage rises
Detected voltage	V_{DLI}	SVHI = 0010	2.05	2.20	2.35	V	When voltage drops
Released voltage	V_{DHI}		2.15	2.30	2.45	V	When voltage rises
Detected voltage	V_{DLI}	SVHI = 0011	2.15	2.30	2.45	V	When voltage drops
Released voltage	V_{DHI}		2.25	2.40	2.55	V	When voltage rises
Detected voltage	V_{DLI}	SVHI = 0100	2.24	2.40	2.56	V	When voltage drops
Released voltage	V_{DHI}		2.34	2.50	2.66	V	When voltage rises
Detected voltage	V_{DLI}	SVHI = 0101	2.33	2.50	2.67	V	When voltage drops
Released voltage	V_{DHI}		2.43	2.60	2.77	V	When voltage rises
Detected voltage	V_{DLI}	SVHI = 0110	2.43	2.60	2.77	V	When voltage drops
Released voltage	V_{DHI}		2.53	2.70	2.87	V	When voltage rises
Detected voltage	V_{DLI}	SVHI = 0111	2.61	2.80	2.99	V	When voltage drops
Released voltage	V_{DHI}		2.71	2.90	3.09	V	When voltage rises
Detected voltage	V_{DLI}	SVHI = 1000	2.80	3.00	3.20	V	When voltage drops
Released voltage	V_{DHI}		2.90	3.10	3.30	V	When voltage rises
Detected voltage	V_{DLI}	SVHI = 1001	2.99	3.20	3.41	V	When voltage drops
Released voltage	V_{DHI}		3.09	3.30	3.51	V	When voltage rises
Detected voltage	V_{DLI}	SVHI = 1010	3.36	3.60	3.84	V	When voltage drops
Released voltage	V_{DHI}		3.46	3.70	3.94	V	When voltage rises
Detected voltage	V_{DLI}	SVHI = 1011	3.45	3.70	3.95	V	When voltage drops
Released voltage	V_{DHI}		3.55	3.80	4.05	V	When voltage rises
Detected voltage	V_{DLI}	SVHI = 1100	3.73	4.00	4.27	V	When voltage drops
Released voltage	V_{DHI}		3.83	4.10	4.37	V	When voltage rises
Detected voltage	V_{DLI}	SVHI = 1101	3.83	4.10	4.37	V	When voltage drops
Released voltage	V_{DHI}		3.93	4.20	4.47	V	When voltage rises
Detected voltage	V_{DLI}	SVHI = 1110	3.92	4.20	4.48	V	When voltage drops
Released voltage	V_{DHI}		4.02	4.30	4.58	V	When voltage rises
LVD stabilization wait time	t_{LVDIW}	-	-	-	633 × t_{CYCP}*	µs	
Detection delay time	t_{LVDID}	dV/dt ≥ - 4mV/µs	-	-	60	µs	

*: t_{CYCP} indicates the APB2 bus clock cycle time.

Low power mode

(T_A = - 40°C to + 85°C)

Parameter	Symbol	Conditions	Value			Unit	Remarks
			Min	Typ	Max		
Detected voltage	V_{DLIL}	SVHI = 0000	1.80	2.00	2.20	V	When voltage drops
Released voltage	V_{DHIL}		1.90	2.10	2.30	V	When voltage rises
Detected voltage	V_{DLIL}	SVHI = 0001	1.89	2.10	2.31	V	When voltage drops
Released voltage	V_{DHIL}		1.99	2.20	2.41	V	When voltage rises
Detected voltage	V_{DLIL}	SVHI = 0010	1.98	2.20	2.42	V	When voltage drops
Released voltage	V_{DHIL}		2.08	2.30	2.52	V	When voltage rises
Detected voltage	V_{DLIL}	SVHI = 0011	2.07	2.30	2.53	V	When voltage drops
Released voltage	V_{DHIL}		2.17	2.40	2.63	V	When voltage rises
Detected voltage	V_{DLIL}	SVHI = 0100	2.16	2.40	2.64	V	When voltage drops
Released voltage	V_{DHIL}		2.26	2.50	2.74	V	When voltage rises
Detected voltage	V_{DLIL}	SVHI = 0101	2.25	2.50	2.75	V	When voltage drops
Released voltage	V_{DHIL}		2.35	2.60	2.85	V	When voltage rises
Detected voltage	V_{DLIL}	SVHI = 0110	2.34	2.60	2.86	V	When voltage drops
Released voltage	V_{DHIL}		2.44	2.70	2.96	V	When voltage rises
Detected voltage	V_{DLIL}	SVHI = 0111	2.52	2.80	3.08	V	When voltage drops
Released voltage	V_{DHIL}		2.62	2.90	3.18	V	When voltage rises
Detected voltage	V_{DLIL}	SVHI = 1000	2.70	3.00	3.30	V	When voltage drops
Released voltage	V_{DHIL}		2.80	3.10	3.40	V	When voltage rises
Detected voltage	V_{DLIL}	SVHI = 1001	2.88	3.20	3.52	V	When voltage drops
Released voltage	V_{DHIL}		2.98	3.30	3.62	V	When voltage rises
Detected voltage	V_{DLIL}	SVHI = 1010	3.24	3.60	3.96	V	When voltage drops
Released voltage	V_{DHIL}		3.34	3.70	4.06	V	When voltage rises
Detected voltage	V_{DLIL}	SVHI = 1011	3.33	3.70	4.07	V	When voltage drops
Released voltage	V_{DHIL}		3.43	3.80	4.17	V	When voltage rises
Detected voltage	V_{DLIL}	SVHI = 1100	3.60	4.00	4.40	V	When voltage drops
Released voltage	V_{DHIL}		3.70	4.10	4.50	V	When voltage rises
Detected voltage	V_{DLIL}	SVHI = 1101	3.69	4.10	4.51	V	When voltage drops
Released voltage	V_{DHIL}		3.79	4.20	4.61	V	When voltage rises
Detected voltage	V_{DLIL}	SVHI = 1110	3.78	4.20	4.62	V	When voltage drops
Released voltage	V_{DHIL}		3.88	4.30	4.72	V	When voltage rises
LVD stabilization wait time	t_{LVDILW}	-	-	-	8039 × t_{CYCP} *	μs	
Detection delay time	t_{LVDILD}	dV/dt ≥ - 0.4mV/μs	-	-	800	μs	

*: t_{CYCP} indicates the APB2 bus clock cycle time.

12.7 Flash Memory Write/Erase Characteristics

12.7.1 Write / Erase time

(V_{CC} = 2.0V to 5.5V, T_A = - 40°C to + 85°C)

Parameter		Value		Unit	Remarks
		Typ*	Max*		
Sector erase time	Large Sector	1.6	7.5	s	Includes write time prior to internal erase
	Small Sector	0.4	2.1		
Half word (16-bit) write time		25	400	µs	Not including system-level overhead time.
Chip erase time		4	19.2	s	Includes write time prior to internal erase

*: The typical value is immediately after shipment, the maximum value is guarantee value under 100,000 cycle of erase/write.

12.7.2 Write cycles and data hold time

Erase/write cycles (cycle)	Data hold time (year)	Remarks
1,000	20*	
10,000	10*	
100,000	5*	

*: At average + 85°C

12.8 Return Time from Low-Power Consumption Mode

12.8.1 Return Factor: Interrupt/WKUP

The return time from Low-Power consumption mode is indicated as follows. It is from receiving the return factor to starting the program operation.

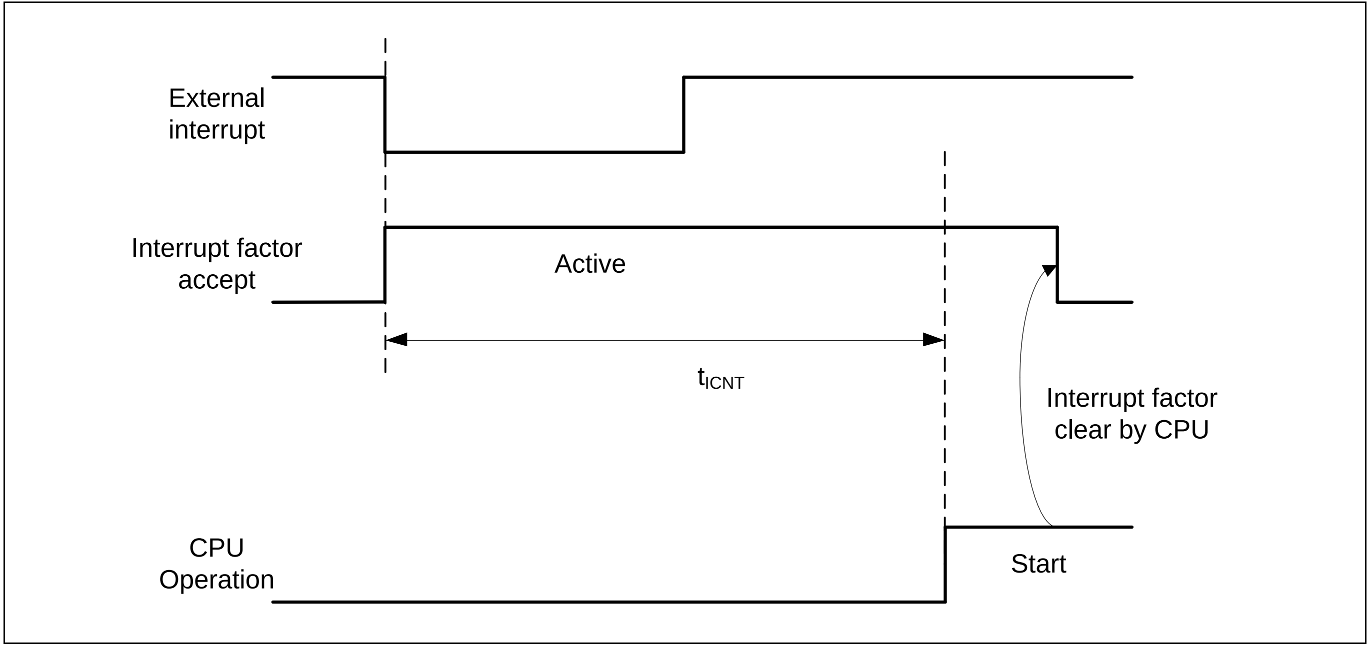
Return Count Time

(V_{CC} = 1.65V to 3.6V, V_{SS} = 0V, T_A = - 40°C to + 85°C)

Parameter	Symbol	Value		Unit	Remarks
		Typ	Max*		
Sleep mode	t_{ICNT}	t_{CYCC}		μs	
High-speed CR Timer mode, Main Timer mode, PLL Timer mode		40	80	μs	
Low-speed CR Timer mode		630	1260	μs	
Sub Timer mode		630	1260	μs	
RTC mode, Stop mode		1083	2100	μs	
Deep Standby RTC mode Deep Standby Stop mode		1099	2127	μs	

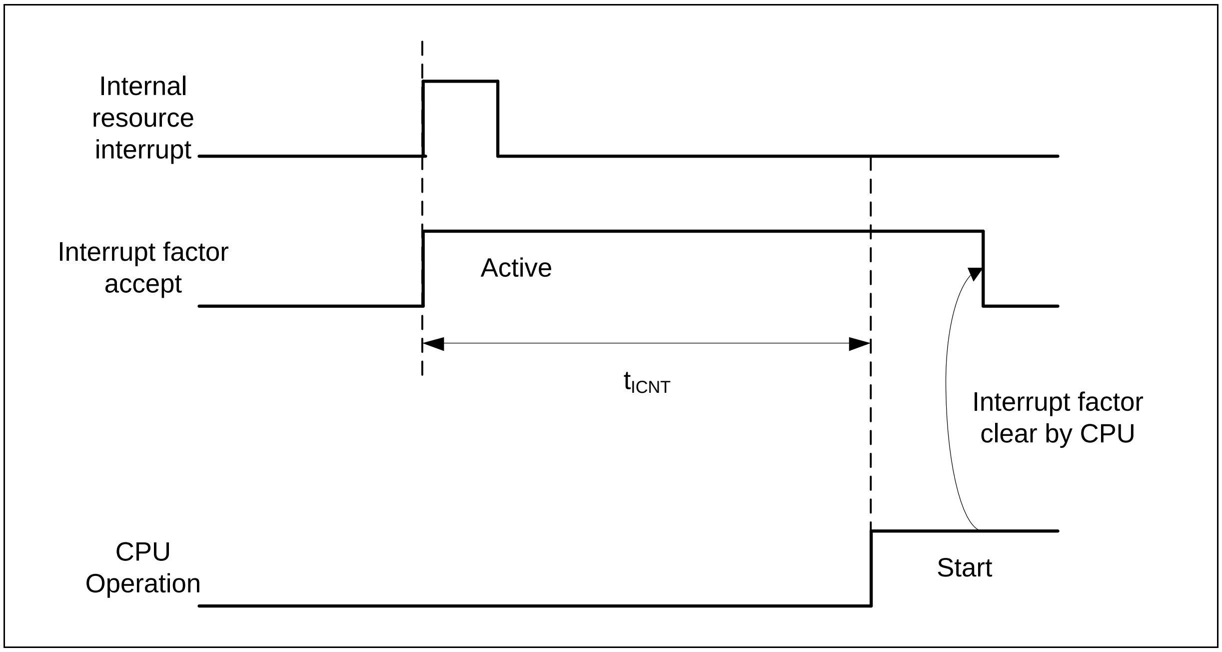
*: The maximum value depends on the accuracy of built-in CR.

Operation example of return from Low-Power consumption mode (by external interrupt*)



*: External interrupt is set to detecting fall edge.

Operation example of return from Low-Power consumption mode (by internal resource interrupt*)



*: Internal resource interrupt is not included in return factor by the kind of Low-Power consumption mode.

Notes:
- *The return factor is different in each Low-Power consumption modes.*
  See Chapter 6: Low Power Consumption Mode and Operations of Standby Modes in FM3 Family
  Peripheral Manual.
- *When interrupt recoveries, the operation mode that CPU recoveries depend on the state before the Low-Power consumption mode transition. See Chapter 6: Low Power Consumption Mode in FM3 Family Peripheral Manual.*

12.8.2 Return Factor: Reset

The return time from Low-Power consumption mode is indicated as follows. It is from releasing reset to starting the program operation.

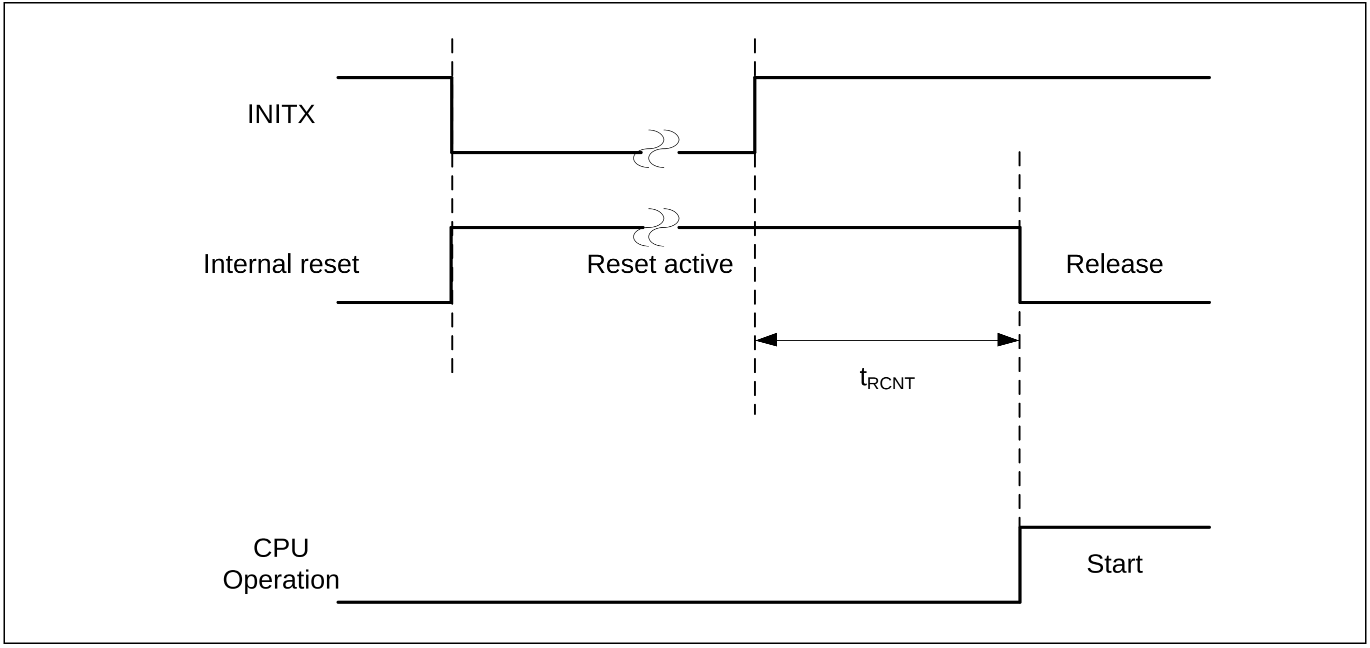
Return Count Time

(V_{CC} = 1.65V to 3.6V, V_{SS} = 0V, T_A = - 40°C to + 85°C)

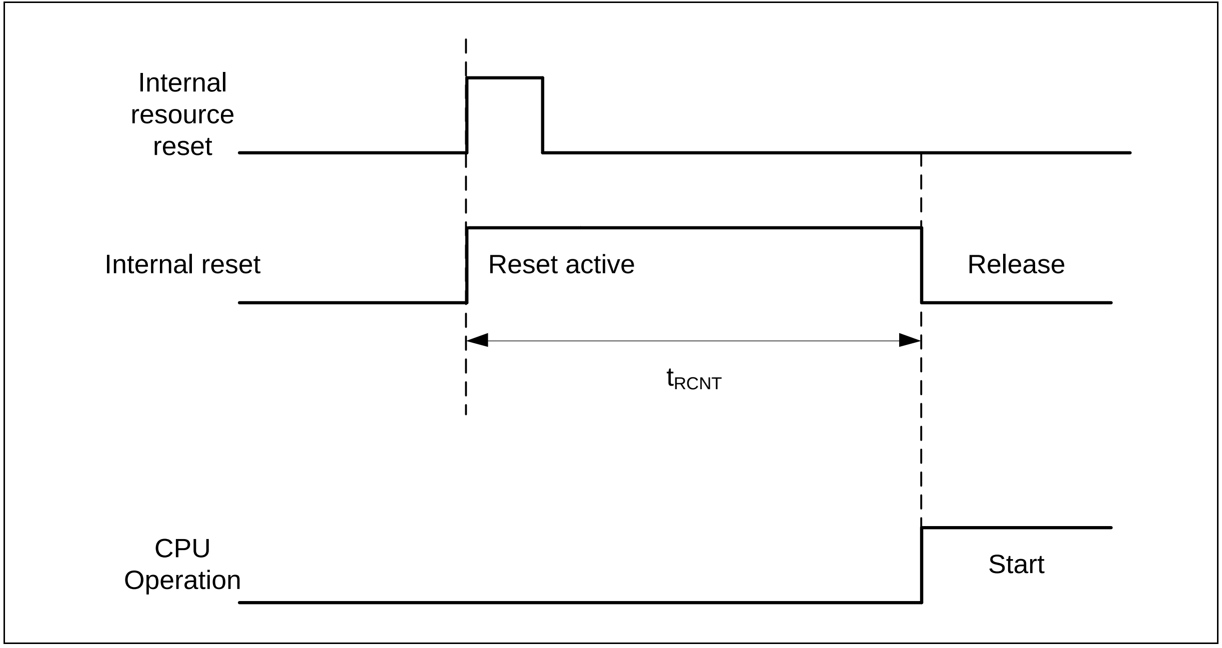
Parameter	Symbol	Value		Unit	Remarks
		Typ	Max*		
Sleep mode	t_{RCNT}	359	647	μs	
High-speed CR Timer mode, Main Timer mode, PLL Timer mode		359	647	μs	
Low-speed CR Timer mode		929	1787	μs	
Sub Timer mode		929	1787	μs	
RTC/Stop mode		1099	2127	μs	
Deep Standby RTC mode Deep Standby Stop mode		1099	2127	μs	

*: The maximum value depends on the accuracy of built-in CR.

Operation example of return from Low-Power consumption mode (by INITX)



Operation example of return from low power consumption mode (by internal resource reset*)



*: Internal resource reset is not included in return factor by the kind of Low-Power consumption mode.

Notes:

– *The return factor is different in each Low-Power consumption modes. See Chapter 6: Low Power Consumption Mode and Operations of Standby Modes in FM3 Family Peripheral Manual.*

– *When interrupt recoveries, the operation mode that CPU recoveries depend on the state before the Low-Power consumption mode transition. See Chapter 6: Low Power Consumption Mode in FM3 Family Peripheral Manual.*

– *The time during the power-on reset/low-voltage detection reset is excluded. See (6) Power-on Reset Timing in 12.4 AC Characteristics in Electrical Characteristics for the detail on the time during the power-on reset/low-voltage detection reset.*

– *When in recovery from reset, CPU changes to the High-speed CR Run mode. When using the main clock or the PLL clock, it is necessary to add the main clock oscillation stabilization wait time or the Main PLL clock stabilization wait time.*

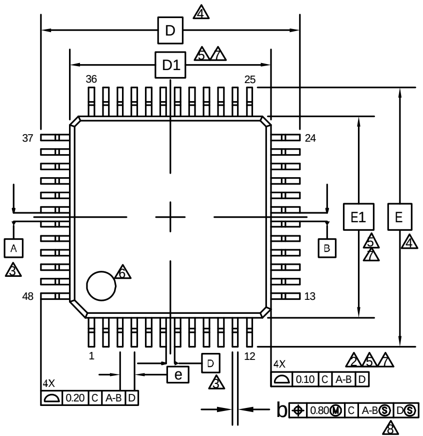
– *The internal resource reset means the watchdog reset and the CSV reset.*

13. Ordering Information

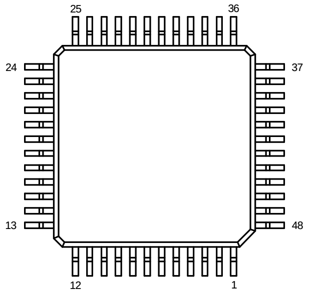
Part number	On-chip Flash memory	On-chip SRAM	Package	Packing
MB9AF131KBPMC-G-SNE2	64 Kbyte	8 Kbyte	Plastic・LQFP (0.5mm pitch), 48-pin (LQA048)	Tray
MB9AF132KBPMC-G-SNE2	128 Kbyte	8 Kbyte		
MB9AF131KBQN-G-AVE2	64 Kbyte	8 Kbyte	Plastic・QFN (0.5mm pitch), 48-pin (VNA048)	
MB9AF132KBQN-G-AVE2	128 Kbyte	8 Kbyte		
MB9AF131LBPMC1-G-SNE2	64 Kbyte	8 Kbyte	Plastic・LQFP (0.5mm pitch), 64-pin (LQD064)	
MB9AF132LBPMC1-G-SNE2	128 Kbyte	8 Kbyte		
MB9AF131LBPMC-G-SNE2	64 Kbyte	8 Kbyte	Plastic・LQFP (0.65mm pitch), 64-pin (LQG064)	
MB9AF132LBPMC-G-UNE2	128 Kbyte	8 Kbyte		
MB9AF131LBQN-G-AVE2	64 Kbyte	8 Kbyte	Plastic・QFN (0.5mm pitch), 64-pin (VNC064)	
MB9AF132LBQN-G-AVE2	128 Kbyte	8 Kbyte		

14. Package Dimensions

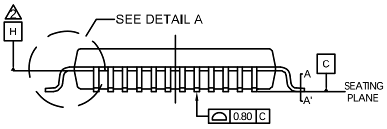
Package Type	Package Code
LQFP 48 (0.5mm pitch)	LQA048



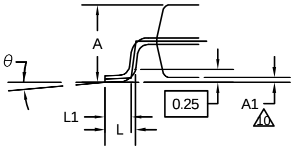
TOP VIEW



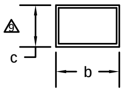
BOTTOM VIEW



SIDE VIEW



DETAIL A



SECTION A-A'

SYMBOL	DIMENSIONS		
	MIN.	NOM.	MAX.
A	—	—	1.70
A1	0.00	—	0.20
b	0.15	—	0.27
c	0.09	—	0.20
D	9.00 BSC		
D1	7.00 BSC		
e	0.50 BSC		
E	9.00 BSC		
E1	7.00 BSC		
L	0.45	0.60	0.75
L1	0.30	0.50	0.70
θ	0°	—	8°

NOTES

1. ALL DIMENSIONS ARE IN MILLIMETERS.

2. DATUM PLANE H IS LOCATED AT THE BOTTOM OF THE MOLD PARTING LINE COINCIDENT WITH WHERE THE LEAD EXITS THE BODY.

3. DATUMS A-B AND D TO BE DETERMINED AT DATUM PLANE H.

4. TO BE DETERMINED AT SEATING PLANE C.

5. DIMENSIONS D1 AND E1 DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS 0.25mm PRE SIDE. DIMENSIONS D1 AND E1 INCLUDE MOLD MISMATCH AND ARE DETERMINED AT DATUM PLANE H.

6. DETAILS OF PIN 1 IDENTIFIER ARE OPTIONAL BUT MUST BE LOCATED WITHIN THE ZONE INDICATED.

7. REGARDLESS OF THE RELATIVE SIZE OF THE UPPER AND LOWER BODY SECTIONS. DIMENSIONS D1 AND E1 ARE DETERMINED AT THE LARGEST FEATURE OF THE BODY EXCLUSIVE OF MOLD FLASH AND GATE BURRS. BUT INCLUDING ANY MISMATCH BETWEEN THE UPPER AND LOWER SECTIONS OF THE MOLDER BODY.

8. DIMENSION b DOES NOT INCLUDE DAMBER PROTRUSION. THE DAMBAR PROTRUSION (S) SHALL NOT CAUSE THE LEAD WIDTH TO EXCEED b MAXIMUM BY MORE THAN 0.08mm. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE LEAD FOOT.

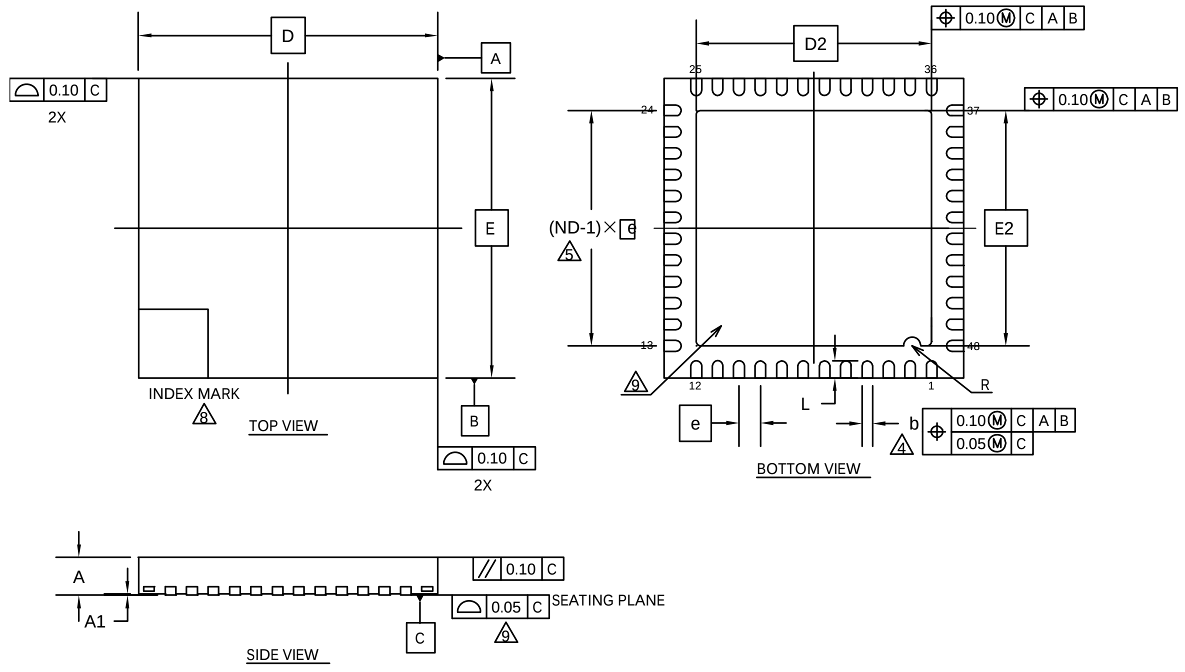
9. THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN 0.10mm AND 0.25mm FROM THE LEAD TIP.

10. A1 IS DEFINED AS THE DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT OF THE PACKAGE BODY.

002-13731 **

PACKAGE OUTLINE, 48 LEAD LQFP
7.0X7.0X1.7 MM LQA048 REV**

Package Type	Package Code
QFN 48	VNA048



SYMBOL	DIMENSIONS		
	MIN.	NOM.	MAX.
A	—	—	0.90
A1	0.00	—	0.05
D	7.00 BSC		
E	7.00 BSC		
b	0.20	0.25	0.30
D2	5.50 BSC		
E2	5.50 BSC		
e	0.50 BSC		
R	0.20 REF		
L	0.35	0.40	0.45

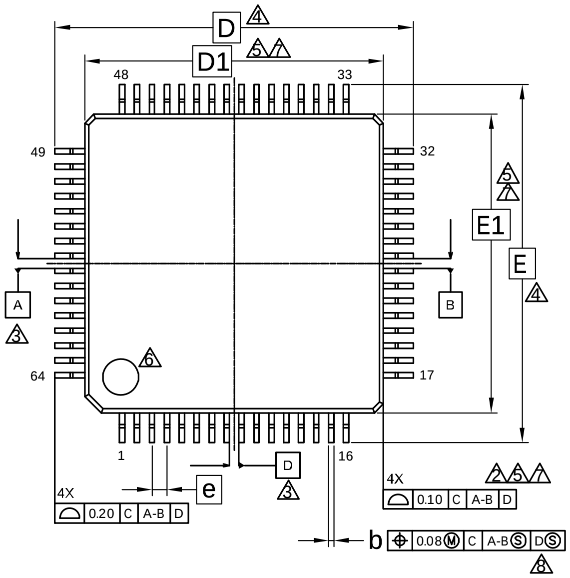
NOTE

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCINC CONFORMS TO ASME Y14.5-1994.
3. N IS THE TOTAL NUMBER OF TERMINALS.
4. DIMENSION "b" APPLIES TO METALLIZED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30mm FROM TERMINAL TIP. IF THE TERMINAL HAS THE OPTIONAL RADIUS ON THE OTHER END OF THE TERMINAL. THE DIMENSION "b" SHOULD NOT BE MEASURED IN THAT RADIUS AREA.
5. ND REFER TO THE NUMBER OF TERMINALS ON D OR E SIDE.
6. MAX. PACKAGE WARPAGE IS 0.05mm.
7. MAXIMUM ALLOWABLE BURRS IS 0.076mm IN ALL DIRECTIONS.
8. PIN #1 ID ON TOP WILL BE LOCATED WITHIN INDICATED ZONE.
9. BILATERAL COPLANARITY ZONE APPLIES TO THE EXPOSED HEAT SINK SLUG AS WELL AS THE TERMINALS.
10. JEDEC SPECIFICATION NO. REF : N/A

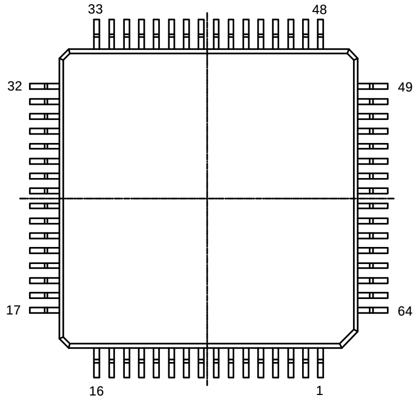
PACKAGE OUTLINE, 48 LEAD QFN
7.0X7.0X0.9 MM VNA048 5.5X5.5 MM EPAD (SAWN) REV**

002-15528 **

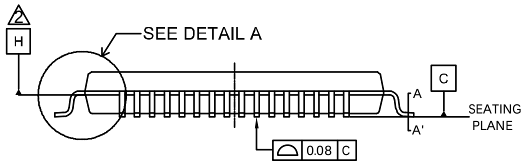
Package Type	Package Code
LQFP 64 (0.5mm pitch)	LQD064



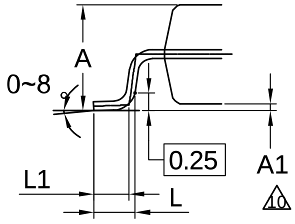
TOP VIEW



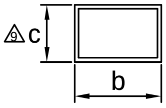
BOTTOM VIEW



SIDE VIEW



DETAIL A



SECTION A-A'

SYMBOL	DIMENSIONS		
	MIN.	NOM.	MAX.
A	—	—	1.70
A1	0.00	—	0.20
b	0.15	—	0.27
c	0.09	—	0.20
D	12.00 BSC.		
D1	10.00 BSC.		
e	0.50 BSC		
E	12.00 BSC.		
E1	10.00 BSC.		
L	0.45	0.60	0.75
L1	0.30	0.50	0.70

NOTES

1. ALL DIMENSIONS ARE IN MILLIMETERS.

△2 DATUM PLANE H IS LOCATED AT THE BOTTOM OF THE MOLD PARTING LINE COINCIDENT WITH WHERE THE LEAD EXITS THE BODY.

△3 DATUMS A-B AND D TO BE DETERMINED AT DATUM PLANE H.

△4 TO BE DETERMINED AT SEATING PLANE C.

△5 DIMENSIONS D1 AND E1 DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS 0.25mm PRE SIDE. DIMENSIONS D1 AND E1 INCLUDE MOLD MISMATCH AND ARE DETERMINED AT DATUM PLANE H.

△6 DETAILS OF PIN 1 IDENTIFIER ARE OPTIONAL BUT MUST BE LOCATED WITHIN THE ZONE INDICATED.

△7 REGARDLESS OF THE RELATIVE SIZE OF THE UPPER AND LOWER BODY SECTIONS. DIMENSIONS D1 AND E1 ARE DETERMINED AT THE LARGEST FEATURE OF THE BODY EXCLUSIVE OF MOLD FLASH AND GATE BURRS. BUT INCLUDING ANY MISMATCH BETWEEN THE UPPER AND LOWER SECTIONS OF THE MOLDER BODY.

△8 DIMENSION b DOES NOT INCLUDE DAMBER PROTRUSION. THE DAMBAR PROTRUSION (S) SHALL NOT CAUSE THE LEAD WIDTH TO EXCEED b MAXIMUM BY MORE THAN 0.08mm. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE LEAD FOOT.

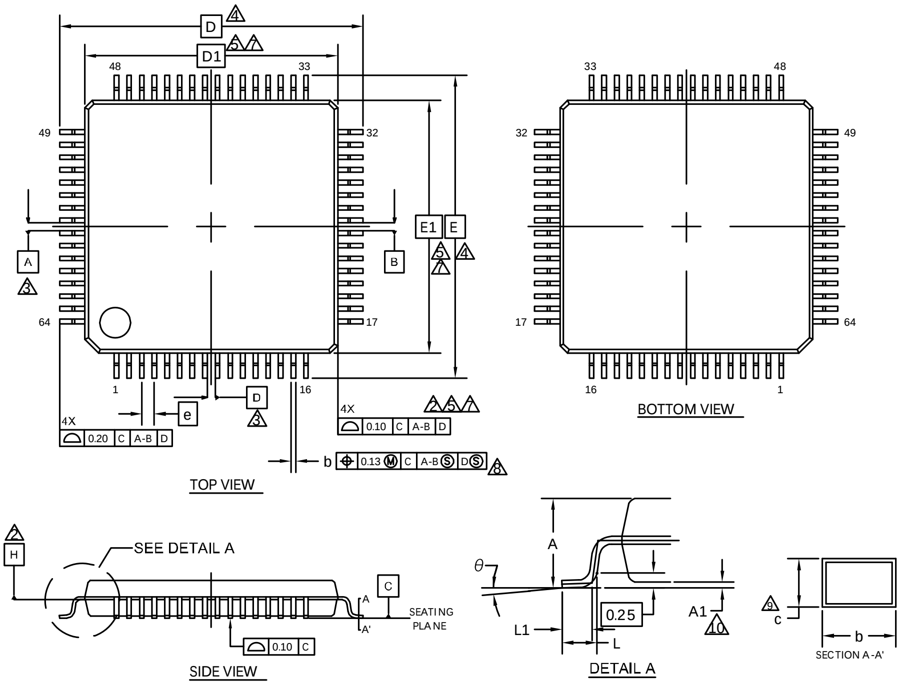
△9 THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN 0.10mm AND 0.25mm FROM THE LEAD TIP.

△10 A1 IS DEFINED AS THE DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT OF THE PACKAGE BODY.

002-11499 **

PACKAGE OUTLINE, 64 LEAD LQFP
10.0X10.0X1.7 MM LQD064 Rev**

Package Type	Package Code
LQFP 64 (0.65mm pitch)	LQG064



SYMBOL	DIMENSION		
	MIN.	NOM.	MAX.
A	—	—	1.70
A1	0.00	—	0.20
b	0.27	0.32	0.37
c	0.09	—	0.20
D	14.00 BSC		
D1	12.00 BSC		
e	0.65 BSC		
E	14.00 BSC		
E1	12.00 BSC		
L	0.45	0.60	0.75
L1	0.30	0.50	0.70
θ	0°	—	8°

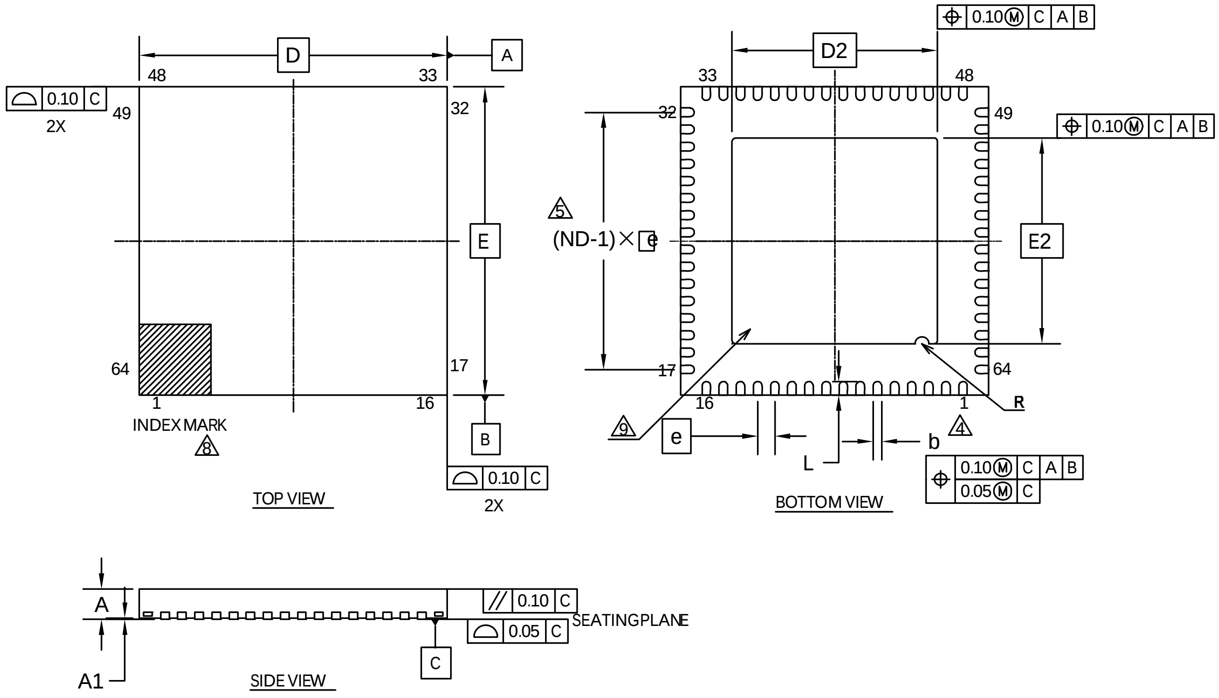
NOTES

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DATUM PLANE H IS LOCATED AT THE BOTTOM OF THE MOLD PARTING LINE COINCIDENT WITH WHERE THE LEAD EXITS THE BODY.
3. DATUMS A-B AND D TO BE DETERMINED AT DATUM PLANE H.
4. TO BE DETERMINED AT SEATING PLANE C.
5. DIMENSIONS D1 AND E1 DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS 0.25mm PRE SIDE. DIMENSIONS D1 AND E1 INCLUDE MOLD MISMATCH AND ARE DETERMINED AT DATUM PLANE H.
6. DETAILS OF PIN 1 IDENTIFIER ARE OPTIONAL BUT MUST BE LOCATED WITHIN THE ZONE INDICATED.
7. REGARDLESS OF THE RELATIVE SIZE OF THE UPPER AND LOWER BODY SECTIONS. DIMENSIONS D1 AND E1 ARE DETERMINED AT THE LARGEST FEATURE OF THE BODY EXCLUSIVE OF MOLD FLASH AND GATE BURRS. BUT INCLUDING ANY MISMATCH BETWEEN THE UPPER AND LOWER SECTIONS OF THE MOLDER BODY.
8. DIMENSION b DOES NOT INCLUDE DAMBER PROTRUSION. THE DAMBAR PROTRUSION (S) SHALL NOT CAUSE THE LEAD WIDTH TO EXCEED b MAXIMUM BY MORE THAN 0.08mm. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE LEAD FOOT.
9. THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN 0.10mm AND 0.25mm FROM THE LEAD TIP.
10. A1 IS DEFINED AS THE DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT OF THE PACKAGE BODY.

PACKAGE OUTLINE, 64 LEAD LQFP
12.0X12.0X1.7 MM LQG064 REV**

002-13881 **

Package Type	Package Code
QFN 64	VNC064



SYMBOL	DIMENSIONS		
	MIN.	NOM.	MAX.
A	—	—	0.90
A1	0.00	—	0.05
D		9.00 BSC	
E		9.00 BSC	
b	0.20	0.25	0.30
D2		6.00 BSC	
E2		6.00 BSC	
e		0.50 BSC	
R		0.20 REF	
L	0.35	0.40	0.45
N		64	
ND		16	

NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING CONFORMS TO ASME Y14.5M-1994.
3. N IS THE TOTAL NUMBER OF TERMINALS.
4. DIMENSION "b" APPLIES TO METALLIZED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30mm FROM TERMINAL TIP. IF THE TERMINAL HAS THE OPTIONAL RADIUS ON THE OTHER END OF THE TERMINAL, THE DIMENSION "b" SHOULD NOT BE MEASURED IN THAT RADIUS AREA.
5. ND REFERS TO THE NUMBER OF TERMINALS ON D SIDE OR E SIDE.
6. MAX. PACKAGE WARPAGE IS 0.05mm.
7. MAXIMUM ALLOWABLE BURR IS 0.076mm IN ALL DIRECTIONS.
8. PIN #1 ID ON TOP WILL BE LOCATED WITHIN THE INDICATED ZONE.
9. BILATERAL COPLANARITY ZONE APPLIES TO THE EXPOSED HEAT SINK SLUG AS WELL AS THE TERMINALS.

PACKAGE OUTLINE, 64 LEAD QFN
9.0X9.0X0.9 MM VNC064 6.0X6.0 MM EPAD (SAWN) Rev*.*

002-13234 **

15. Major Changes

Spansion Publication Number: DS706-00066

Page	Section	Change Results
Revision 1.0		
-	-	Initial release
Revision 2.0		
2	Features · On-chip Memories	Changed the description of on-chip SRAM
33	Handling Devices	Added "· Stabilizing power supply voltage"
33	Handling Devices Crystal oscillator circuit	Added the following description "Evaluate oscillation of your using crystal oscillator by your mount board."
37	Memory Map Memory map(2)	Added the summary of Flash memory sector
47 - 49	Electrical Characteristics 3. DC Characteristics (1) Current rating	· Changed the table format · Added Timer mode current · Added Flash Memory Current · Moved A/D Converter Current
53	Electrical Characteristics 4. AC Characteristics (4-1) Operating Conditions of Main PLL (4-2) Operating Conditions of Main PLL	· Added the figure of Main PLL connection
54	Electrical Characteristics 4. AC Characteristics (6) Power-on Reset Timing	· Changed the figure of timing · Changed from Reset release delay time(t_{OND}) to Time until releasing Power-on reset(t_{PRT})
56 - 63	Electrical Characteristics 4. AC Characteristics (8) CSIO/UART Timing	· Modified from UART Timing to CSIO/UART Timing · Changed from Internal shift clock operation to Master mode · Changed from External shift clock operation to Slave mode
67	Electrical Characteristics 5. 12bit A/D Converter	· Added the typical value of Integral Nonlinearity, Differential Nonlinearity, Zero transition voltage and Full-scale transition voltage · Added Conversion time at $AV_{CC} < 2.7$ V
70	Electrical Characteristics 7. Low-voltage Detection Characteristics	Deleted the figure
73	Electrical Characteristics 8. Flash Memory Write/Erase Characteristics	Change to the erase time of include write time prior to internal erase
74 - 77	Electrical Characteristics 9. Return Time from Low-Power Consumption Mode	Added Return Time from Low-Power Consumption Mode
78	Ordering Information	Changed notation of part number

NOTE: Please see "Document History" about later revised information.

Document History

Document Title: MB9A130LB Series 32-bit ARM® Cortex®-M3 FM3 Microcontroller
Document Number: 002-05671

Revision	ECN	Orig. of Change	Submission Date	Description of Change
**	-	AKIH	06/09/2015	Migrated to Cypress and assigned document number 002-05671. No change to document contents or format.
*A	5162460	AKIH	03/10/2016	Updated to Cypress format.
*B	5742425	YSKA	05/23/2017	Adapted new Cypress logo Modified RTC description in “Features, Real-Time Clock(RTC)”. Changed starting count value from 01 to 00. Deleted “second, or day of the week” in the Interrupt function. Changed package code as the following in chapter: 2. Packages 3. Pin Assignment 13. Ordering Information 14. Package Dimensions. FPT-48P-M49 -> LQA048, LCC-48P-M73 -> VNA048 FTP-64P-M38 -> LQD064, FPT-64P-M39 -> LQG064, LCC-64P-M24 -> VNC064 Corrected “J-TAG" to “JTAG" in 4. List of Pin Functions. Added Note for JTAG pin in 4. List of Pin Functions. Added the Baud rate spec in 12.4.9 CSIO/UART Timing.
*C	5883538	HUAL	09/14/2017	Modified Part number as below due to Fab transfer MB9AF132LBPMC-G-SNE2 => MB9AF132LBPMC-G-UNE2

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